VIKING® VX UHF LTR REPEATER PART NO. 242-20X4-213

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LAND MOBILE PRODUCT WARRANTY

The manufacturer's warranty statement for this product is available from your product supplier or from the E.F. Johnson Company, 299 Johnson Avenue, Box 1249, Waseca, MN 56093-0514. Phone (507) 835-6222.

WARNING

This device complies with Part 15 of the FCC rules. Operation is subject to the condition that this device does not cause harmful interference. In addition, changes or modification to this equipment not expressly approved by E. F. Johnson could void the user's authority to operate this equipment (FCC rules, 47CFR Part 15.19).

DO NOT allow the antenna to come close to or touch, the eyes, face, or any exposed body parts while the radio is transmitting.

DO NOT operate the radio near electrical blasting caps or in an explosive atmosphere.

DO NOT operate the radio unless all the radio frequency connectors are secure and any open connectors are properly terminated.

DO NOT allow children to operate transmitter equipped radio equipment.

SAFETY INFORMATION

Proper operation of this radio will result in user exposure below the Occupational Safety and Health Act and Federal Communication Commission limits.

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SECTION 1 INTRODUCTION AND OPERATION

1.1 SCOPE OF MANUAL

This service manual provides installation, operation, programming, service, and alignment information for the VIKING® VX LTR® Repeater, Part No. 242-20X4-213.

1.2 REPEATER DESCRIPTION

The VIKING VX repeater is designed for operation in a Johnson LTR system. It operates on the UHF channels from 380-520 MHz. Channel spacing is 12.5 kHz and RF power output is adjustable from 25 to 110 watts.

This repeater is modular in design for ease of service. There are separate assemblies for the logic cards, receiver, exciter, power amplifier and power supply sections.

This repeater is programmed with a laptop or personal computer using the repeater software, Part No. 023-9998-390.

1.3 REPEATER IDENTIFICATION

The repeater identification number is printed on a label that is affixed to the inside of the repeater cabinet. The following information is contained in that number:

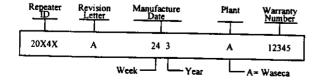


Figure 1-1 REPEATER IDENTIFICATION

1.4 MODEL NUMBER BREAKDOWN

The following breakdown shows the part number scheme used for the Viking VX.

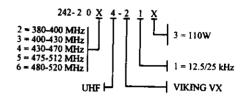


Figure 1-2 PART NUMBER BREAKDOWN

1.5 ACCESSORIES

The accessories available for the Viking VX LTR repeater are listed in Table 1-1. A brief description of some of these accessories follows.

External Speaker - This 16 ohm speaker plugs into the MAC card jack. The speaker provides local audio and is adjusted by the volume control.

RJ-11 to 6-BNC Adapter - This adapter box provides connections for the high speed data bus at the rear of the repeater and the data bus from the logic drawers in existing repeater systems.

19" Aluminum Shelf - Rack mounted shelf, 20" deep, that can be used to support the batteries.

12V DC Battery - This is a sealed 12V DC lead-acid battery intended for battery backup systems. Two batteries are required per repeater. At 25°C, with a 100% transmit duty cycle at 25W, the repeater will operate for 2 hours and at 110W, the repeater will operate for 1 hour.

2000 Series Service Kit - This kit contains an alarm wire harness, extender power cable, programming kit, extender card, extender harness, and a TIC bias cable. These items are used when tuning the repeater and while troubleshooting.

1.6 PRODUCT WARRANTY

The warranty statement for this transceiver is available from your product supplier or from the Warranty Department, E.F. Johnson Company, 299
Johnson Avenue, Box 1249, Waseca, MN 56093-0514. This information may also be requested by phone from the Warranty Department. The Warranty Department may also be contacted for Warranty Service Reports, claim forms, or any questions concerning warranties or warranty service by dialing (507) 835-6970.

1.7 FACTORY CUSTOMER SERVICE

The Customer Service Department of the E.F. Johnson Company provides customer assistance on technical problems and the availability of local and factory repair facilities. Customer Service hours are 7:30 am - 4:30 pm Central Time, Monday - Friday. There is also a 24-hour emergency technical support telephone number. From within the continental United States, the Customer Service Department can be reached at this toll-free number:

1-800-328-3911

When your call is answered at the E.F. Johnson Company, you will hear a brief message informing you of numbers that can be entered to reach various departments. This number may be entered during or after the message using a tone-type telephone. If you have a pulse-type telephone, wait until the message is finished and an operator will come on the line to assist you. When you enter a first number of "1" or "2", another number is requested to further categorize the type of information you need. You may also enter the 4-digit extension number of the person that you want to reach if you know what it is.

FAX Machine - Sales (507) 835-6485 FAX Machine - Cust Serv (507) 835-6969

If you are calling from outside the continental United States, the Customer Service telephone numbers are as follows:

Customer Service Department - (507) 835-6911 Customer Service FAX Machine - (507) 835-6969 You may also contact the Customer Service Department by mail. Please include all information that may be helpful in solving your problem. The mailing address is as follows:

> E.F. Johnson Company Customer Service Department 299 Johnson Avenue P.O. Box 1249 Waseca, MN 56093-0514

1.8 FACTORY RETURNS

Repair service is normally available through local authorized E.F. Johnson Land Mobile Radio Service Centers. If local service is not available, the equipment can be returned to the factory for repair. However, it is recommended that you contact the Field Service Department before returning equipment. A service representative may be able to suggest a solution to the problem so that return of the equipment would not be necessary. If using the toll-free number in the preceding section, enter "2".

Be sure to fill out a Factory Repair Request Form #271 for each unit to be repaired, whether it is in or out of warranty. These forms are available free of charge by calling the repair lab (see Section 1.7) or by requesting them when you send a unit in for repair. Clearly describe the difficulty experienced in the space provided and also note any prior physical damage to the equipment. Then include a form in the shipping container with each unit. Your phone number and contact name are very important because there are times when the technicians have specific questions that need to be answered in order to completely identify and repair a problem.

When returning equipment for repair, it is also a good idea to use a PO number or some other reference number on your paperwork in case you need to call the repair lab about your unit. These numbers are referenced on the repair order and it makes it easier and faster to locate your unit in the lab.

Return Authorization (RA) numbers are not necessary unless you have been given one by the Field Service Department. They require RA numbers for exchange units or if they want to be aware of a specific problem. If you have been given an RA number,

Table 1-1 VIKING VX REPEATER
ACCESSORIES

Accessory	Part No.
RJ-11 to 6-BNC Adapter	023-2000-194
19" Aluminum Shelf	508-0500-029
12V DC Battery	503-5012-420
External speaker	250-0151-005
2000 Series Service Kit	250-2000-230
Power Supply Only	250-2000-800
Power Supply w/Batt Bkup, no cable	250-2000-801
Battery Backup board only	023-2000-830
Battery Backup option and cable	023-2000-835
Battery Backup Cable Kit	023-2000-223
RG-316-BNC/BNC cable 68" *	597-3003-260
RG-316-BNC/BNC cable 71" *	597-3003-261
RG-316-BNC/BNC cable 87" *	597-3003-262
RG-316-BNC/BNC cable 96" *	597-3003-263
RG-316-BNC/BNC cable 106" *	597-3003-264
RG316-BNC/BNC cable 12"	597-3003-253
RG316-BNC/BNC cable 118"	597-3003-265
PC programmer PGMR software	023-9998-390
Programming cable kit	023-2000-195
Extender Card	023-2000-230
Extender cable kit, 7 ft.	250-2000-010
Rack self supporting	
3 ft.	508-0500-021
5.5 ft.	508-0500-022
6 ft.	508-0500-023
6.5 ft.	508-0500-024
7 ft.	508-0500-025
7.5 ft.	508-0500-026
8 ft.	508-0500-027
9 ft.	508-0500-028
Combiner coaxial protector	585-0898-005
External speaker/microphone	589-0015-011
FSK Modem IC (U110)	544-3988-008
Power line protector	597-1004-010
RJ-11 to RJ-11, 3 ft. cable	597-2002-200
*Included in kit 023-2000-128	

Battery Backup and Cable Option - This option can be factory or field installed (refer to installation instructions 004-2000-830). It includes the battery backup module that resides in the power supply and the necessary interconnect cabling to connect the repeater to the batteries (see Section 2.5).

Battery Backup Cable Kit - This kit provides the cables required for connecting the screw lugs on the power supply to the 12V DC batteries (refer to installation instructions 004-2000-830).

Power Supply with Battery Backup - This power supply is equipped with battery backup (see Section 2.5). Battery cables are not included.

Battery Backup (board only) - This is a battery backup module only for field replacement (refer to installation instructions 004-2000-830).

PC Programmer PGMR Software - 3.5" programming disk used to program the repeater.

Programming Cable Kit - This kit connects the MPC and a computer during programming and for monitoring repeater activity at the site.

Extender Card - Used to extend the cards plugged into the backplane beyond the card rack enclosure when tuning the repeater and while troubleshooting.

Extender Cable Kit - These are seven foot extension cables for the RF Transceiver power and data, when the transceiver is removed from the cabinet.

Rack Self Supporting - Accommodates from one to five repeaters mounted on vertical columns. This also provides space for combiners and duplexers.

Combiner Coaxial Protector - This accessory provides lightning and static suppression in-line between the antenna and combiner.

External Speaker/Microphone - This is a speaker and microphone combination that plugs into the MAC connectors. The microphone provides local audio and push-to-talk, while the speaker provides local audio adjusted with the volume control.

Power Line Protector - This accessory provides lightning, static and surge protection on the AC power line. This line protector is rack mounted with multiple outlets.

RJ-11 to RJ-11 Cable - This three foot cable is used to connect two or more repeaters to the high speed data bus through the modular jack on the rear of the repeater.

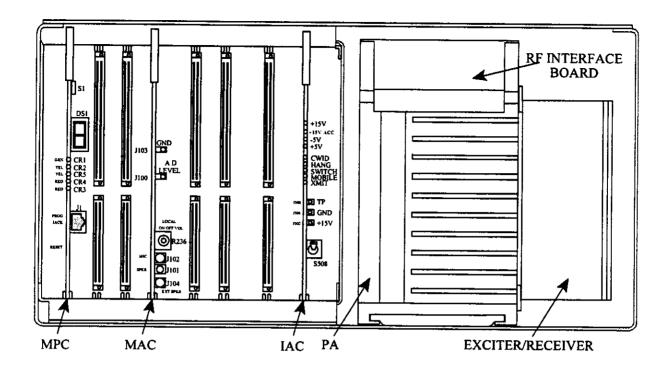


Figure 1-4 REPEATER CARDS

reference this number on the Factory Repair Request Form sent with the unit. The repair lab will then contact the Field Service Department when the unit arrives.

1.9 REPLACEMENT PARTS

E.F. Johnson replacement parts can be ordered directly from the Service Parts Department. To order parts by phone, dial the toll-free number and then enter "1" as described in Section 1.7. When ordering, please supply the part number and quantity of each part ordered. E.F. Johnson dealers also need to give their account number.

If there is uncertainty about the part number, include the designator (C112, for example) and the model number of the equipment the part is from (refer to Section 1.3).

You may also send your order by mail or FAX. The mailing address is as follows and the FAX number is shown in Section 1.7.

E.F. Johnson Company Service Parts Department 299 Johnson Avenue P.O. Box 1249 Waseca, MN 56093-0514

1.10 SOFTWARE UPDATES/REVISIONS

All inquiries concerning updated software, its installation and revisions should be directed to the Customer Service Department (see Section 1.7).

1.11 REPEATER OPERATION

1.11.1 MAIN PROCESSOR CARD (MPC)

Refer to Figure 1-4.

Programming Jack

J1 provides input connection from the computer and the "flash memory" in the MPC. The programming information in an IBM® PC programs the MPC directly from the serial card through an interconnect cable to the COM1 or COM2 port.

Reset

S1 provides a manual reset of the Main Processor Card (MPC). A manual reset causes a complete power-up restart.

Display and LEDs

Each combination of DS1 display read-out and CR4/CR5 indication refers to an active alarm. See Table 1-2 for alarms and definitions. LED indications: CR1 is blinking; MPC is operational, CR2 on; 380-470 MHz, off is 475-520 MHz and CR5 on; indicates an LTR Repeater.

RF Thermal Sense Alarm Condition Exists

NOTE: Safety measures are disabled

Ok

Figure 1-3 ALARM IN TEST MODE

Alarms

When the Repeater is in Test mode the safety measures are disabled. Therefore, if the Repeater is keyed for an extended period and the power amplifier temperature increase, thermal shutdown will not occur. There are pop-up windows that appear in the Test mode screens to alert the user that there is an alarm and action should be taken. Refer to Figure 1-3 for an example of this type of alarm.

1.11.2 MAIN AUDIO CARD (MAC)

Refer to Figure 1-4.

External Speaker Jack

J104 provides repeater audio output to an external speaker. The local volume control adjusts the volume level of this speaker.

Speaker/Microphone Jacks

J102 provides audio input from a microphone. J101 provides the receive audio to the microphone.

Local On/Off/Volume Control

R236 provides control of the receive audio output to J101 and J104. Turning this control clockwise past the detent applies voltage to the local audio amplifier.

A D Level Test Point

J100 provides audio/data level output for test level checks.

Ground

J103 is connected to ground for test equipment when monitoring test point J100.

1.11.3 INTERFACE ALARM CARD (IAC)

Refer to Figure 1-4.

Voltage Test Output

J502 provides a +15V test point on the IAC.

Ground

J501 is connected to ground for test equipment when monitoring voltage test point J502.

A D Level Test Point

J500 provides a test point to monitor audio and data levels, AC fail and thermal sensor.

Power Supply On/Off Switch

S508 turns the power supply DC voltages on and off from the IAC in the front of the repeater.

Power Indicator

CR501 indicates the +5V supply is at normal level and applied to the IAC. CR524 indicates -5V supply is at normal level and applied to the IAC. CR523 indicates the +15V accessory supply is at normal level. CR525 indicates that the +15V supply is at normal level and applied to the IAC.

CWID Indicator

Indicates that the CW Identification is being transmitted on the lowest-frequency repeater. The CWID is a continuous-wave (CW) transmission of the station call letters in Morse Code to satisfy the station identification requirement. The CWID is programmed into the repeater memory. This indicator also is used when an alarm is transmitted with Morse code.

Hang Indicator

Indicates that the hang word is being transmitted by the repeater. This word is transmitted on calls in which the channel is held for the duration of the call and not just for the duration of the transmission. The hang word tells the mobiles to stay on the same channel and not re-access the system when responding to a call.

Switch Call Indicator

Not used in the LTR repeater.

Mobile Call Indicator

Mobile-to-repeater transmission in progress is indicated by the Mobile Call Indicator.

Xmit Indicator

This indicates that the repeater transmitter is keyed by the logic.

Table 1-2 ACTIVE REPEATER ALARMS

Alarm No.	DS1	CR3	CR4	Definition
0	0	Off	On	Test Mode
1	1	Off	On	IAC input 1 Active
2	2	Off	On	IAC input 2 Active
3	3	Off	On	IAC input 3 Active
4	4	Off	On	IAC input 4 Active
5	5	Off	On	IAC input 5 Active
6	6	Off	On	IAC input 6 Active
7	7	Off	On	IAC input 7 Active
8	8	Off	On	IAC input 8 Active
9	9	Off	On	MAC Processor Alarm
10	Α	Off	On	HSDB Processor/Cable Alarm
11	В	Off	On	IRDB Cable Alarm
12	С	Off	On	RNT/CIM Channel Problem Alarm
13	D	Off	On	TIC Processor Alarm
14	Е	Off	On	MMC Processor Alarm
15	F	Off	On	VNC Alarm
16	0	On	Off	AC Power Failure
17	1	On	Off	Battery Power Failure
18	2	On	Off	Power supply thermal sense
19	3	On	Off	Fan 1 current out of specification
20	4	On	Off	Fan 2 current out of specification
21	5	On	Off	IAC mismatch
32	0	On	On	RF shutdown
33	1	On	On	RF Half Power Mode
34	2	On	On	Thermal sense in RF portion
35	3	On	On	RF Finals 1-2 power out failure
36	4	On	On	RF Finals 3-4 power out failure
37	5	On	On	RF VSWR Failure
38	6	On	On	Normal Synthesizer Tx Lock failure
39	7	On	On	Normal Synthesizer Rx Lock failure
40	8	On	On	HS Synthesizer Tx Lock failure
41	9	On	On	HS Synthesizer Rx Lock failure
42	Α	On	On	RF Quarter Power Alarm

In its time slot, each repeater places information on the data bus indicating its status. If a repeater is not busy, only start bits appear in its slot. If a repeater is busy, it places in its slot the Home repeater and ID code of the mobile receiving the call on that repeater. If a repeater number is unassigned, nothing appears in that time slot.

1.13.2 MOBILE DATA MESSAGE ORDER

Each repeater monitors all the time slots on the repeater data bus. If it detects its number in another time slot, it begins transmitting an additional data message to its mobiles. This message tells mobiles programmed to detect that ID code to go to that repeater to receive a call. This additional message continues for as long as the mobile is transmitting on the other repeater.

The sequence of data messages transmitted on a home repeater is as follows: Every third message is to the mobile currently receiving a call on that repeater. Then alternating between these messages are messages to its mobiles that have been trunked to other repeaters. For example, assume that five

different mobiles on a five-repeater system are making calls. If all have Repeater 1 as their home channel (not very likely in actual practice), the data message order on Repeater 1 is as follows: 1 2 3 1 4 5 1 2 3 and so on.

1.13.3 ID VALIDATOR OPERATION

If the ID Validator is used, it is programmed with the status of up to all 5000 home repeater/ID code combinations possible with a 20-channel system. Each combination is programmed as either valid or invalid. Information in the twenty time slots on the repeater data bus is monitored. If an invalid home repeater/ID code combination is detected, the ID Validator places in time slot 21 the number of the repeater being used by the invalid mobile and also the ID code. When a repeater detects its number in slot 21, it transmits the turn-off code (31) to the mobile receiving the call. That mobile then squelches and resumes monitoring its home channel. This effectively disables the invalid mobile because it cannot talk to anyone. When the turn-off code is sent, the repeater places "21" in the repeater position of its time slot to indicate to the ID validator that turn-off has occurred.

1.11.4 POWER SUPPLY

The power supply is sealed and the line and supply fuses are inside. If a supply fuse opens, the power supply must be removed and opened for repair (see Section 2.4 and 8.5). Refer to the power supply service manual 004-2000-810.

4

Standby Battery Jack

This provides a connection point for a +24V DC standby battery. Current is drawn from the battery only when the power supply output voltage is lower than the battery voltage. A trickle charge switch on the supply ensures that the battery is fully charged. Disable this switch when a separate battery charger is used (see Section 2.5).

1.12 REPEATER INFORMATION

1.12.1 INTRODUCTION

NOTE: The VIKING VX does not require a separate LTR logic drawer.

The repeater model used in an LTR system is determined by frequency range. 800 MHz systems use the VIKING VX (-232/-234) or LTR 8000s, UHF use 1010s, and VHF use 1100s. Repeaters operate on a single frequency (one repeater is required for each channel). The MPC in each repeater performs all control and signaling functions on that channel. Information is exchanged between repeaters via a high-speed data bus (modular cable). No system controller is required.

Optional accessories, such as the Telephone Interconnect Card (TIC) can be installed in the repeater and the ID Validator drawer can be installed in the repeater rack. Refer to Johnson LTR ID Validator Manual, Part No. 001-4408-501 and Johnson Telephone Interconnect Card Manual, Part No. 004-2000-370 for detailed information.

1.12.2 HOME REPEATERS

All mobiles have one of the site repeaters assigned as its "Home" repeater. This is the repeater from which it receives most of its control information. When a mobile is not placing or receiving a call, it is

always monitoring its Home repeater to determine which channel is free and if it is being called by another mobile.

The Home repeater is always used to make a call unless it is busy. When the Home repeater is busy, any other repeater in the site may then be used. Up to 250 ID codes are assigned to each repeater. An ID code and Home repeater number are the "address" of the mobiles in the system. Therefore, up to 1250 separate addresses can be assigned in a 5-repeater system and up to 5000 can be assigned in a 20-repeater system. An ID code may be assigned to an individual mobile or a group of mobiles as required.

1.12.3 INTER-REPEATER DATA COMMUNICA-TION

Data communication between VIKING VX and LTR repeaters at a site is via a high-speed data bus. This bus cable is installed in a daisy-chain manner between repeaters. If both VIKING VX and LTR repeaters are located at a site, 20 repeaters can be interconnected. Refer to Section 2.8 for information on connecting the data bus.

1.12.4 MOBILE TRANSCEIVERS

The mobile and handheld transceivers used in an LTR system must be compatible with the type of signaling in use and also the frequency range.

1.13 REPEATER DATA BUS SIGNALING

1.13.1 **GENERAL**

A single-line serial data bus interconnects the logic units of all the LTR repeaters at the site. The first repeater powered on generates the synchronization pulse that is used by all other repeaters to determine their time slot on the data bus. If all repeaters are powered on at the same time, the lowest numbered repeater generates the synchronization pulse. There are 21 slots with 1-20 used for repeater reporting and 21 used by the ID Validator (see Section 1.13.3). The time slot used by a repeater is determined by the number assigned to that repeater by the programming in the MPC. Repeater 1 uses time slot 1, repeater 5 uses time slot 5, and so on. The data rate on the repeater data bus is 18,750 bits per second.

SPECIFICATIONS

GENERAL¹

Frequency Ranges 380-400, 400-430, 430-470, 470-512, 480-520 MHz Transmit/Receive

Dimensions 9.125" H x 17" W x 20.9" D

AC Voltage/Frequency 100-240V AC/50-60 Hz

AC Current

AC Input Power

O.38A (Standby), 1.4A (25W), 5A (110W)

45W (Standby), 170W (25W), 560W (110W)

DC Current at 26.5V DC (Low Power)

Number of Channels

Channel Spacing

6.3A (25W), 16.5A (110W)

1 (Synthesized, programmable)

12.5 kHz/25 kHz selectable

Channel Resolution 6.25 kHz

Temperature Range -30°C to +60°C (-22°F to +140°F)

Duty Cycle Continuous

FCC Type Acceptance ATH2422004 (25 kHz)

FCC Compliance Parts 15, 90

RECEIVER

12 dB SINAD 0.35 μV 20 dB Quieting 0.50 μV

Signal Displacement Bandwidth
Adjacent Channel Rejection

±1 kHz (12.5 kHz), ±2.0 kHz (25 kHz)
-85 dB (12.5 kHz), -90 dB (25 kHz)

Intermodulation Rejection
Spurious & Image Rejection
Audio Squelch Sensitivity
Audio Response
-85dB
-100 dB
-100 dB
-12 dB SINAD
-1/-3 dB TIA

Audio Distortion Less than 3% at 0.5W/16 ohms

Local Audio Power 0.5W/16 ohms

Audio Sensitivity $\pm 0.75 \text{ kHz}$ (12.5 kHz), $\pm 1.5 \text{ kHz}$ (25 kHz)

Hum & Noise Ratio -50 dB Frequency Spread 2 MHz

Frequency Stability ±1 PPM -30°C to +60°C (-22°F to +140°F) Modulation Acceptance Bandwidth ±3.5 kHz (12.5 kHz), ±7.0 kHz (25 kHz)

TRANSMITTER

RF Power Out 380-470 MHz 110W (Default setting), 25-110W (Variable Set Point)

470-520 MHz 100W (Default setting), 25-100W (Variable Set Point)

Spurious Emissions -90 dBc Harmonic Emissions -90 dBc

 Audio Deviation
 ±1.6 kHz (12.5 kHz), ±3.5 kHz (25 kHz)

 LTR Data Deviation
 ±0.8 kHz (12.5 kHz), ±1 kHz (25 kHz)

 CWID Deviation
 ±1 kHz (12.5 kHz), ±2 kHz (25 kHz)

 Repeat Deviation
 ±0.8 kHz (12.5 kHz), ±1.5 kHz (25 kHz)

Audio Response +1/-3 dB TIA
Audio Distortion Less than 2%

Hum & Noise (TIA) -50 dB (12.5 kHz), -55 dB (25 kHz)

Frequency Spread 6 MHz

Frequency Stability ±1 PPM -30°C to +60°C (-22°F to +140°F)

Emission Designators 16K0F3E, 16K0F3D, 16K0F1D

These general specifications are intended for reference and are subject to change without notice. Contact the Systems Applications consultants for guaranteed or additional specifications.

INTRODUCTION AND OPERATION

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January 1997 Part No. 001-2004-200

SECTION 2 INSTALLATION

2.1 INTRODUCTION

Information in this section tells how to set up the repeater for operation in an LTR system. It is assumed that the repeater has been previously aligned at the factory or as described in the alignment procedure in Section 7.

Even though each repeater is thoroughly aligned and tested at the factory, it is good practice to check performance before it is placed in service. This ensures that no damage occurred during shipment and that the repeater is otherwise operating properly. Performance testing is described in Sections 7.1, 7.2, 7.3 and 7.4.

2.1.1 SITE PREPARATION AND ANTENNA IN-STALLATION

Site preparation and antenna installation are not within the scope of this manual. Basic installation requirements are discussed in the "Dealer Guide To Site Preparation", Part No. 004-8000-100. Factory installation is also available. Contact your Johnson representative for more information.

2.2 ENVIRONMENT

The following conditions should be considered when selecting a site for the Repeater.

Operating Temperature.

-30°C to +60°C (-22°F to +140°F).

Humidity.

Less than 95% non-condensing relative humidity at 50°C.

Air Quality.

For equipment operating in a controlled environment with the Repeaters rack mounted, the airborne particles must not exceed $30 \mu g/m^3$.

For equipment operating in an uncontrolled environment with the Repeaters rack mounted, the airborne particles must not exceed $100 \mu g/m^3$.

NOTE: If the Repeater is installed in an area that exceeds these environmental conditions, the site should be equipped with air filters to remove dust and dirt that could cause the equipment to overheat.

When the repeaters are installed in an environment that contains small airborne particles, e.g. grain dust or salt fog, the repeater cabinets need to be sealed. A heat exchanger, i.e. air conditioner, is then required to cool the cabinets. The air conditioners must be suited for the environment. Each repeater (110W) requires >2400 BTU/hr dissipation to maintain exterior cabinet temperature.

2.3 VENTILATION

The RF modules and the power supply are equipped with fans, controlled by thermostats, that force air through the equipment for cooling. The air flow is from the front to the back of the equipment. This permits the Repeaters to be stacked or rack mounted (see Figure 2-3). There are a few considerations when installing Repeaters to provide adequate air circulation.

 The Repeaters should be mounted with a minimum of 6 inches clearance between the front or back of the cabinet for air flow. The power supply requires a minimum of 18 inches at the back of the Repeater for removal.

NOTE: Repeaters should not touch. Leave a minimum of one empty screw hole (approximately 1/2") between repeaters vertically especially for bottom ventilation slots in high power repeaters.

- 2. Cabinet enclosures must provide air vents for adequate air circulation.
- 3. Temperature and humidity must be considered when several Repeaters are installed at a site. This might require air conditioning the site.

INTRODUCTION AND OPERATION

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January 1997 Part No. 001-2004-200 management or architects. Tower site grounds must be made with grounding rods. The many techniques for providing adequate grounds for towers and poles and for installing building ground bus lines are beyond the scope of this manual. Refer to National Electrical Code article 250 "Grounding Techniques," article 800 "Communications Systems" and follow local codes.

The ground bus should be routed to the floor area within 5 feet of the system with a runner of 6 AWG or larger solid copper wire or 8 AWG stranded copper wire.

The outer conductor of each transmission line at the point where it enters the building should be grounded using 6 AWG or larger solid copper wire or 8 AWG stranded wire.

Secondary protection (other than grounding) provides the equipment protection against line transients that result from lightning. There are two types of secondary protection, RF and Telephone Line. Use the same wire sizes as specified for coaxial cables for any ground connections required by the secondary protectors.

RF

An RF protector keeps any lightning strike to the antenna feed line or tower from damaging the Repeaters. Install this protection in-line with the combiner and antenna feed line.

RF protectors are selected by calculating the maximum instantaneous voltage at the output of the combiner. Do this by using the following equation.

$$V_P = 1.414 (X) (\sqrt{P(50)})$$

where:

 V_p = Voltage at the output of the combiner. P = repeater output in watts

X=	for	VSWR=
1.05		1.10:1
1.09		1.20:1
1.13		1.30:1
1.17		1.40 : 1
1.20		1.50:1
1.30		1.86:1

Example: Repeater power output of 60W with a VSWR of 1.3 : 1 (for this VSWR, X = 1.13):

$$V_p = 1.414 (1.13) (\sqrt{60(50)})$$

 $V_p = 1.59782 (\sqrt{60(50)})$
 $V_p = 1.59782 (54.772256)$
 $V_p = 87.52V$

Telephone Line

There are four types of protection suppressors for telephone lines; Gas Tube, Silicon Avalanche Diode, Metal Oxide Varistor and Hybrid.

The hybrid protector is ideal for E.F. Johnson equipment, and is strongly recommended. A hybrid suppressor combines several forms of protection not available in just one type of device. For example, a high-speed diode reacts first, clamping a voltage strike within 10 ns, a heavy duty heat coil reacts next to reduce the remainder of the current surge, and a high-powered three-element gas tube fires, grounding Tip and Ring.

2.6.1 PROTECTION GUIDELINES

Follow these guidelines for grounding and lightning protection. Each Repeater installation site is different; all of these may not apply.

- Ensure that ground connections make good metalto-metal contact (grounding rod, grounding tray, metal conduit) using #6 gauge solid wire or braided wire straps.
- With surge protectors, ensure that ground wires go directly to ground, and not through other equipment.
- 3. Run the ground wire for RF coax protectors directly to ground.
- With coax protectors, ensure maximum instantaneous voltage does not exceed the rated voltage.
- Do not run ground wires parallel to any other wiring (e.g. a ground wire parallel to a telephone line), except other ground wires.
- Double check all equipment for good ground and that all connections are clean and secure.

2.4 AC POWER

The AC power source to the Johnson VIKING VX Repeater can be 120V AC or 240V AC. Nothing need be done to the power supply for 240V AC operation. However, a 240V AC outlet requires that the 120V AC power plug be replaced. A locking AC power cord is provided for the supply.

The 120V AC cord is a standard 3-wire grounded cord used with a standard AC wall outlet. The outlet must be capable of supplying a minimum of 560W. With the nominal 120V AC input, the source must supply 5A for each 110W repeater and should be protected by a circuit breaker. It is recommended that all of the repeaters in a rack should not be on the same breaker in order to provide one operational repeater in the event a breaker trips. An AC surge protector is recommended for all equipment.

Each Repeater requires an outlet, so for a 5-channel system, a minimum of 5 outlets is required. An additional three outlets should be added for test equipment. The outlets must be within 3 feet of each Repeater cabinet. Future system expansion should be considered when electrical work is being planned for the initial system.

The VIKING VX Repeater power supply can be equipped with an optional 24V DC back-up in the event of AC power failure. Since the transmitter will remain on full power, if desired, the DC power source must have a current capability of about 20A per 110W repeater or 100A for 5 - 110W repeaters. The multi-coupler requires another 0.5A for a total system requirement at 24V DC of 100.5A for 110W repeaters.

2.5 BATTERY BACKUP

If the power supply is equipped with battery backup, screw lugs are provided on the front of the power supply for battery connections (see Figure 2-1). A switch is provided for charging the battery or can be off if a separate battery charger is used. A battery temperature sensor connection is also provided. The temperature sensor cable is shown in Figure 2-2. LED indicators are provided to show Reverse Battery connection, Charger On/Off and Battery Fault.

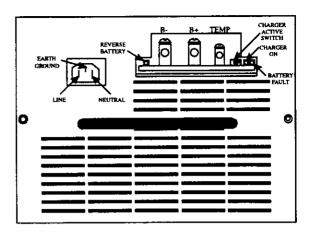


Figure 2-1 BATTERY BACKUP CONNECTOR

The temperature sensor is required to adjust the charging voltage over temperature.

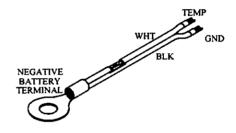


Figure 2-2 TEMPERATURE SENSOR CABLE

2.6 GROUNDING

CAUTION

PROPER SITE GROUNDING AND LIGHTNING PROTECTION ARE VERY IMPORTANT TO PRE-VENT PERMANENT DAMAGE TO THE REPEATER.

As in any fixed radio installation, measures should be taken to reduce the possibility of lightning damage to the Viking VX equipment. Proper grounding eliminates shock hazard, protects against electromagnetic interference (EMI) and lightning.

Ground each piece of equipment separately. Do not ground one piece of equipment by connecting it to another grounded piece of equipment. A good DC ground must be found or created at the site. Rooftop site grounds can be researched through the building

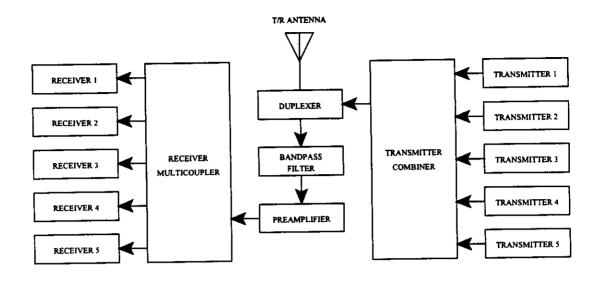


Figure 2-4 5-CHANNEL COMBINING SYSTEM

2.8 REPEATER DATA BUS INSTALLATION

VIKING VX repeaters with High Speed Data Bus (HSDB) software Version 201 or earlier (reference U14 label) installed on the MPC board must use the optional RJ-11 to BNC Adapter Module (see Table 1-1 and Figure 2-7) to connect the HSDB. Any VIKING VX repeater (regardless of the HSDB software version) that connects to a HSDB that is also servicing LTR 1010 repeaters, other VIKING VX repeaters that use VIKING VNC cards, or an ID Validator must also use the adapter module. The BNC Adapter Module is installed on the back of the VIKING VX repeater cabinet (see Figure 2-11).

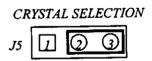
Systems constructed only with LTR VIKING VX repeaters that have Version 202 or later HSDB software and do not use VNC cards can be connected directly to the HSDB from the RJ-11 jack on the back of the repeater.

2.8.1 MPC DATA BUS SWITCH SETTINGS

Switch settings on the MPC for the two types of installations require S2 and S3 sections to be switched as indicated in Figures 2-8 through 2-11.

2.8.2 MPC DATA BUS JUMPER SETTINGS

Refer to Figure 2-5 for crystal selection and HSDB Code selections jumper placement. The jumper on J5, pins 2-3 selects 12 MHz crystal for LTR. The jumper on J4, pins 3-4 connects EPROM U14, pin 27 (A14) to +5V for LTR single-ended 5V data bus.



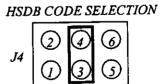


Figure 2-5 MPC JUMPERS

Jumper J4 must be placed with the following guidelines (see Figures 2-8 through 2-11).

2.7 UNPACKING AND INSPECTION

E.F. Johnson ships the Repeater securely crated for transportation. When the Repeater arrives, ensure the crates remain upright, especially if storing the crates temporarily.

When unpacking the Repeater, check for any visible damage or problems caused by shipping. If there is obvious damage from shipping mishaps, file claims with the carrier. If there appears to be any damage caused before shipping, file a claim with E.F. Johnson. Contact Customer Service for assistance (see Section 1.7).

If everything appears undamaged, remove the Repeater equipment from the crate, using normal precautions for unpacking.

NOTE: Do not discard the packing materials. If you must return an item; use the same packing materials and methods (including static protective bags for circuit cards) to repack the equipment. You are responsible for proper repacking. E.F. Johnson cannot be responsible for damage to equipment caused by negligence.

NOTE: Repeaters should not touch, leave a minimum of one empty screw hole (approximately 1/2") between repeaters vertically especially for bottom ventilation slots in high power repeaters.

NOTE: Each repeater should be grounded separately by connecting a ground bus from the ground lug on the back side of the RF module to the ground bar on the rack (see Figure 2-6).

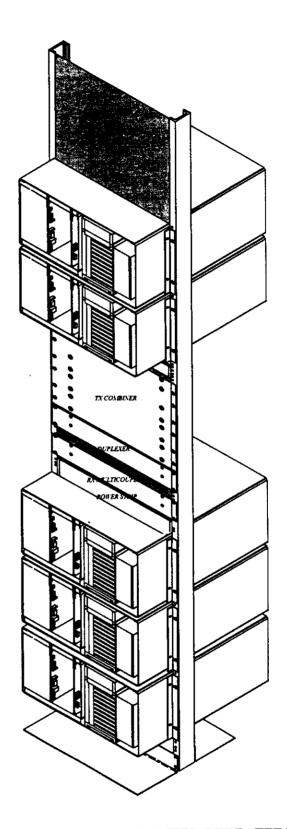


Figure 2-3 RACK MOUNTED REPEATERS

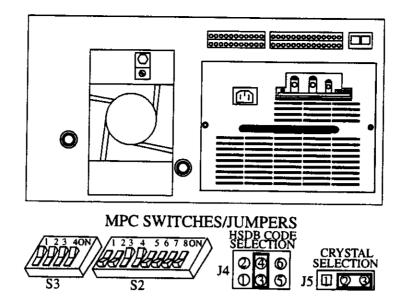


Figure 2-8 SINGLE REPEATER INSTALLATION

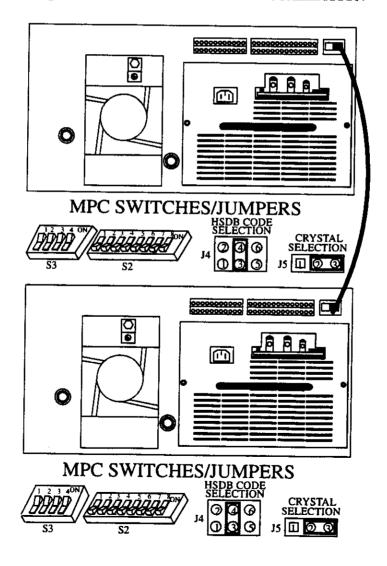


Figure 2-9 TWO REPEATER INSTALLATION

J4, pins 3-4 for operation with the RJ-11 to BNC adapter module with 200X and 1010 mixed systems with any version of HSDB software (see Section 4.5.4).

J4, pins 3-4 for operation with the RJ-11 to BNC adapter module with 200X only systems with any version of HSDB software.

J4, pins 5-6 for operation with the RJ-11 to RJ-11 cable with 200X only systems with Version 202 or later HSDB software (see Section 4.5.4).

2.9 CONNECTING RECEIVE AND TRANSMIT ANTENNAS

Receive and Transmit antenna connector locations are shown in Figure 2-6. Although each transmitter and receiver could be connected to a separate antenna, this is usually not done because of the large number of antennas required by a multiple repeater installation. Therefore, an antenna combining system is usually used. An example of a combining system for a five-channel system is shown in Figure 2-4. The amount of power loss introduced by a combiner depends on the type of combiner used. If it has a loss of 3 dB, power output to the antenna is reduced by half.

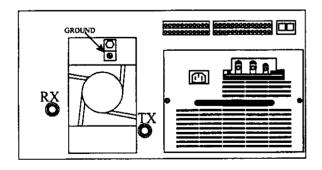


Figure 2-6 ANTENNA CONNECTIONS

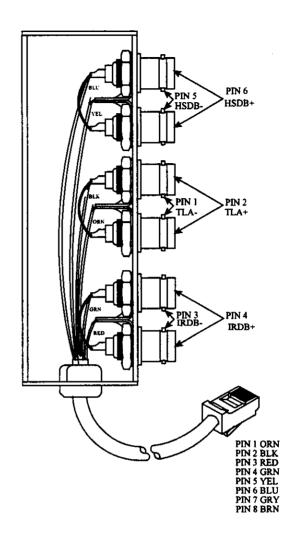


Figure 2-7 RJ-11 TO BNC ADAPTER MODULE

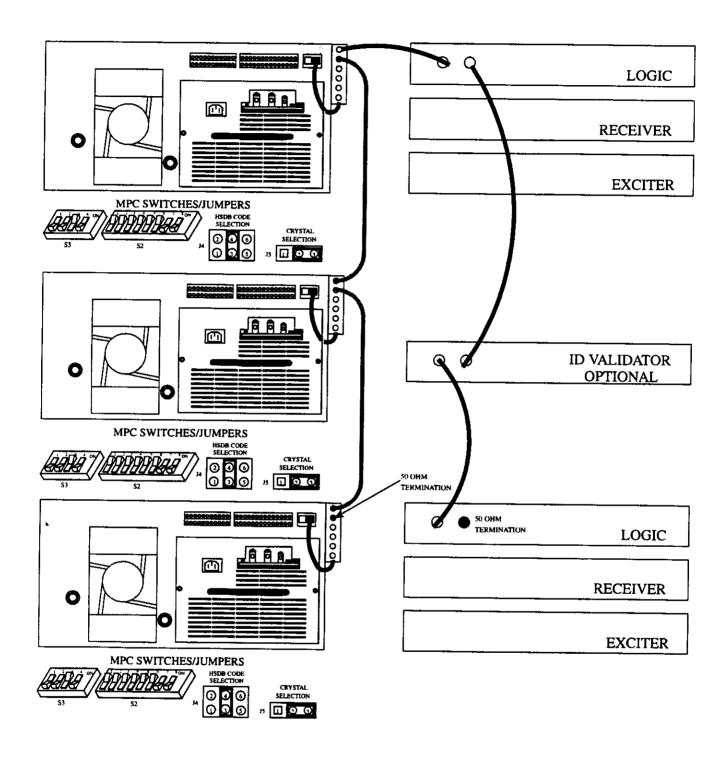


Figure 2-11 MIXED VIKING VX AND CR1010 REPEATER INSTALLATION

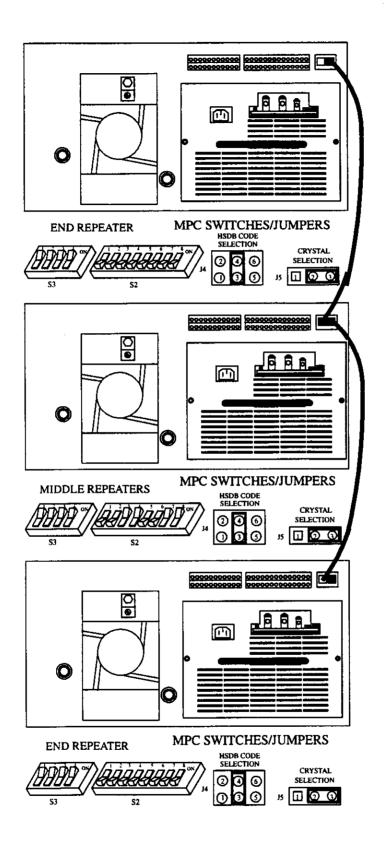


Figure 2-10 THREE OR MORE REPEATERS INSTALLATION

SECTION 3 SOFTWARE

3.1 INTRODUCTION

The Johnson 2004 Repeater Program on 3.5 inch disk, Part No. 023-9998-390, uses an IBM® personal computer to program the EEPROM Memory in the Main Processor Card (MPC). To lessen the chance of programming errors and simplify operation, the program uses yes/no questions or toggles through the available responses.

The computer is connected directly from the serial card to the MPC. The interconnect cables used are shown in Figure 4-29. The DB-9 to 8-pin modular adapter is connected to the serial port of the computer and an interconnect cable connects the adapter to the MPC.

NOTE: These connections are for the IBM computer and may differ from an IBM compatible. In which case, consult the manuals for your computer for serial card outputs and connections.

3.1.1 HOW TO USE THIS MANUAL

This manual introduces the program and illustrates how to use the features. This manual is organized to easily find programming information with the Table of Contents, Index and Parameter Tables for the responses required for programming.

Graphic reproductions of the screens are shown for reference. Adjacent to the screens are tables to provide the parameters, available responses and a brief description of the parameter. It is not the intent of this manual to teach computer operation, but to allow the user to become familiar with the available screens and the responses without having to be at the computer.

3.1.2 GETTING STARTED

NOTE: Before starting you should already know how to start MS-DOS®, format and make backup copies of disks, copy and delete files, and run programs. If you are unfamiliar with any of these actions, refer to the MS-DOS manual for your computer for more information (see Section 5).

Follow the computer instructions for loading the disk. The MS-DOS Revision 2.0 or later operating system is needed to run the programs. The computer needs to have RS-232C capability, for example, the Serial Card in slot "COM1" or "COM2".

3.1.3 COMPUTER DESCRIPTION

The programming software is designed to run on an IBM PC or compatible computer that meet the following minimum requirements.

- 1. One 3.5" high density disk drive.
- 2. 640K of memory
- 3. MS-DOS version 2.0 or higher
- 4. One serial port
- 5. Monochrome or color monitor and video card

Although the program uses color to highlight certain areas on the screen, a monochrome (black and white) monitor or LCD laptop also provide satisfactory operation. Most video formats such as EGA and VGA are supported. A serial port is required to connect the Repeater to the computer. This port is standard with most computers.

The cables from the Repeater to the computer are not included. With most computers, the adapter-to-computer cable is a standard DB-25 M-F cable, PN 023-5800-017, (the male connector plugs into the adapter). If your computer requires a male connector, a male-to-male cable is also available, PN 023-5800-016. The cable from the adapter to the Repeater has a modular-type 8-pin connector (see Figure 4-29).

3.1.4 EEPROM DATA STORAGE

The data programmed into the MPC is stored by an EEPROM Memory. Since this type of device is nonvolatile, data is stored indefinitely without the need for a constant power supply. A repeater can be INSTALLATION

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January 1997 Part No. 001-2004-200 If you have a single floppy drive and no hard disk drive, you need to create programming disks. The reason for this is that there is not adequate space on the backup disk(s) for storing radio files. If your computer has dual floppy disk drives, the backup disk can be placed in one drive and then the radio files stored on a disk in the second drive.

To make a programming disk, format a blank disk using FORMAT B: or FORMAT B: /S (use "/S" if it must be a bootable disk). Then copy the required program file or files to the programming disk. To do this, type COPY A:(filename.ext) B:(filename.ext). For example, to copy the file 2004pgm2.exe from drive A to drive B, type

COPY A:2004pgm2.exe B:2004pgm2.exe

This procedure works for either single or dual drive computers. Refer to your computer reference manual for more information on these DOS commands.

The programming software is shipped in a compressed format. The name of the compressed file is 2000pgm2.exe and it extracts the following files so the program can be used on a PC.

2004PGMR.EXE	469K
2004PGMR.HLP	42K
UHF12LMN.HLP	2K
2004PGMR.LNF	165K
UHF12LMN.LNF	11 K
UHF12LMN.LNF	236K
UHF12LUS.LNF	59K
UHF25LMN.LNF	11 K
UHF25LMN.LNF	227K
UHF25LUS.LNF	58K

The 2004PGM2.EXE file is self extracting which means that the files extract automatically when executed. To extract these files so the program can be used, first make the current directory the destination directory for these files. For example, to make it the \RADIOPRG directory on drive C: (if not the current directory), type C: (Return) and then CD \RADIO-PRG as just described. To make it the disk in drive B:, simply type B:. Then insert the program disk in drive A: and type A:2004PGM2 (or B: 2004PRM2 if drive B: is being used). The program files are automatically extracted into the current directory or disk.

3.2.2 MINIMUM FREE MEMORY REQUIRED

Approximately 560K of free conventional memory is required to run this program (use the CHKSK or MEM command to display the amount of free memory). If you have at least 640K of memory and not enough is available, there may be other programs that are also being loaded into conventional memory. Contact Customer Service for information on how these programs can be moved or disabled to make more space available.

3.3 REPEATER PROGRAMMER

When the program is loaded into the computer and executed, the menu shows the files available from the directory. The program is used to create, edit, transfer and receive the repeater and channel parameters described in Section 5.

IMPORTANT

The commands and displays referred to in this manual are for the IBM PC and may differ from IBM compatible. Refer to the computer's operating system manual for command explanations.

3.3.1 PROGRAM FILES

The files in the software directory are needed to run the program.

3.4 ALIGNMENT SOFTWARE

File Edit Transfer Hardware Test Utilities

PA
Receiver
Exciter
Full Rptr/Station
RNT Interface
Telephone Interface
VNC Interface

Figure 3-1 REPEATER TEST MENU

The software for the VIKING VX repeater programs the MPC to open and close the audio/data gates necessary for the alignment selected from the Test-Full Repeater menu. Under the menu heading Test are

removed from the site or even stored indefinitely without affecting programming. Since EEPROM Memory is also reprogrammable, a new device is not needed if programming is changed.

3.1.5 COMMAND LINE OPTIONS

HELP

To show all options available from the command line type: /h or /?. Either '/' or '-' can be used. For example: 2004pgmr /h

The options can be entered in any order. For example: 2004pgmr /d /b /c

COM PORT

The Johnson programming software defaults to serial port COM1. However, if this port is already in use, the software can be reconfigured to use serial port COM2. To do this, use one of the following methods:

- When running the compiled (.EXE) version, type / c2 on the command line after the program name.
 For example: 2004pgmr /c2 or -c2
- 2. Select COM port from Utilities heading.

BAUD RATE

The software defaults to 9600 baud, however this rate can be changed. To do this from the command line, type /bxxxx (xxxx = baud rate). For example: 2004pgmr /b or -b

NOTE: When the baud rate is changed on the command line, the baud rate jumpers on J3 in the MPC must also be changed to the same baud rate (see Section 6.8.8).

DEMO MODE

To view the screens for Read Setup Parms and Write Setup Parms from the Transfer menu when a repeater is not connected to the computer this option is used. Normally these screens are not available without a repeater connected. To do this from the command line, type: /d or -d.

For example: 2004pgmr/d

3 1 6 COLOR OR MONOCHROME OPERATION

The programming software utilizes color for a color monitor and video card. However, with LCD-type displays, this may make some information hard to read because the contrast is poor. To improve contrast, a monochrome mode can be selected in the display mode from Utilities heading.

3.2 REPEATER PROGRAM SOFTWARE

3.2.1 INSTALLING THE SOFTWARE

When you receive the programming software, make a backup copy and store the master in a safe place. Copy the distribution disks using DOS DISK-COPY command. For example, type:

DISKCOPY A: A: (single floppy drive)

or

DISKCOPY A: B: or C: (multi-drive systems).

If you have a hard disk drive, you may want to create one or more separate directories for transceiver programming and then transfer the program disk files to those directories. To create a new directory, use the MKDIR command. For example, to create directory RADIOPRG, type:

MKDIR \RADIOPRG.

Then to make the new directory the current directory, use the CHDIR command. For example, to change to the \RADIOPRG directory, type

CHDIR \RADIOPRG.

To copy all files from a floppy disk in drive A: to this directory, type:

COPY A:*.*

SECTION 4 PULL DOWN MENUS

4.1 MENU DISPLAYS

The menus available are listed at the top of the screen (see Figure 3-2). Move the cursor with the arrow keys to highlight the menu name. Press Enter to view the menu and the arrow keys to scroll through the menu. Call up the highlighted selection by pressing Enter.

4.2 FILE MENU

This menu manipulates new or existing files into directories and saves files to be called up at another time.

File Edit Transfer Hardware Test Utilities

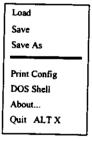


Figure 4-1 FILE MENU

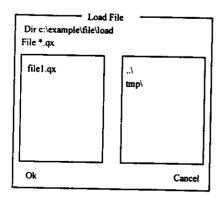


Figure 4-2 LOAD FILE

4.2.1 LOAD

Load reads information from a stored file. The program requests the filename to be loaded into the buffer. The filename from a disk can be entered in the highlighted area. Then move the cursor down with the arrow key and highlight "Ok" and press Enter. To select an existing file, use the arrow keys to move down the menu list and press Enter when the highlighted filename is the file to load.

4.2.2 SAVE

This saves the edited version of an existing file loaded in the buffer under the same filename in the directory and deletes the old file. It loads a new file created in the Edit menu into the directory.

4.2.3 SAVE AS

This saves the edited version of an existing file loaded in the buffer under a new filename or gives a new file created in the Edit menu a filename.

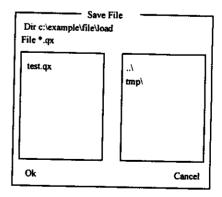


Figure 4-3 SAVE FILE

the alignment procedures for the PA (see Section 7.3), Receiver (see Section 7.1), Exciter (see Section 7.2) and overall Full Repeater (see Section 7.5) including the MAC card (see Figure 3-1).

Refer to Section 7 for Alignment Procedures as shown in the program, alignment points diagrams and test setup diagrams.

3.5 HELP F1

Help screens are available for most parameters and options in this program. Whenever a parameter or options clarification is needed, press F1 and if a help screen is available it will pop-up on the screen. Press Escape <ESC> to exit the pop-up screen.

HELP - F1

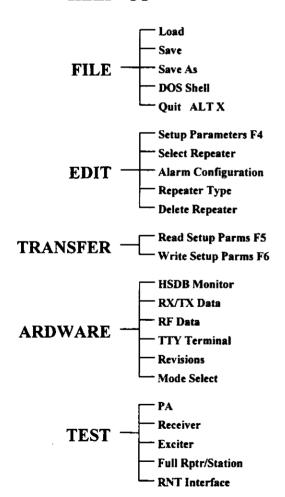


Figure 3-2 PROGRAMMING FLOWCHART

Part No. 001-2004-200

TRANSMIT ID

Each of the 8-alarm outputs can be assigned a Group ID from 1-225. The default setting is 0 (zero) for disabled. This Group ID and the Repeater number identify an alarm that is active. This ID can be programmed into a transceiver so that when the alarm is active, the alarm description is received in Morse code.

ALARM TRANSMIT RATE

This sets the time interval for transmitting the alarm message in Morse code. If more than one alarm is active, this is the inter-alarm time.

CROSS REFERENCE

The cross reference screen selects the output alarm that is activated by each input alarm. There are up to 48 alarms (0-47), 4 external input alarms and 40 internal alarms (see Table 1-2). There are four output alarms. An alarm condition on any input can cause an output alarm. This screen configures which input alarm activates an output alarm.

NOTE: More than one alarm condition can have the same output alarm (see Figure 4-10).

	Alar	m Cross Re	ference Sele	ction	
Select	which Outp	ut Alarm is	activated by	each Input	Alarm.
0. None	8. None	16. None	24. None	32. None	40. None
1.1	9. None	17. None	25. None	33. 4	41. None
2.1	10. None		26. None	34. None	42. None
3. 2	11. None	19. None	27. None	35. None	43. None
4.3	12. None	20. None	28. None	36. None	44. None
5. None	13. None	21. None	29. None	37. None	45. None
6. None	14. None	22. None	30. None	38. None	46. None
7. None	15. None	23. None	31. None	39. None	47. None
Press F2 to Accept					

Figure 4-10 ALARM CROSS REFERENCE

4.3.4 REPEATER TYPE

This screen (see Figure 4-11) selects the repeater type (LTR signaling protocol and features):

Frequency Band	UHF
Power Level	110W
IAC Type	4 I/O IAC
	8 I/O IAC

Repeater Type Selection

Select the Repeater Type LTR

Channel Bandwidth: UHF (25k)
Frequency Band: 380-470 MHz
LAC Type: 4 I/O LAC
Press F2 to Accept
Select Signaling Method (Spacebar)

Figure 4-11 REPEATER TYPE

4.3.5 DELETE REPEATER

Select Rptr To Delete Rptr 1

Figure 4-12 DELETE REPEATER

4.3.6 TELEPHONE PARAMETERS

Refer to the Telephone Interface Card manual, Part No. 004-2000-370, for information on the Telephone Access Parameters, Telephone Interface and TIC Calibration Data.

4.4 TRANSFER

File Edit Transfer Hardware Test Utilities

Read Setup Parms F5
Write Setup Parms F6
Read TIC Calibration Data
Write TIC Calibration Data
Edit Option Keys

Figure 4-13 TRANSFER MENU

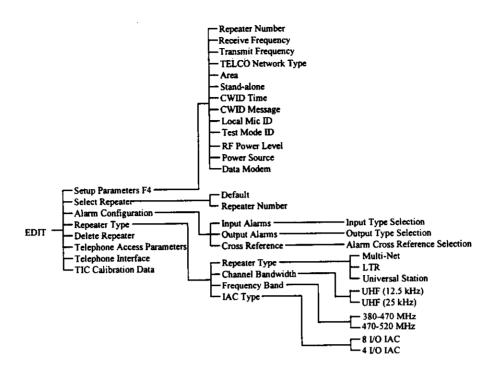


Figure 4-4 EDIT PROGRAMMING FLOWCHART

4.2.4 PRINT REPEATER CONFIGURATION

Select the destination for the configurations. Printer - Prints to printer connected to PC. File - Writes printable test to selected filename.

Select which repeater data will be printed.

All Repeaters - Prints the data for all valid repeaters.

Single Repeater - Prints the data for the entered repeater number.

NOTE: A list of valid repeaters can be seen under the Edit-Select Repeater menu selection.

4.2.5 DOS SHELL

DOS shell temporarily suspends the program and returns to DOS. Directories and other DOS commands can be performed. To return to the program from DOS, type EXIT and press Enter.

4.2.6 QUIT (ALT X)

Quit exits the repeater program and returns to DOS. Save all files before exiting the repeater program.

4.3 EDIT

File Edit Transfer Hardware Test Utilities

Setup Parameters F4	
Select Rptr	
Alarm Config	
Auxiliary Parms	
Repeater Type	
Delete Rptr	
Telephone Access Parms	
Telephone Interface	
TIC Calibration Data	

Figure 4-5 EDIT MENU

4.5.1 HSDB MONITOR

High Speed Data Bus (HSDB) connects all repeaters at a site and continually sends updates on the status of each repeater. This information screen provides a list of all repeaters at the site (1 to 20). If a repeater is not sending data, IDLE is next to the repeater number. The data sent by the repeater is used to determine the Home, GID and UID of destination (mobile) users to receive the call placed by the originator.

The Home column refers to the Home repeater number of the originator, therefore the Repeater number and the Home number may not be the same number. The UID is the Unique ID used to identify the originator of special calls. The GID column refers to the Group ID of the talk group of the originator (236=UID Call, 237 Telco call). The GoTo column shows the repeater channel all destination users switch to so they receive the call.

Rptr Home UID GoTo GID

Figure 4-20 HSDB MONITOR

4.5.2 RECEIVE/TRANSMIT DATA

This is an information screen used at the repeater site while the computer (laptop) is connected to the MPC in the repeater being monitored. This information is contained in the receive data stream exchanged between the repeater and the destination user (mobile) and the data content of the repeater transmit data stream. The message contains data received from the destination and data sent to the mobile by the repeater. The repeater receives the destination's: Unique ID, Home Repeater Number, Group ID, Priority, Status and Time Stamp. The information sent to the destination in the update message from the repeater includes: Unique ID of originator, Home Repeater Number, Group ID, GoTo Channel Number, Free Channel Number and Priority of the current repeater. The time stamp is included because messages are sent continually and this provides a reference for when a data exchange took place.

UID Home GID Pri Stat Time

Figure 4-21 MOBILE TRAFFIC MONITOR

4.5.3 RF DATA

The A/D Monitor Screen shows the state of the lines (see Figure 4-22). These lines are monitored by the A to D converter in the IAC. The normal values for each line are defined as follows.

Synthesizer Lock Lines	Yes or No
Forward Power (LP)	25-110 Watts
Reflected Power	0-6 Watts
Final Out (ratio)	approx equal
Chassis Temp	27°C-55°C
Wideband Audio Output	approx 200
LO Injection	approx 200
RSSI	20-150
Fan Current	100-200, 0
Fan	On or Off
Power Supply Temp	22°C-45°C
Battery Voltage	21V-28V

Values with no label are the actual A to D reading. To calculate the voltage on the line, divide the value by 51. Example: Value ÷ 51 = Volts. Any variation from the above values may indicate a problem in that area. Values on this screen are relative measurements only.

RF Line Monitor			
Synthesizer Lock Lines	Receive Paramet	crs	
Exciter Synthesizer: Yes Receive Synthesizer: Yes Exciter High Stability: No Receive High Stability: No	Wideband Audio Output LO Injection: RSSI:	t: 0 0 0	
Transmit Parameters (Not Calibrated)	System Paramete:	rs O	
Forward Power: 0 Watts Reflected Power: 0 Watts	Fan 2 Current: Fan On:	0 Off	
Final Output 1/2: 0/ 0 ratio Final Output 3/4: 0/ 0 ratio	Chassis Temp: Power Supply Temp: Battery Voltage:	0 C 0 C 0 Volts	

Figure 4-22 RF LINE MONITOR

4.3.2 SELECT REPEATER

Select the repeater number to be programmed or edited from the pop-up menu (see Figure 4-6). Move the cursor with the arrow keys to highlight the repeater number and press Enter.



Figure 4-6 REPEATER LIST

4.3.3 ALARM CONFIGURATION

This programs the input alarm (see Figure 4-8) and output alarm (see Figure 4-9) configurations and provides a cross reference screen.

Select Which Alarms To Edit
Input Alarms
Output Alarms
Cross Reference

Figure 4-7 ALARM CONFIGURATION

Use the arrow keys to move down the list. Use the Space bar to toggle through the parameters: Disabled, Active Low, Active High, for each alarm.

INPUT ALARMS

There are four input alarms that can be activated by external devices (see Section 6.10). These inputs can be disabled, energized or de-energized. Alarms 3 and 4 can also be analog input.

If the input is disabled, the input alarm line is inactive. When energized and current flow is detected, the alarm is activated. When de-energized and no current flow is detected, the alarm is activated. Analog inputs provide a detection of an analog input out of limit condition. Select the Low and High Limit pair to trip an Analog Input Alarm. The High Limit must be greater in value than the Low Limit (0.0V-5.0V in 0.1V steps).

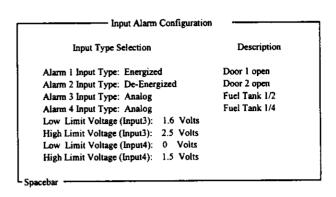


Figure 4-8 INPUT ALARMS

OUTPUT TYPE SELECTION

Select the operation of the Output Alarm. The available types are:

Active Open - An active alarm opens (no contact) the output lines.

Active Closed - An active alarm closes (contact) the output lines.

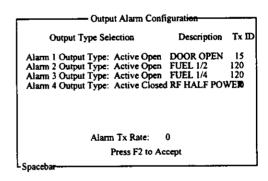


Figure 4-9 OUTPUT ALARMS

ALARM DESCRIPTION

This is a text string (up to 15 characters) to describe the alarm. This test string is sent via Morse code if the alarm input is programmed with a Tx ID and an output is selected in the cross reference menu (see Figure 4-10).

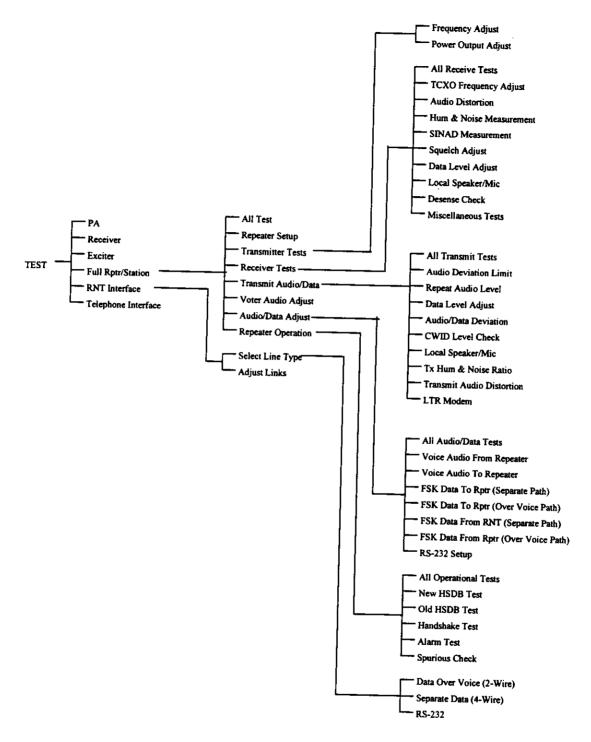


Figure 4-25 TEST PROGRAMMING FLOWCHART

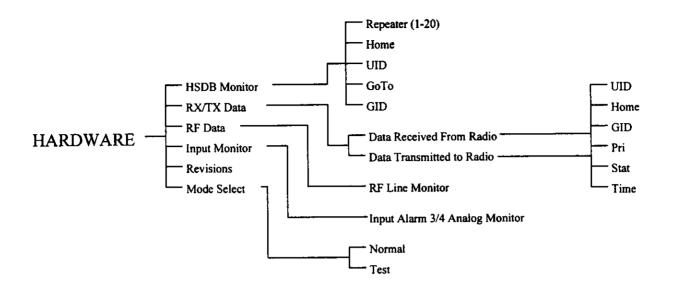


Figure 4-14 HARDWARE PROGRAMMING FLOWCHART

4.4.1 WRITE SETUP PARAMETERS

This command sends the contents of a file to the repeater and programs the EEPROM memory in the Main Processor Card (MPC).

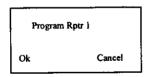


Figure 4-15 WRITE SETUP PARAMETERS

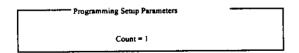


Figure 4-16 PROGRAM WRITE SETUP

4.4.2 READ SETUP PARAMETERS

This command reads the contents of the EEPROM memory of a repeater and loads it into a buffer. The contents of the buffer is then displayed to show the programming of the repeater.

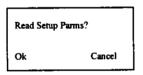


Figure 4-17 READ SETUP PARAMETERS

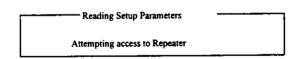


Figure 4-18 READING SETUP

4.5 HARDWARE

File Edit Transfer Hardware Test Utilities

HSDB Monitor
Rx/Tx Data
RF Data
Input Monitor
Revisions
Mode Select

Figure 4-19 HARDWARE MENU

Select Color Mode Desired

(*) Color () Monochrome

- Spacebar to Select

Figure 4-30 COLOR MODE SELECTION

4.7.3 USER LEVEL

There are two levels to choose from, Novice and Advanced. The Novice uses prompts in the Edit-Parameters screens when Escape or F2 keys are pressed that ask "are you sure" before the task is executed. The Advanced selection performs the task without asking the question.

4.5.4 REVISION/VERSION

The Revision/Version is displayed for the repeater modules in this screen. The format is R.V (revision.version) for all modules. The MPC information also includes the release date of the software and the serial number of the repeater. The HSDB version in Figure 4-23 is for J4, pins 5/6 connected in the MPC and Figure 4-24 is the version for J4, pins 3/4 connected in the MPC.

4.5.5 MODE SELECT

The Mode Select screen places the repeater either in the Normal mode or the Test mode. In the Normal mode the repeater operates as a normal repeater.

In the Test mode the repeater transmits a test word. This test word is the Test Mode ID setup in the Setup Parameters (see Section 4.3.1).

CAUTION

While in the test mode the repeater is "busy", therefore it is important to place the repeater in Normal mode when the test mode is no longer required.

Repeater Version Display

Reneater Number: 1

HSDB: 2.1d MAC: 1.09 TIC: 0.00

MPC or TPI: 11.19 11/20/96 11 Serial Number: 1234567891234567

Figure 4-23 REVISION/VERSION

Repeater Version Display

Repeater Number: 1

HSDB: 50.02 MAC: 1.09 TIC: 0.00

MPC or TPI: 11.19 11/20/96 11 Serial Number: 1234567891234567

Figure 4-24 REVISION/VERSION

SECTION 5 REPEATER PROGRAMMING

5.1 CREATING A NEW FILE

An example will be used to show the programming for a new file created for Site 1.

NOTE: At any point in the programming sequence, if F1 is selected, a help screen appears to explain the menu selection highlighted at that point.

5.1.1 SELECT REPEATER TO EDIT

A repeater is selected to program. When no file exists with programmed repeaters, the default is selected and edited.

- 1. Highlight EDIT, press Enter.
- 2. Highlight SELECT REPEATER, press Enter.
- 3. Default is the only repeater in this list, press Enter.
- 4. Highlight EDIT, press Enter.
- 5. Highlight SETUP PARAMETERS, press Enter.
- 6. The Setup Parameters screen appears (see Figure 5-1). Fill in the parameters for this repeater. A brief description of the parameters is in Table 5-1. Full descriptions are in Section 4.3.1.
- 7. Select parameters, press F2 to accept.
- 8. Highlight EDIT, press Enter.
- Highlight ALARM CONFIGURATION and press Enter, if alarms are to be configured.
- 10. Program the Alarms to be configured (see Section 4.3.3), press F2 to accept.
- 11. Highlight FILES, press Enter.
- 12. Highlight SAVE, press Enter.

- 13. Type in a valid DOS filename. For this example site1.dat is used.
- 14. The file consists of default and repeater one under the filename of site 1.dat.

5.2 ADDING A REPEATER TO A FILE

The example used for Site 1 will again be used to add repeaters to the filename site1.dat.

- 1. Highlight EDIT, press Enter.
- 2. Highlight SELECT REPEATER, press Enter.
- The repeater list shown for this file includes default and repeater one. These contain the same parameters with the exception that when selected for edit the programmed repeater can be overwritten and the data lost.
- 4. Highlight DEFAULT, press Enter.
- 5. Highlight EDIT, press Enter.
- 6. Highlight SETUP PARAMETERS, press Enter.
- 7. Change the Repeater number and other parameters as required for this repeater, press F2.
- 8. Highlight EDIT, press Enter.
- Highlight ALARM CONFIGURATION and press Enter, if alarms are to be configured.
- 10. Program the Alarms to be configured (see Section 4.3.3), press F2 to accept.
- 11. Highlight FILES, press Enter.
- 12. Highlight SAVE, press Enter.
- 13. Repeater 2 is added to the Repeater List in file site 1.dat.

4.6 TEST

File Edit Transfer Hardware Test Utilities

PA
Receiver
Exciter
Full Rptr/Station
RNT Interface
Telephone Interface
VNC Interface

Figure 4-26 TEST MENU

4.6.1 POWER AMPLIFIER

This menu selection walks through the alignment of the Power Amplifier and RF Interface Board on the computer screen. Refer to Section 7.3 for the PA and RFIB alignment in this manual and Figures 7-3 and 7-4 for alignment points diagrams.

4.6.2 RECEIVER

This menu selection walks through the alignment of the receiver on the computer screen. Refer to Section 7.1 for the Receiver alignment in this manual and Figure 7-1 for an alignment points diagram and Figure 7-8 for a test setup of the Receiver.

4.6.3 EXCITER

This menu selection walks through the alignment of the Exciter on the computer screen. Refer to Section 7.2 for the Exciter alignment and Figure 7-2 for an alignment points diagram and Figure 7-2 for a test setup of the Exciter.

4.6.4 FULL REPEATER

This menu selection walks through the alignment of the entire repeater. The Receiver and Exciter portions are performance tests and adjustments. The Audio and Data portions are level adjustments for the Main Audio Card (MAC). Refer to Figure 7-16 for an alignment points diagram for the MAC.

4.7 UTILITIES

File Edit Transfer Hardware Test Utilities

COM Port Display Mode Alarm Display User Level

Figure 4-27 UTILITIES MENU

4.7.1 COM PORT

This is the COM port used to send and receive data from the Repeater MPC. An interface cable connects the Repeater to the computer (see Figure 4-29). This screen also selects the data baud rate.

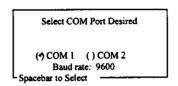


Figure 4-28 COM PORT SELECTION

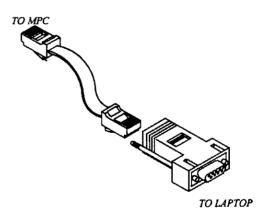


Figure 4-29 LAPTOP INTERCONNECT CABLE

4.7.2 DISPLAY MODE

This screen allows the color mode to be selected for color monitors. When using a laptop, monochrome is recommended for better resolution.

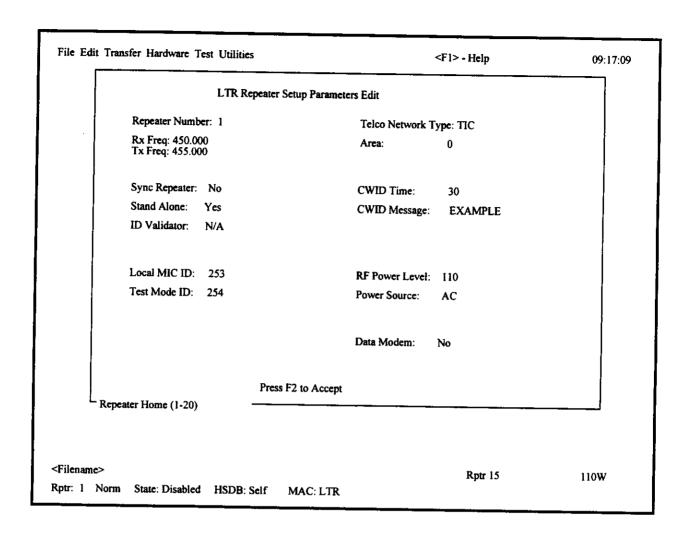


Figure 5-1 SETUP PARAMETERS

PULL DOWN MENUS

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January 1997 Part No. 001-2004-200

SECTION 6 CIRCUIT DESCRIPTION

6.1 RECEIVER

6.1.1 INTRODUCTION

The receiver is a double conversion type with intermediate frequencies of 52.95 MHz and 450 kHz. The first injection frequency is phase locked to a temperature compensated crystal oscillator (TCXO) with a frequency stability of ± 1.0 PPM from -30° to +60°C (-22° to +140°F). Two 3-pole bandpass filters in the front-end reject signals outside the receive band. Two 4-pole crystal filters and two 4-pole ceramic filter establish receiver selectivity (see block diagram Figure 6-1).

6.1.2 REGULATED VOLTAGE SUPPLIES

The +15V DC power source is supplied by the repeater power supply. The +15V supply enters the receiver on J201, pin 1. U302 provides the +12V DC receive voltage to the RF and IF amplifiers. U303 supplies +12V DC to the first and second injection amplifiers. U304 supplies +12V DC to the remaining RF circuits. U301 supplies +6V DC to the remaining circuits.

6.1.3 HELICAL FILTERS, RF AMPLIFIER

The receive signal enters the receiver on coaxial connector A201. A helical filter consisting of L102, L103 and L104 is a three-pole bandpass filter tuned to pass only a narrow band of frequencies within the 380-520 MHz band. This filter also attenuates the image and other unwanted frequencies.

Impedance matching between the helical filter and RF amplifier Q101 is provided by C103, L106, and C104. Q101 amplifies the receive signal to recover filter losses and increases receiver sensitivity. Biasing for Q101 is provided by R102/Q102/R107/R108 and C112 provides RF bypass. Additional filtering of the receive signal is provided by 3-pole helical filter L108-L110. L107/C113/C114 match the output from Q101 to 3-pole helical filter L108-L110.

6.1.4 12.5 kHz IF

First Mixer and Crystal Filter

First mixer U101 mixes the receive frequency with the first injection frequency to produce the 52.95 MHz first IF. Since high-side injection is used, the injection frequency is 52.95 MHz above the receive frequency. Jumper J203 selects between a 12.5 kHz IF and a 25 kHz IF. Install jumper plug P203 on J203, pins 2-3 to select the 12.5 kHz IF. The output of U101 is matched to Z211 at 52.95 MHz by L211, C236 and C237.

Z211A and Z211B form a two-section, four-pole filter with a center frequency of 52.95 MHz and a -3 dB bandwidth of 8 kHz. This filter attenuates adjacent channels and other signals close to the receive frequency. The filter sections are a matched pair and the dot on the case indicates which leads connect together. Matching with Q202 is provided by C241, L213 and C240.

IF Amplifier, Crystal Filter

Q202 amplifies the 52.95 MHz IF signal to recover filter and mixer losses and improve receiver sensitivity. Biasing for Q202 is provided by R236/R233/R234/R235 and C242/C243/C246 provide RF bypass. The output of Q202 is matched to crystal filter Z212 at 52.95 MHz by C245, C247 and L214.

Z212A and Z212B form a two-section, four-pole filter with a center frequency of 52.95 MHz and a -3 dB bandwidth of 8 kHz. This filter establishes the selectivity of the receiver by further filtering the 52.95 MHz IF. The filter sections are a matched pair and the dot on the case indicates which leads connect together. Matching with U203 is provided by C250, C251, C252, L216 and R237.

Table 5-1 REPEATER SETUP PARAMETERS

Parameter	Response	Description
Repeater Number	1-20	Each repeater is assigned a Home Repeater number from 1-20
Channel Frequency	Rx:	Each repeater is programmed with the transmit and receive
	Tx:	frequency that it is operating on.
Telco Network Type	None	Data signaling type for RNT, FSK, RS232 or FSK B&B.
	FSK	None=LTR dispatch only.
	RS232	TIC is for Telephone Interface Card w/o RNT.
	FSK Blank & Burst	VNC=network telephone interconnect w/o RNT.
	TIC	
	VNC	
Area	0, 1	Same as value of the Area bit in the mobiles.
Sync Repeater	No	Not used.
Stand Alone	Yes, No	Select if the repeater is not connected to additional repeaters
		(via HSDB).
ID Validator	Yes, No	Not used.
CWID Time	0 = disabled	Time between CWID transmissions.
	1-60 min	
CWID Message	15 characters/numbers	Station call letters.
G 1g.	UPPER CASE	
Local MIC ID	0 = disabled (default)	Group ID transmitted when the local microphone PTT is
	1-250, 253	active.
Test Mode ID	0 = disabled	Group ID transmitted when the Repeater is in the Test Mode
	1-250,	
	254 (default)	
RF Power Level	25-110	Power level in watts for transmit power.
Power Source	AC or DC	The type of primary power source for the Repeater.
Data Modem	Yes, No	Select if the Data Modem option is installed.

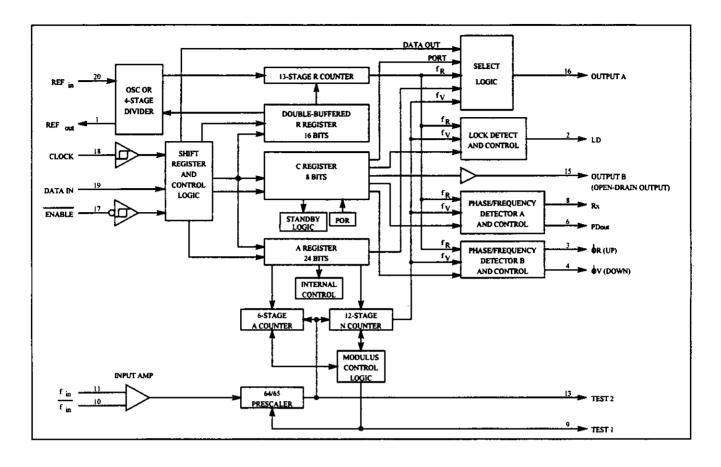


Figure 6-4 SYNTHESIZER BLOCK DIAGRAM

6.1.8 BUFFER

A cascode amplifier formed by Q410/Q411 provides amplification and isolation between the VCO and Synthesizer. A cascode amplifier is used because it provides high gain, high isolation and consumes only a small amount of power. The input signal to this amplifier is coupled from the VCO RF output on pin 5. DC blocking and coupling to the VCO is provided by C455 and to the buffer by C456. Bias for the amplifier is provided by R442, R445, R446 and R277. Q411 is a common-emitter amplifier and Q410 is a common-base with C458 and C457 providing RF bypass. L405 provides some filtering of the cascode output. R448 lowers the Q of L405. The output of the amplifier is coupled by C442/C441 to U401, pin 11.

6.1.9 SYNTHESIZER

The inputs/outputs of synthesizer U401 are shown in Figure 6-4. The output signal from the synthesizer loop is the receiver first injection frequency. This signal is produced by a VCO (voltage-controller oscillator). The frequency of this oscillator is controlled by a DC voltage. This DC voltage is generated by integrating the pulses from the phase detector in synthesizer chip U401.

Frequencies are selected by programming counters in U401 to divide by a certain number. This programming is provided through J201, pins 12, 18 and 20. The frequency stability of the synthesizer is established by the ± 1.0 PPM stability of TCXO Y401. The output of this oscillator is stable from -30°C to +60°C (-22°F to +140°F).

REPEATER PROGRAMMING

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and C227 bypasses other frequencies. The output signal is adjusted by R220 and fed to J205, pin 1. Install jumper plug P205 on J205, pins 1-2 to select the 25 kHz audio to be routed to J201, pin 6.

RSSI Amplifier

U201, pin 13 is an output from an internal RSSI (receive signal strength indicator) circuit which provides a current proportional to the strength of the 450 U202A and the level is adjusted by R219. The DC output signal is then fed to J204, pin 1. Install jumper plug P204 on J201, pins 1-2 to select the 25 kHz RSSI to be routed to J201, pin 7.

6.1.6 VCO (A006)

The Voltage-Controlled Oscillator (VCO) is formed by Q802 circuitry and a resonator consisting of Z801. The VCO oscillates in a frequency range from 433-572 MHz. Biasing of Q802 is provided by R805, R806, R807 and R808. AC voltage divider tion and matches Q802 to the tank circuit. The ceramic resonator is grounded at one end to provide shunt inductance to the tank circuit.

The VCO frequency is controlled in part by DC voltage across varactor diode CR802. As voltage across a reverse-biased varactor diode increases, its increases as the control voltage increases. The control line is RF isolated from tank circuit by choke L802. The amount of frequency change produced by CR802 is controlled by series capacitor C804.

6.1.7 ACTIVE FILTER

Q801 functions as a capacitance multiplier to provide filtering of the 12V supply to Q802. R803 and R804 provide transistor bias, and C812 provides the capacitance that is effectively multiplied by the gain of Q801. If a noise pulse or other voltage change appears on the collector, the base voltage does not change because of C812. Therefore, the base current change because of C812. Therefore, the base current change because of C812. Therefore, the base current stant. R805 decouples the VCO output from AC ground. L803 is an RF choke and C810, C811, C813 and C814 provide RF bypass.

Second Mixer/Detector

As shown in Figure 6-2, U201 contains second oscillator, second mixer, limiter, detector and RSSI circuitry. The 52.95 MHz IF signal is mixed with a 52.5 MHz signal produced by TCXO Y401, tripler Q204 and amplifier Q203. The 17.5 MHz (±1 PPM) output of Y401 is fed through C275 to tripler Q204. The tripler passes the third harmonic at 52.5 MHz to amplifier Q203. Amplifier Q203 amplifies the 52.5 MHz to amplifier Q203.

Biasing of Q204 is provided by R258, R259 and R260. RF choke L222 blocks the flow of RF through R261. An AC voltage divider formed by C280/C281 L224 form a high pass filter to attenuate frequencies below 52.95 MHz. C283 and C284 match the output of the filter to U203. The third harmonic of the filter to U203. The third harmonic of the provided by R254, R255, R256 and R257. The amplifier Q203 fired 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed to U201 OSC B input fied 52.5 MHz output is passed for U201 OSC B input fied 52.5 MHz output is passed for U201 OSC B input fied 52.5 MHz output is passed for U201 OSC B input fied 52.5 MHz output is passed for U201 OSC B input fied 52.5 MHz output fied 52.5 MHz out

The 450 kHz second IF is then fed to ceramic filter Z203/Z204, then into the IF amplifier. The center frequency of Z203/Z204 is 450 kHz with a bandwidth of 15 kHz used to attenuate wideband noise. The limiter amplifies the 450 kHz signal 92 dB which removes any amplitude fluctuations.

From the limiter the signal is fed to the quadrature detector. An external phase-shift network connected to U201, pin 8, shifts the phase of one of the detector inputs 90° at 450 kHz (the other inputs are unshifted in phase). When modulation occurs, the frequency of the IF signal changes at an audio rate as does the phase of the shifted signal. The detector, that has no output with a 90° phase shift, converts the phase shift into an audio signal. Z205 is adjusted to provide maximum undistorted output from the detector, that provide maximum undistorted output from the detector.

Widehand Audio Amplifier

U202B amplifies the detected audio and data signal. R212/R213/R214 set the gain of the amplifier and R215/R215/R217/R218 and R7202 provide a DC reference level. C226 bypasses the 450 kHz IF signal

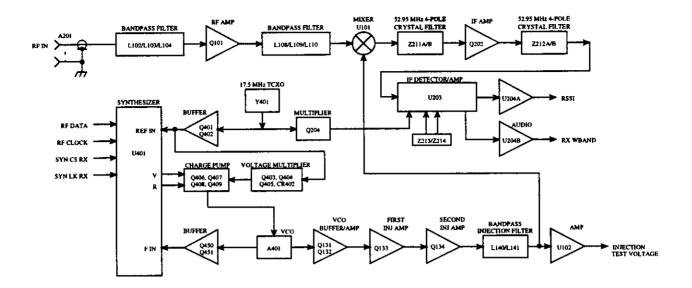


Figure 6-1 12.5 kHz IF RECEIVER BLOCK DIAGRAM

Second Mixer/Detector

As shown in Figure 6-2, U203 contains second oscillator, second mixer, limiter, detector and RSSI circuitry. The 52.95 MHz IF signal is mixed with a 52.5 MHz signal produced by TCXO Y401 and tripler Q204. The 17.5 MHz (±1 PPM) output of Y401 is fed through C275 to tripler Q204. The tripler passes the third harmonic at 52.5 MHz to the oscillator input of U203.

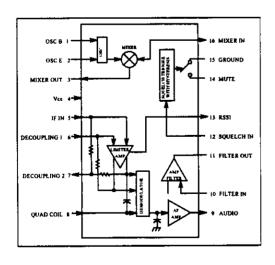
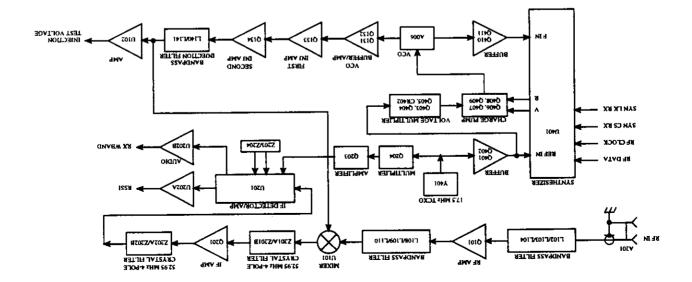


Figure 6-2 U201/U203 BLOCK DIAGRAM

Biasing of Q204 is provided by R258, R259 and R260. RF choke L222 blocks the flow of RF through R261. An AC voltage divider formed by C280/C281 matches Q204 to the highpass filter. The third harmonic of the TCXO frequency is then used to drive the OSC B input at 52.5 MHz. L223, C282 and L224 form a high pass filter to attenuate frequencies below 52.95 MHz. C283 and C284 match the output of the filter to U203.

The 450 kHz second IF is then fed to ceramic filter Z213/Z214, then into the IF amplifier. The center frequency of Z213/Z214 is 450 kHz with a bandwidth of 9 kHz used to attenuate wideband noise. The limiter amplifies the 450 kHz signal 92 dB which removes any amplitude fluctuations.

From the limiter the signal is fed to the quadrature detector. An external phase-shift network connected to U203, pin 8, shifts the phase of one of the detector inputs 90° at 450 kHz (the other inputs are unshifted in phase). When modulation occurs, the frequency of the IF signal changes at an audio rate as does the phase of the shifted signal. The detector, which has no output with a 90° phase shift, converts the phase shift into an audio signal. Z215 is adjusted to provide maximum undistorted output from the detector. The audio signal is then fed out on U203, pin 9.



Ligure 6-3 25 kHz IF RECEIVER BLOCK DIAGRAM

IF and a 25 kHz IF. Install jumper plug P203 on 1203, pins 1-2 to select the 25 kHz IF. The output of U101 is matched to the crystal filter at 52.95 MHz by L201, C201 and C202.

X201A/B form a two-section, four-pole filter with a center frequency of 52.95 MHz and a -3 dB bandwidth of 15 kHz. This filter attenuates adjacent channels and other signals close to the receive frequency. The filter is a matched pair and the dot on the case indicates which leads connect together. Matching with Q201 is provided by C205, L203 and C206.

IF Amplifier, Crystal Filter

Q201 amplifies the 52.95 MHz IF signal to recover filter and mixer losses and improve receiver sensitivity. Biasing for Q201 is provided by R204/R201/R202/R203 and C207/C209/C211 provide RF bypass. The output of Q201 is matched to crystal filter Z202A at 52.95 MHz by C210, C212 and L204.

X202A/B form a two-section, four-pole filter with a center frequency of 52.95 MHz and a -3 dB bandwidth of 15 kHz. This filter establishes the selectivity of the receiver by further filtering the and the dot on the case indicates which leads connect together. Matching with U201 is provided by C215, C216, C217, L206 and R205.

Wideband Audio Amplifier

U204B amplifies the detected audio and data signal. R244/R245/R246 set the gain of the amplifier and R247/R248/R249/R250/R7204 provide a DC reference level. C261 bypasses the 450 kHz IF signal and C262 bypasses other frequencies. The output signal is adjusted by R253 and fed to J205, pin 3. Install jumper plug P205 on J205, pins 2-3 to select the 12.5 kHz audio to be routed to J201, pin 9.

RSSI Amplifier

U203, pin 13 is an output from an internal RSSI (receive signal strength indicator) circuit which provides a current proportional to the strength of the 450 kHz IF signal. The RSSI output is buffered through U204A and the level is adjusted by R221. The DC output signal is then fed to J204, pin 3. Install jumper plug P204 on J204, pins 2-3 to select the 12.5 kHz RSSI to be routed to J201, pin 7.

6.1.5 25 kHz IF

First mixer U101 mixes the receive frequency with the first linjection frequency to produce the 52.95 MHz first IF. Since high-side injection is used, the injection frequency is 52.95 MHz above the receive frequency. Jumper 1203 selects between a 12.5 kHz

The VCO frequency of A401 is controlled by a DC voltage produced by integrating the phase detector output pulses of U401. The phase detector senses the phase and frequency of the two input signals (f_V and f_R) and causes the VCO control voltage to increase or decrease if they are not the same. When the frequencies are the same the VCO is "locked" on frequency.

One input signal to the phase detector in U401 is the reference frequency (f_R). This is the 17.5 MHz TCXO frequency divided by the R (reference) counter to the channel spacing or 6.25 kHz.

The other input to the phase detector in U401 is from the VCO frequency divided down by the "N" counter and prescaler in synthesizer U401 to 6.25 kHz. The "N" counter is programmed through the synthesizer data line on J201, pin 20. U401 is programmed so that the phase detector input (f_V) is identical to the reference frequency (f_R) (6.25 kHz) when the VCO is locked on the correct frequency.

The synthesizer contains the R (reference), N, and A counters, phase and lock detectors and counter programming circuitry. Frequencies are selected by programming the three counters in U401 to divide by assigned numbers. The programming of these counters is performed by circuitry in the Main Processor Card (MPC), which is buffered and latched through the Interface Alarm Card (IAC) and fed into the synthesizer on J201, pin 20 to Data input port U401, pin 19.

Data is loaded into U401 serially on the Data input port U401, pin 19. Data is clocked into the shift registers a bit at a time by a low to high transition on the Clock input port U401, pin 18. The Clock pulses come from the MPC via the IAC to J201, pin 18.

As previously stated, the counter divide numbers are chosen so that when the VCO is operating on the correct frequency, the VCO-derived input to the phase detector (fv) is the same frequency as the TCXO-derived input (fR) which is 6.25 kHz.

The f $_R$ input is produced by dividing the 17.5 MHz TCXO frequency by 2800. This division is done by the "R" counter in U401. The counter always divides by 2800 regardless of the channel frequency. This produces a reference frequency (f_R) of

6.25 kHz. Since the VCO is on frequency (receive frequency plus 52.95 MHz) and no multiplication is used, the channel frequencies change in 6.25 kHz steps and the reference frequency (f_R) is 6.25 kHz for all frequencies selected by this receiver.

The fv input is produced by dividing the VCO frequency using the prescaler and N counter in U401. The prescaler divides by 64 or 65. The divide number of the prescaler is controlled by the N and A counters in U401.

The N and A counters function as follows: both the N and A counters begin counting down from their programmed number. When the A counter reaches zero, it halts until the N counter reaches zero. Both counters then reset and the cycle repeats. The A counter is always programmed with a smaller number than the N counter. While the A counter is counting down, the prescaler divides by 65. Then when the A counter is halted, the prescaler divides by 64.

Example:

Assume a receive frequency of 450.025 MHz. Since the VCO is 52.95 MHz above the receive frequency it must be 502.975 MHz. To produce this frequency, the N and A counters are programmed as follows:

N = 1257 A = 28

NOTE: Section 8.2.5 describes how the N and A counter numbers can be calculated for other channels.

To determine the overall divide number of the prescaler and N counter, the number of VCO output pulses required to produce one N counter output pulse can be counted. In this example, the prescaler divides by 65 for 65 x 28 or 1,820 input pulses. It then divides by 64 for $64 \times (1257 - 28)$ or 78,656 input pulses. The overall divide number K is therefore (78,656 + 1,820) or 80,476. The VCO frequency of 502.975 MHz divided by 80,476 equals 6.25 kHz which is the fx input to the phase detector. The overall divide number K can also be determined by the following formula: K = 64N + A

Where,

N = N counter divide number and A = A counter divide number.

6.1.10 BUFFER AMPLIFIER

A cascode amplifier formed by Q401 and Q402 provides amplification and also isolation between the TCXO and Synthesizer U401. A cascode amplifier is used because it provides high reverse isolation. The input signal to this amplifier is from TCXO Y401. C405 provides DC blocking. Bias for the amplifier is provided by R404, R406, R407, R408 and R409. L401 is an RF choke. RF bypass is provided by C403, C401 and C407. The output of Q401/Q402 is coupled to U401 by C432.

6.1.11 LOCK DETECT

When the synthesizer is locked on frequency, the Lock Detect output on U401, pin 2 is a logic high voltage with very narrow negative-going pulses. Then when the synthesizer is unlocked, these pulses become much wider, the width may vary at a rate determined by the frequency difference of f_V and f_R . The lock detect pulses are applied to J401, pin 14 and sent to the RF Interface on J103, pin 14 for detection and sampling in the IAC.

6.1.12 CHARGE PUMP, LOOP FILTER

The charge pump circuit charges and discharges C450, C451 and C452 in the loop filter to provide the 21V VCO control voltage (see Section 6.1.13). Pulses which control the charge pump are fed out of U401, pins 3/4. When both phase detector inputs are in phase, these output signals are high except for a very short period when both pulse low in phase. If the frequency of the fx input to the phase detector is higher than that of the fv input (or if the phase of f_R leads f_V), the VCO frequency is too low. The negative-going pulses on the fv output (pin 4) then become much wider and the fx output (pin 3) stays essentially high. If the frequency of the f_V input is greater than f_R (VCO frequency too high), the opposite occurs.

Q406 and Q407 are drivers which make the 5V levels and polarity of U401 phase detector outputs compatible with the high voltage supply to Q408 and Q409. Capacitors C444 and C446 momentarily bypass R432 and R437 when negative-going pulses occur. This speeds up the turn-off time of Q406 and Q407 by minimizing the effect of the base charge.

When a negative-going pulse occurs on pin 4, Q406 turns on which turns on Q408. Q408 sources current to charge up the loop filter capacitors C450/

C451, thereby increasing the VCO control line voltage. When a negative-going pulse occurs on pin 3, Q407 turns on which turns on Q409. Q409 sinks current to discharge the loop filter capacitors C450/C451 thereby decreasing the VCO control line voltage. The source current from Q408, when it is on, equals the sink current from Q409, when it is on.

6.1.13 VOLTAGE MULTIPLIER

The 17.5 MHz from Y401 is amplified by Q401/Q402 and passed to the reference input of synthesizer U401, pin 20. This signal is also coupled from the output of Q401/Q402 through C408 to amplifier Q403. Biasing for Q403 is provided by R410, R411 and R412. The output of Q403 is direct coupled to switching transistors Q404/Q405.

When Q405 is turned on and Q404 if off, C409 is grounded on the side connected to the emitter of Q405. This allows the other side of C409 to charge from the 12V supply through R414, CR402 to C409. When Q404 turns on and Q405 is off, C414 charges up to approximately 12V plus the voltage that was stored across C809 from the last cycle. The output voltage is 21V due to voltage loss in the transistor and diodes. C413 is an RF bypass and C414 charges to 21V to stabilize the voltage. The 21V output is filtered by C415/L403/C416 to remove the 17.5 MHz ripple. The 21V output is applied to the charge pump Q408/Q409 and the VCO control line.

6.1.14 BUFFER AMPLIFIER (Q131, Q132)

A cascode amplifier formed by Q131 and Q132 provides amplification and also isolation between the VCO and Receiver RF stages. A cascode amplifier is used because it provides high reverse isolation. The input signal to this amplifier is coupled from VCO A401 by C131. C131 also provides DC blocking. Bias for the amplifier is provided by R134, R133, R138, R132, R131 and R136. L131 is an RF choke and R135 sets the RF output impedance of the cascode. RF bypass is provided by C143, C142, C141, C140, C139, C138, C133, C134, C135 and C136. The output of Q131/Q132 is matched to the Receiver RF stages by a section of microstrip, C144, signal pad R139/R140/R141, C145, C146 and L133. C145 couples the signal to the input of the first injection amplifier.

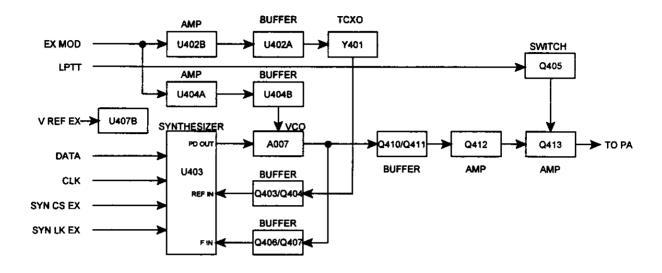


Figure 6-5 EXCITER BLOCK DIAGRAM

With reference to the ground on the Exciter, the 3.5V reference stability is maintained by U126B/C/D on the MAC. The 3.5V DC passes through summing amplifier U129B and transmit modulation gate U118D to P100, pin 29 (Tx MOD). P100, pin 29 is connected to backplane connector J2, pin 8 and RFIB connector J101, pin 22 to J102, pin 13. The transmit modulation and 3.5V reference enter the Exciter on J401, pin 13 and are routed to U402B, pin 6. R425 sets the TCXO modulation level. The modulation signal and the 3.5V DC are applied to U402A, pin 2.

6.2.4 BUFFER

A cascode amplifier formed by Q406/Q407 provides amplification and also isolation between the VCO and synthesizer. A cascode amplifier is used because it provides high reverse isolation. The input signal to this amplifier is tapped from the VCO RF output. DC blocking to the VCO is provided by C441 and to the buffer by C433. Bias for the amplifier is provided by R451, R453, R454 and R455. Q407 is a common-emitter amplifier and Q406 is a common-base with C432 providing RF bypass. L403 decouples the output from AC ground and R452 lowers the Q of L403. The amplifier is coupled by C429 to U403, pin 11.

6.2.5 SYNTHESIZER

The inputs/outputs of synthesizer U403 are shown in Figure 6-4. The synthesizer output signal is the transmit frequency. This signal is produced by a VCO (voltage-controller oscillator) that is frequency controlled by a DC voltage produced by synthesizer chip U403. This DC voltage is filtered by a loop filter made up of C805, C806 and R804 in the VCO circuitry.

Frequencies are selected by programming counters in U403 to divide by a certain number. This programming is provided through J401, pins 12, 19 and 20. The frequency stability of the synthesizer is established by the ±1.0 PPM stability of TCXO Y401. This oscillator is stable from -30°C to +60°C (-22°F to +140°F).

The VCO frequency of A007 is controlled by a DC voltage produced by the phase detector in U403. The phase detector senses the phase and frequency of the two input signals and causes the VCO control voltage to increase or decrease if they are not the same. When the frequencies are the same, the VCO is then "locked" on frequency.

6.1.10 BUFFER AMPLIFIER

A cascode amplifier formed by Q401 and Q402 provides amplification and also isolation between the TCXO and Synthesizer U401. A cascode amplifier is used because it provides high reverse isolation. The input signal to this amplifier is from TCXO Y401. C405 provides DC blocking. Bias for the amplifier is provided by R404, R406, R407, R408 and R409. L401 is an RF choke. RF bypass is provided by C403, C401 and C407. The output of Q401/Q402 is coupled to U401 by C432.

6.1.11 LOCK DETECT

When the synthesizer is locked on frequency, the Lock Detect output on U401, pin 2 is a logic high voltage with very narrow negative-going pulses. Then when the synthesizer is unlocked, these pulses become much wider, the width may vary at a rate determined by the frequency difference of f_V and f_R . The lock detect pulses are applied to J401, pin 14 and sent to the RF Interface on J103, pin 14 for detection and sampling in the IAC.

6.1.12 CHARGE PUMP, LOOP FILTER

The charge pump circuit charges and discharges C450, C451 and C452 in the loop filter to provide the 21V VCO control voltage (see Section 6.1.13). Pulses which control the charge pump are fed out of U401, pins 3/4. When both phase detector inputs are in phase, these output signals are high except for a very short period when both pulse low in phase. If the frequency of the fx input to the phase detector is higher than that of the fv input (or if the phase of f_R leads f_V), the VCO frequency is too low. The negative-going pulses on the fv output (pin 4) then become much wider and the fx output (pin 3) stays essentially high. If the frequency of the f_V input is greater than f_R (VCO frequency too high), the opposite occurs.

Q406 and Q407 are drivers which make the 5V levels and polarity of U401 phase detector outputs compatible with the high voltage supply to Q408 and Q409. Capacitors C444 and C446 momentarily bypass R432 and R437 when negative-going pulses occur. This speeds up the turn-off time of Q406 and Q407 by minimizing the effect of the base charge.

When a negative-going pulse occurs on pin 4, Q406 turns on which turns on Q408. Q408 sources current to charge up the loop filter capacitors C450/

C451, thereby increasing the VCO control line voltage. When a negative-going pulse occurs on pin 3, Q407 turns on which turns on Q409. Q409 sinks current to discharge the loop filter capacitors C450/C451 thereby decreasing the VCO control line voltage. The source current from Q408, when it is on, equals the sink current from Q409, when it is on.

6.1.13 VOLTAGE MULTIPLIER

The 17.5 MHz from Y401 is amplified by Q401/Q402 and passed to the reference input of synthesizer U401, pin 20. This signal is also coupled from the output of Q401/Q402 through C408 to amplifier Q403. Biasing for Q403 is provided by R410, R411 and R412. The output of Q403 is direct coupled to switching transistors Q404/Q405.

When Q405 is turned on and Q404 if off, C409 is grounded on the side connected to the emitter of Q405. This allows the other side of C409 to charge from the 12V supply through R414, CR402 to C409. When Q404 turns on and Q405 is off, C414 charges up to approximately 12V plus the voltage that was stored across C809 from the last cycle. The output voltage is 21V due to voltage loss in the transistor and diodes. C413 is an RF bypass and C414 charges to 21V to stabilize the voltage. The 21V output is filtered by C415/L403/C416 to remove the 17.5 MHz ripple. The 21V output is applied to the charge pump Q408/Q409 and the VCO control line.

6.1.14 BUFFER AMPLIFIER (Q131, Q132)

A cascode amplifier formed by Q131 and Q132 provides amplification and also isolation between the VCO and Receiver RF stages. A cascode amplifier is used because it provides high reverse isolation. The input signal to this amplifier is coupled from VCO A401 by C131. C131 also provides DC blocking. Bias for the amplifier is provided by R134, R133, R138, R132, R131 and R136. L131 is an RF choke and R135 sets the RF output impedance of the cascode. RF bypass is provided by C143, C142, C141, C140, C139, C138, C133, C134, C135 and C136. The output of Q131/Q132 is matched to the Receiver RF stages by a section of microstrip, C144, signal pad R139/R140/R141, C145, C146 and L133. C145 couples the signal to the input of the first injection amplifier.

6.1.15 FIRST AND SECOND INJECTION AMPLIFIERS (Q133, Q134)

U303 provides the +12V source for these amplifiers. First injection amplifier Q133 is biased by CR131, R143, R144, R145 and R146. C148, C151, C149 and C150 provide RF bypass from the DC line. L134 on the collector is an RF choke. Q133 is matched to the 50 ohm signal pad R147, R148 and R149 by lowpass filter C152/L135/C153, C154. C155, L136, L156, L137, C157 and a section of microstrip match Q134 to the 50 ohm signal pad.

Second injection amplifier/buffer Q134 is similar in design to Q133. The output of Q134 is matched to 50 ohms by L134/C162/C163 and C164 provides DC blocking. L140/L141 are tuned to the receive frequency plus 52.95 MHz and passed to Mixer U101. This injection frequency is also coupled through C165 to the injection test voltage circuit U102A. CR133, R158, R159 provide DC input to U102A, pin 3. The output of U102A, pin 1 is connected to J201, pin 13 for a receive injection test point and to the RF Interface Board on J103, pin 13.

6.2 EXCITER

6.2.1 VCO (A007)

The Voltage-Controlled Oscillator (VCO) is formed by Q802, associated circuitry and a resonator consisting of Z801. The VCO oscillates in a 40 MHz frequency band somewhere between 380-520 MHz depending on the model of the repeater. Biasing of Q802 is provided by R805, R806 and R807. An AC voltage divider formed by C807 and C808 initiates and maintains oscillation. C806 couples Q802 to resonator Z801. Resonator Z801 provides the shunt inductance of the tank circuit. The shunt capacitance of the tank circuit is made primarily of C803/C804 in series with CR801/CR802. RF choke L804 completes the DC bias path to ground.

The VCO frequency is controlled in part by DC voltage across varactor diode CR802. As voltage across a reverse-biased varactor diode increases, its capacitance decreases. Therefore, VCO frequency increases as the control voltage increases. The control line is RF isolated from tank circuit by choke L802. The amount of frequency change produced by CR802 is controlled by series capacitor C804.

The frequency is modulated in a similar manner. The transmit audio/data signal is applied across varactor diode CR803 to vary the VCO frequency at an audio rate. C815/C816 in series with CR803 determine the amount of modulation produced by the audio signal.

6.2.2 ACTIVE FILTER

Q801 functions as a capacitance multiplier to provide filtering of the 12V supply to Q802. R803 and R804 provide transistor bias, and C812 provides capacitance that is effectively multiplied by the gain of Q801. If a noise pulse or other quick voltage change appears on the collector, base voltage does not change significantly because of C812. Therefore, the base current does not change and transistor current remains constant. R805 decouples the VCO output from AC ground. L803 is an RF choke and C810, C811, C813, C814 and C809 provide RF bypass.

6.2.3 VCO/TCXO FREQUENCY MODULATION

Both the VCO and TCXO are modulated in order to achieve the required frequency response. If only the VCO was modulated, the phase detector in U403 would sense the frequency change and increase or decrease the VCO control voltage to counteract the change (at the lower audio frequencies inside the closed loop bandwidth of the synthesizer). If only the TCXO frequency was modulated, the VCO would not track the higher audio frequencies (those beyond the closed loop bandwidth of the synthesizer). However, by modulating both the VCO and TCXO a flat audio response is achieved. Potentiometers R425 and R446 balance the modulating signals.

There are two 3.5V sources on the Exciter board; one is a reference for the modulation amplifier to the VCO, the other is for the modulation amplifier to the TCXO.

The reference voltage on U402B, pin 5 is also on buffer U407B, pin 5 to J401, pin 9 and RFIB connector J102, pin 9. The voltage leaves the RFIB on J101, pin 14 to J2, pin 27 on the backplane, to the bottom connectors via pin 7 and finally to the MAC on P100, pin 7.

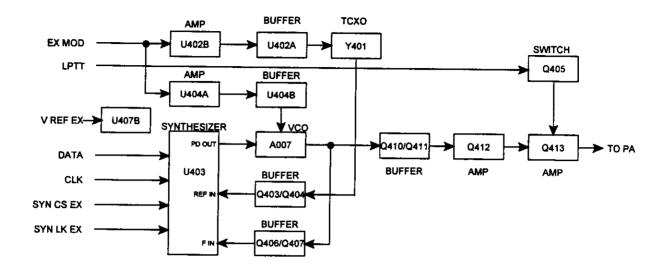


Figure 6-5 EXCITER BLOCK DIAGRAM

With reference to the ground on the Exciter, the 3.5V reference stability is maintained by U126B/C/D on the MAC. The 3.5V DC passes through summing amplifier U129B and transmit modulation gate U118D to P100, pin 29 (Tx MOD). P100, pin 29 is connected to backplane connector J2, pin 8 and RFIB connector J101, pin 22 to J102, pin 13. The transmit modulation and 3.5V reference enter the Exciter on J401, pin 13 and are routed to U402B, pin 6. R425 sets the TCXO modulation level. The modulation signal and the 3.5V DC are applied to U402A, pin 2.

6.2.4 BUFFER

A cascode amplifier formed by Q406/Q407 provides amplification and also isolation between the VCO and synthesizer. A cascode amplifier is used because it provides high reverse isolation. The input signal to this amplifier is tapped from the VCO RF output. DC blocking to the VCO is provided by C441 and to the buffer by C433. Bias for the amplifier is provided by R451, R453, R454 and R455. Q407 is a common-emitter amplifier and Q406 is a common-base with C432 providing RF bypass. L403 decouples the output from AC ground and R452 lowers the Q of L403. The amplifier is coupled by C429 to U403, pin 11.

6.2.5 SYNTHESIZER

The inputs/outputs of synthesizer U403 are shown in Figure 6-4. The synthesizer output signal is the transmit frequency. This signal is produced by a VCO (voltage-controller oscillator) that is frequency controlled by a DC voltage produced by synthesizer chip U403. This DC voltage is filtered by a loop filter made up of C805, C806 and R804 in the VCO circuitry.

Frequencies are selected by programming counters in U403 to divide by a certain number. This programming is provided through J401, pins 12, 19 and 20. The frequency stability of the synthesizer is established by the ± 1.0 PPM stability of TCXO Y401. This oscillator is stable from -30°C to +60°C (-22°F to +140°F).

The VCO frequency of A007 is controlled by a DC voltage produced by the phase detector in U403. The phase detector senses the phase and frequency of the two input signals and causes the VCO control voltage to increase or decrease if they are not the same. When the frequencies are the same, the VCO is then "locked" on frequency.

The synthesizer contains the R (reference), N, and A counters, phase and lock detectors and counter programming circuitry.

One input signal to the phase detector in U403 is the reference frequency (fr). This frequency is the 17.5 MHz TCXO frequency divided by the reference counter to the channel spacing or 6.25 kHz. The other input signal (fv) is the VCO frequency divided by the "N" counter in U403. The counters are programmed through the synthesizer data line on J401, pin 20. Each channel is programmed by a divide number so that the phase detector input is identical to the reference frequency (fr) when the VCO is locked on the correct frequency.

Frequencies are selected by programming the three counters in U403 to divide by assigned numbers. The programming of these counters is performed by circuitry in the Main Processor Card (MPC), buffered and latched through the Interface Alarm Card (IAC) and fed into the synthesizer on J401, pin 20 to Data input port U403, pin 19.

Data is loaded into U403 serially on the Data input port U403, pin 19 when U403, pin 17 is low. Data is clocked into the shift registers a bit at a time by a low to high transition on the Clock input port U403, pin 18. The Clock pulses come from the MPC via the IAC to J401, pin 19.

As previously stated, the counter divide numbers are chosen so that when the VCO is operating on the correct frequency, the VCO-derived input to the phase detector (fv) is the same frequency as the TCXO-derived input (fR). The fR input is produced by dividing the 17.5 MHz TCXO frequency by 2800. This produces a reference frequency (fR) of 6.25 kHz. Since the VCO is on frequency and no multiplication is used, the frequencies are changed in 12.5 kHz steps. The reference frequency is 12.5 kHz for all frequencies selected by this Exciter.

The fv input is produced by dividing the VCO frequency using the prescaler and N counter in U403. The prescaler divides by 64 or 65. The divide number of the prescaler is controlled by the N and A counters in U403. The N and A counters function as follows:

Both the N and A counters begin counting down from their programmed number. When the A counter reaches zero, it halts until the N counter reaches

in U403. The N and A counters function as follows:

Both the N and A counters begin counting down

zero. Both counters then reset and the cycle repeats. The A counter is always programmed with a smaller number than the N counter. While the A counter is counting down, the prescaler divides by 65. Then when the A counter is halted, the prescaler divides by 64.

Example: To illustrate the operation of these counters, assume a transmit frequency of 450.250 MHz. Since the VCO is the channel frequency for transmit this frequency is used. To produce this frequency, the N and A counters are programmed as follows:

N = 1125 A = 40

To determine the overall divide number of the prescaler and N counter, the number of VCO output pulses required to produce one N counter output pulse can be counted. In this example, the prescaler divides by 65 for 65 x 40 or 2,600 input pulses. It then divides by 64 for 64 x (425 - 40) or 69,440 input pulses. The overall divide number K is therefore (69,440 + 2,600) or 72,040. The VCO frequency of 450.250 MHz divided by 72,040 equals 6.25 kHz which is the fx input to the phase detector. The overall divide number K can also be determined by the following formula:

K = 64N + A

Where.

N = N counter divide number and A = A counter divide number.

NOTE: Section 8.2.5 describes how the N and A counter numbers can be calculated for other channels.

6.2.6 BUFFER AMPLIFIER (Q403, Q404)

A cascode amplifier formed by Q403 and Q404 provides amplification and isolation between the TCXO and Synthesizer U403. A cascode amplifier is used because it provides high gain, high reverse isolation and consumes only a small amount of power. The input signal to this amplifier is coupled from TCXO Y401, pin 5 by C420. C420 also provides DC blocking. Bias for the amplifier is provided by R430, R431, R432, R433 and R428. L402 is an RF choke. RF bypass is provided by C416, C418 and C419. The output of Q403/Q404 is coupled to U403, pin 20 by C417.

6.2.7 BUFFER AMPLIFIER (Q406, Q407)

A cascode amplifier formed by Q406 and Q407 provides amplification and also isolation between the VCO and Synthesizer U403. A cascode amplifier is used because it provides high gain, high isolation and consumes only a small amount of power. The input signal to this amplifier is coupled from VCO A007, pin 6 by C433. C433 also provides DC blocking. Bias for the amplifier is provided by R450, R451, R453, R454 and R455. L403 is an RF choke. RF bypass is provided by C430, C431 and C479. The output of Q406/Q407 is coupled to U403, pin 11 by a non-polarized capacitor formed by C429/C499.

6.2.8 LOCK DETECT

When the synthesizer is locked on frequency, the Lock Detect output on U403, pin 2 is a high voltage with narrow negative-going pulses. When the synthesizer is unlocked, the negative-going pulses are much wider, the width may vary at a rate determined by the frequency difference of fv and fx.

The locked or unlocked condition of the synthesizer is filtered by R440/C423 and applied to J401, pin 16, then sent to the RF Interface on J102, pin 16 for detection.

6.2.9 BUFFER AMPLIFIER (Q410, Q411)

A cascode amplifier formed by Q410/Q411 provides amplification and also isolation between the VCO and exciter RF stages. A cascode amplifier is used because it provides high gain, high isolation and consumes only a small amount of power. The input signal to this amplifier is tapped from VCO A007, pin 4 by C441. C441 also provides DC blocking. Bias for the amplifier is provided by R464, R465, R466, R467 and R468. L406 is an RF choke and R483 lowers the Q of the coil. RF bypass is provided by C434, C442, C445, C443, C444 and C480. The output of Q410/Q411 is matched to the Exciter RF stages by a section of microstrip, C446, signal pad R459/R460/R461, C498, C450 and L408.

6.2.10 RF AMPLIFIERS (Q412, Q413)

RF amplifier Q412 is biased by CR402, R469, R470, R471 and R472. C448 provides RF bypass from the DC line. L409 is an RF choke to the supply

line. Q412 is matched to the 50 ohm signal pad by low pass filter C449/L410/C451, C503 and signal pad R473/R474/R475.

RF amplifier/buffer Q413 is similar in design to Q412. The collector voltage of Q413 is switched by Q405. When the Logic Push-To-Talk (LPTT) on J401, pin 11 is low Q405 turns on and conducts the 15V supply to the collector of Q405 and to Q413. The output of Q413 is matched to 50 ohms by C509, L412, C510, and C465 provides DC blocking. A 3 dB attenuator R490/R491/R492 follows amplifier Q413. The RF output of the Exciter is on coaxial connector J402 to the Power Amplifier.

6.3 110W POWER AMPLIFIER

6.3.1 AMPLIFIER/PREDRIVER (U501)

RF input to the PA from the Exciter is through a coaxial cable and connector to WO511. C501 couples the RF to signal pad R501/R502/R503 that connects the input to U501. U501 is a 6W amplifier/pre-driver operating in the 380-520 MHz range.

Power control is connected to WO505 from the RF Interface board (RFIB). RF is filtered from the control voltage line by various capacitors to U501, pin 2. This control voltage regulates the RF output of the amplifier on U501, pin 5 to approximately 5W.

6.3.2 DRIVER (Q501)

The output of U501 passes through several sections of 50 ohm microstrip and matching capacitors to the gate of Q501. Driver Q501 is a MOSFET amplifier with a normal output of approximately 22W. Supply voltage is RF bypassed by various capacitors. L501, C541, C542 and microstrip match the output of the driver to 35 ohms. The RF is applied to the input of the splitter and to the finals.

6.3.3 FINAL AMPLIFIERS (Q502, Q503)

Q502 and Q503 are combined 60W amplifiers. The 22W RF input from the driver Q501 is applied to a 70.7 ohm Wilkinson splitter and then to the gate of each MOSFET amplifier. The 60W outputs on the drain of the amplifiers are combined using a Wilkinson combiner. Q502 has a half-wave transmission

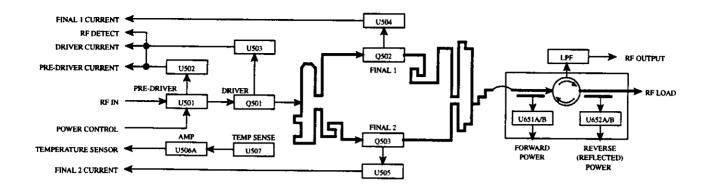


Figure 6-6 110W POWER AMPLIFIER BLOCK DIAGRAM

line on the input and Q503 has a half-wave on the output. These T-lines are used to drive the 60W amplifiers out of phase. The output of the combiner is fed from WO513 directly to the forward/reverse power detect board.

The Wilkinson splitter and combiner provide the capability to split the drive input and combine the final outputs while maintaining isolation between the two final amplifiers. The combiner consists of two quarter-wave transmission lines and a balancing resistor. During normal operation, a signal of relatively equal phase and amplitude is present on both ends of the balancing resistor. Therefore, no current flows and no power is dissipated in the balance resistor. If one final failed, the other final of a pair would continue to function.

6.3.4 POWER DETECTORS (U503, U504, U505)

The supply current is monitored through a resistor that creates a current output level indicative of the power output. The outputs of U503, U504 and U505 are monitored by the repeater software through the RF Interface Board. If a final amplifier fails, the software will reduce the output power to prevent over-driving the remaining final amplifier.

6.3.5 THERMAL SENSOR (U507)

Thermal protection is provided by temperature sensor U507. The operating range of the sensor is from -30° C to 100° C (-22° F to 212° F). Amplifier

U506A sends the output of U507 through WO509 to the RF Interface Board. The RF Interface Board reduces the power amplifier to half power (via the MPC) if the temperature reading is too high and turns the fan on and off (not via the MPC). The fan is turned on at approximately 50°C and off again at 42°C.

6.3.6 FORWARD/REVERSE POWER DETECT, CIRCULATOR, LOW-PASS FILTER

The power amplifier output is directly coupled to the forward/reverse power detect board via a jumper. The output then enters the circulator and exits to the low-pass filter board and the antenna jack for a minimum power output of 110W at the default setting. If an antenna is not connected, the circulator connects the output power to R685.

Forward and reverse power are electromagnetically coupled from the input and reflected ports of the circulator. R663/R680 calibrate the forward and reverse sense levels. The sensed levels are coupled to the RF Interface Board and software.

6.4 RF INTERFACE BOARD

The RF Interface Board (RFIB) connects the Receiver, Exciter and Power Amplifier to the backplane and power supply (see Figure 6-7).

The input and output connectors for the RF Interface Board are defined as follows.

6.4.1 POWER CONNECTOR

The power supply is connected to the RF Interface Board when the RF module is inserted into the station cabinet (see Figure 10-3). The jack portion of the connection is on the RF Interface Board, the plug portion is attached to the station cabinet.

P101/P102 +26.5V DC - Supply voltage to PA. $\pm 26V \pm 1\%$, 20A at 110W.

P103 +15V DC - Supply voltage to Exciter, Receiver and Power Control. 15V ±1%, 5.5A max.

P104/P105 GROUND - Ground return for the RF assembly.

6.4.2 SIGNAL CONNECTOR (J101)

This is the signal interface connector (36 pin) that connects the RFIB to the backplane connector J2 (34 pin) through cable assembly A8.

Pin 1 GROUND

Pin 1 carries ground current between the RF Interface board and Backplane board.

Pin 2 PC STR

Pin 2 is the power Control Strobe. This is normally low until after the power control data is shifted into the power control register. Then the strobe line goes high and back to low. The clock or data lines cannot be changed until after the strobe is set.

Pin 3 HS CS EX

Pin 3 is not used at this time.

Pin 4 GROUND

Pin 4 carries ground current between the RF Interface board and Backplane board.

Pins 5-6 UNUSED

Pin 7 RX WBAND

The wide band audio is from the receive audio demodulator U202 and goes to the MAC in the Controller card cage. The typical amplitude is

387 mV RMS (-6 dBm) and 2V DC with Standard TIA Test Modulation into the receiver. Little wave shaping is done on the receiver board other than a 31 kHz RC LPF which strips off the 450 kHz IF. Buffering is done with an op-amp.

Pin 8 RF DATA A

Data A (U105, pin 11) is the least significant bit (LSB) in the 3 multiplex chips located on the RFIB. This pin is a CMOS input from the Controller requiring a logic high for activation.

Pin 9 RF DATA C

Data C (U105, pin 9) is the most significant bit (MSB) in the 3 multiplex chips located on the RFIB. This pin is a CMOS input from the Controller requiring a logic high for activation.

Pin 10 RF MUX2 INH

The Multiplexer-2 Inhibit (U106, pin 6) is a CMOS input from the Controller that inhibits (disables) the output from the RF 2 Multiplexer with a logic high.

Pin 11 RF CLK

The clock will control the synthesizer chip and power control circuit when loading. This pin is a TTL input from the Controller.

Pin 12 HS CS RX

Pin 12 is not used at this time.

Pin 13 RF MUX1 INH

The Multiplexer-1 Inhibit (U105, pin 6) is a CMOS input from the Controller that inhibits (disables) the output from the RF 1 Multiplexer with a logic high.

Pin 14 V REF EX

This is the 3.5V reference to the Exciter TCXO. 3.5V from the Exciter is passed from J102, pin 9 to this pin and the backplane. The voltage then passes through the MAC and back to the backplane to J101, pin 22 with the TX MOD. These are connected to J102, pin 13 back to the Exciter.

Pins 15-18 UNUSED

Pin 19 RF MUX3 INH

The Multiplexer-3 Inhibit (U104, pin 6) is a CMOS input from the Controller that inhibits (disables) the output from the RF 3 Multiplexer with a logic high.

Pin 20 LPTT

The Logic Push-To-Talk is an open collector from the Controller. It has a sink capability of 20 mA and a maximum voltage rating of 18V. The transmitter should produce power when this pin is a logic low.

Pin 21 SYN CS EX

This input goes low to enable the loading of data into the exciter synthesizer chip U403.

Pin 22 TX MOD

The audio from the MAC in the Controller processes a number of inputs to the station to produce the signals on this pin. This signal goes through the RFIB and then to the Exciter. A 707 mV RMS sine wave (2V P-P) at 1 kHz produces 60% of system deviation in the transmitter. The source impedance is low and the input impedance is less than 10k ohms.

Pin 23 GROUND

Pin 23 carries ground current between the RFIB and Chassis Backplane.

Pin 24 UNUSED

Pin 25 LOGIC CONTROL TO FANS

Pin 25 is in parallel with the temperature sensor.

Pin 26 RF DATA B

The Data B (U105, pin 10) is the middle significant bit in the three multiplex chips located on the RFIB. This pin is a CMOS input from the Controller requiring a logic high for activation.

Pin 27 A D LEVEL

20 lines (of the possible 24) of RF functions sampled are multiplexed to the Controller through this pin using three multiplex chips.

- 1. RF Forward Power Sense
- 2. RF Power Sense Device 1
- 3. RF Power Sense Device 2
- 4. RF Power Sense Device 3
- 5. RF Power Sense Device 4
- 6. RF Reflected Power Sense
- 7. PA Temperature
- 8. Transmit Audio Modulation
- 9. High Stability Exciter Lock Detector
- 10. Exciter Lock Detector
- 11. Receiver Detector Audio
- 12. Receive Signal Strength Indicator
- 13. Receiver Injection Level
- 14. High Stability Receive Lock Detector
- 15. Receiver Lock Detector
- 16. Fan Current 1
- 17. Fan Current 2
- 18. Fan 1 On Sense
- 19. Power Supply Temp
- 20. Battery Voltage

Pin 28 RF DATA

A data pin with TTL levels from the Controller which has the dual role of loading the synthesizer chips and adjusting the power control D/A lines for proper output power. Up to four synthesizer chips and a shift-register could be connected to this pin.

Pin 29 SYN CS RX

This input goes low to enable the loading of data into the receiver synthesizer chip U401.

Pin 30 RSSI

This pin is the Receive Signal Strength Indication to the Controller. This RSSI is used for tune-up of the Receiver front-end during factory test mode. The dynamic range is 60 dB. It has an output from an opamp with the voltage going from 0.5V to 4.5V. The level has an adjustment in the Receiver.

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Pin 31 GROUND

Pin 31 carries ground current between the RFIB and Chassis Backplane.

Pins 32-36 UNUSED

6.4.3 FAN CONNECTOR (J104)

The outputs to the fan connectors are 4-pin plugin terminals that supply DC voltage. The plug on the fan is a 2-pin connector. The plug-in terminals are located on the back of the RFIB.

Pin 1 FAN 1 LOW

Pin 1 is the ground return for Fan 1.

Pin 2 FAN HI

Pin 2 carries the voltage to Fan 1. The current is 1/4A nominal at 20V to 30V. This pin goes high when the PA heat sensor rises above 50°C and goes low below 45°C.

Pin 3 FAN2 LO

Pin 3 is the ground return for Fan 2.

Pin 4 FAN HI

Pin 4 carries the voltage to Fan 2. The Voltage is 20V-30V at 1/4A nominal. Pin 4 goes high when the PA heat sensor rises above 50°C and goes low below 45°C.

6.4.4 POWER AMPLIFIER CONNECTIONS

WO 115 POWER SENSE

This capacitive feedthrough pin is at +15V DC to the Power Detect Board.

WO 116 +26.5V DC

This capacitive feedthrough pin is at +26.5V DC and carries the PA current, 25A nominal at 110W from P102 to the Power Amplifier board.

WO 117 +26.5V DC GROUND

This capacitive feedthrough pin carries ground current from P105 to the Power Amplifier board. It must be capable of carrying up to 25A.

W118 +15V DC

This capacitive feedthrough pin connects +15V DC P103 to the PA, Exciter, and Forward/Reverse Power Detect boards. Maximum current handling is 6A (4A nominal at 110W).

WO 119 NOT USED

WO 120 CTRL OUT

This capacitive feedthrough pin carries the output of the power control driver on the RFIB to the power control pin of the power module on the Power Amplifier board. The voltage varies from 0V-15V with current as high as 0.5A.

WO 121 FWD PWR

This capacitive feedthrough pin is the forward power sense line. It is a voltage source that is a function of the output power of the Power Amplifier. The voltage level will be between 0V-5V and drive a 10k ohm load. A typical voltage of 3V correlates to 110W out of the PA. This line goes through the multiplexers and A D LEVEL line to the Controller for processing.

WO 122 RF OUT 1

This capacitive feedthrough pin is a voltage source that is a function of the output power of U501. The voltage level will be between 0V-5V and drives a 10k ohm load. This line goes through the multiplexers and A D LEVEL line to the Controller for processing.

WO 123 RF OUT 2

This capacitive feedthrough pin is a voltage source that is a function of the output power of Q501. The voltage level will be between 0V-5V and drive a 10k ohm load. This line goes through the multiplexers and A D LEVEL line to the Controller for processing.

WO 124 RF OUT 3

This capacitive feedthrough pin is a voltage source that is a function of the output power of Q502. The voltage level will be between 0V-5V and drive a 10k ohm load. This line goes through the multiplexers and A D LEVEL line to the Controller for processing.

WO 125 RF OUT 4

This capacitive feedthrough pin is a voltage source that is a function of the output power of Q503. The voltage level will be between 0V-5V and drive a 10k ohm load. This line goes through the multiplexers and A D LEVEL line to the Controller for processing.

WO 126 REFL PWR

This capacitive feedthrough pin is the reflected power sense line. It is a voltage indicative of the power reflected due to a mismatch. The voltage produced will typically be such that less than a 3:1 VSWR will not trigger alarms and when VSWR = 6:1 the controller will reduce power. The voltage level will be between 0V-5V and drive a 10k ohm load. This line goes through the multiplexers and A D LEVEL line to the Controller for processing. The time to sense and reduce the power takes several seconds.

WO 127 TEMP

This capacitive feedthrough pin is the temperature sense line of the Power Amplifier. It will be a linearly variable function of temperature ranging from 0V-5V output and 0°C to +100°C (+32°F to 212°F) input when driving a 10k ohm load. The primary functions of this line are for fan on/off and PA power reduction. The fan should be turned on at 50°C and off at 45°C. The PA should have power reduced when 90°C (194°F) is reached and with absolute turn-off at 95°C (203°F). This line goes through the multiplexers and A D LEVEL line to the Controller for processing.

WO147 RF DETECT DRIVER

This senses power out of the driver. It is used to limit the power out of the driver to 0.4 dB over 110W at room temperature.

WO143 +26V DC

This is the +26.5V DC source to the RFIB from P101.

WO144 +15V DC

This is the +15V DC source to the RFIB from P103.

WO145 GROUND

W145 carries ground current from P104 to the RFIB.

6.4.5 EXCITER CONNECTOR (J102)

The connector from the Exciter (J401) to the RF Interface board (J102) links the Exciter to the MPC in the Controller Backplane.

Pin 1 VCC1

The voltage on this pin is a fused +15V \pm 1%, nominal current of 0.5A. It provides current to the Exciter from the RFIB.

Pins 2-8 GROUND

Pin 9 +3.5V DC

Pin 9 is the +3.5V DC TCXO reference voltage from the Exciter to the MAC.

Pin 10 GROUND

Pin 11 LPTT

The Logic Push-To-Talk (LPTT) is an open collector from the Controller. It has a sink capability of 20 mA nominal and a voltage rating of 18V maximum. The transmitter should produce power when this pin is a logic low.

Pin 12 SYN CS EX

Pin 12 is the Exciter synthesizer chip select. It allows data input to the synthesizer chip when the line is pulled to a logic low.

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Pin 13 TX MOD

The audio from the MAC in the Controller processes a number of inputs to the station per the TIA specifications to produce the signal on this pin. This signal goes through the RFIB to the Exciter. A 707 mV RMS (2V P-P) sine wave at 1 kHz provides 60% of system deviation in the transmitter. The DC voltage on the line is $3.5V \pm 0.1V$. The source impedance should be low (output of an op-amp or analog switch < 200 ohms) and the input impedance will not be less than 10k ohms.

Pins 14-15 GROUND

These pins carry ground current between the RFIB and the Exciter board.

Pin 16 SYN LK EX

Pin 16 is the Exciter synthesizer lock detector output. The synthesizer is locked with a TTL logic high state.

Pin 17 HS LK EX

Pin 17 is not used at this time.

Pin 18 HS CS EX

This input is not used at this time.

Pin 19 RF CLK

The clock controls the Exciter synthesizer when loading. The input source in the Controller is TTL with the speed determined by the synthesizer chip. There could be as many as four synthesizers and a shift register.

Pin 20 RF DATA

Pin 20 is a data pin from the Controller which has the dual role of loading the synthesizer chip and adjusting the power control D/A lines for proper output power. The data has TTL levels. Up to four synthesizer chips and a shift register could be connected to this pin.

6.4.6 RECEIVER CONNECTOR (J103)

The connector from the Receiver (J201) to the RF Interface board (J103) links the Receiver to the MPC in the Controller Backplane.

Pin 1 VCC1

Pin 1 is fused $+15V \pm 1\%$ with a nominal current of 1A provides current from the RFIB to the Receiver.

Pins 2-6 UNUSED

Pin 7 RSSI

This pin is the Receive Signal Strength Indicator (RSSI) to the Controller. The RSSI is used for tune-up of the Receiver front-end during test mode. The dynamic range is 60 dB. Output is from an op-amp with the voltage going from 0.5V to 4.5V. The level has an adjustment in the Receiver (see Section 6.1.4 or 6.1.5).

Pin 8 UNUSED

Pin 9 RX WBAND

The receive wide band audio is from the demodulator and goes to the Main Audio Card (MAC) in the Controller card cage. The typical amplitude is 387 mV RMS (-6 dBm) and 2V DC with Standard TIA Test Modulation into the Receiver. Little wave shaping is done on the Receiver board other than a 31 kHz RC LPF which strips off the 450 kHz IF. Buffering is done with an op-amp which can drive a 10k ohm load.

Pin 10 UNUSED

Pin 11 GROUND

Pin 11 carries ground current between the RFIB and the Receiver board.

Pin 12 SYN CS RX

Pin 12 is the Receiver synthesizer chip select. This chip is the same part as used in the Exciter. A low enables loading the Synthesizer.

CIRCUIT DESCRIPTION

Pin 13 RX INJ

This pin is the power sense for the Receiver injection. It is a linear voltage source that is a function of the injection power. The voltage level will be between 0V - 5V and be able to drive a 10k ohm load.

Pin 14 SYN LK RX

Pin 14 is the main synthesizer lock detector output for the Receiver. The synthesizer is locked with a TTL logic high state.

Pin 15 GROUND

Pin 15 carries ground current between the RFIB and the Receiver board.

Pin 16 HS CS RX

Pin 16 is not used at this time.

Pin 17 GROUND

Pin 17 carries ground current between the RFIB and the Receiver board.

Pin 18 RF CLK

The clock controls the Receiver synthesizers when loading. The input source in the Controller is TTL with the speed determined by the synthesizer chip.

Pin 19 HS LK RX

Pin 19 is not used at this time.

Pin 20 RF DATA

Pin 20 is a data pin from the Controller which has the dual role of loading the synthesizer chips and adjusting the power control D/A lines for proper output power. The data has TTL levels. Up to four synthesizer chips and a shift register could be connected to this pin.

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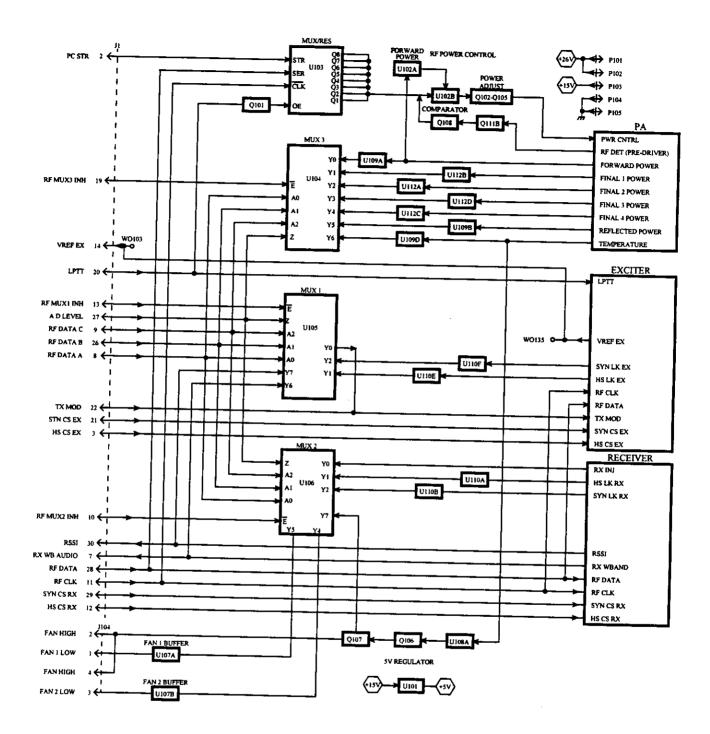


Figure 6-7 RF INTERFACE BOARD BLOCK DIAGRAM

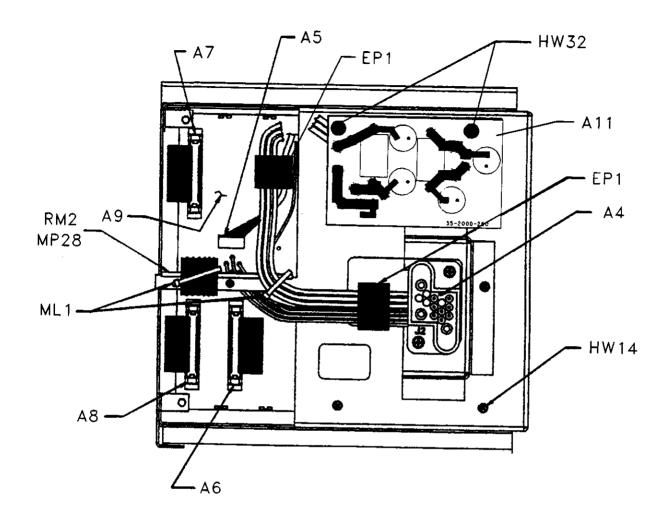


Figure 6-8 BACKPLANE CONNECTORS

6.5 CARD RACK

The card rack provides slots for up to eight logic cards; including Main Processor Card (MPC), Main Audio Card (MAC) and the Interface Alarm Card (IAC). The IAC has a notch in the card to accommodate a pin in Slot-8 so that no other card can be plugged into this slot.

On the back of the card rack is the Backplane with plug-in connectors to the cards and cables to the RF modules, Power Supply and External Connector Board.

Refer to the component layout and schematic diagram in Section 10 for more information on the repeater backplane.

6.6 EXTERNAL CONNECTOR BOARD

The external connector board (A10) is the interface for the alarm outputs, connecting repeaters through the high speed data bus.

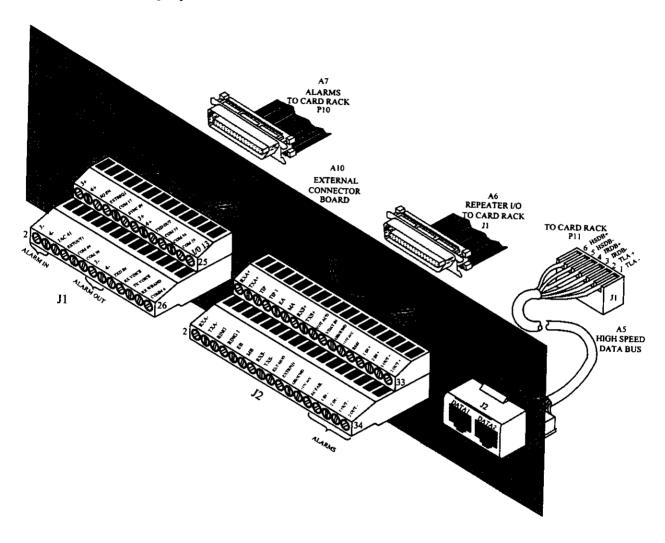


Figure 6-9 EXTERNAL CONNECTOR BOARD

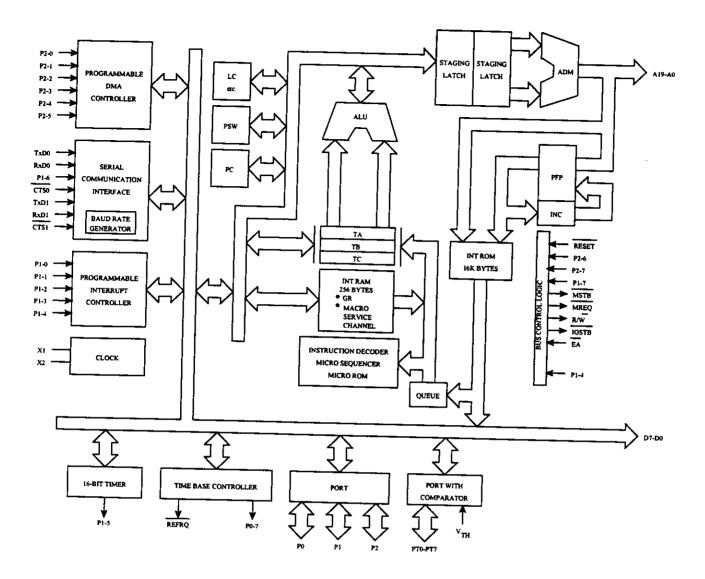


Figure 6-10 U27 BLOCK DIAGRAM

6.7 MAIN PROCESSOR CARD

6.7.1 INTRODUCTION

The Main Processor Card (MPC) connects to the computer with repeater software to program the repeater parameters, sets and reads the alarms, handles communication between repeaters, maintains the audio gating for the MAC, handles initialization requests from cards and contains the repeater RF data for the Receiver, Exciter and CWID.

Control functions for each repeater are performed by the Main Processor in the MPC installed in each repeater. The MPC contains the main software and control over the repeater via microprocessor U27 (see Figure 6-11).

Information is exchanged between repeaters via a High-Speed Data Bus (HSDB) that interconnects all the MPCs. This control technique is called distributive processing and it eliminates the need for a separate system controller at each site. The HSDB processor (U13) on the MPC provides these control functions. The MPC also contains:

- 1. Flash Memory, RAM, non-volatile EEPROM.
- I/O chip select to allow the addressing of data latches for Input/Output.
- Read/Write selection to be sent and received on the Controller Backplane.
- Clock line, data line and chip select line from the IAC to load the Receiver and Exciter synthesizers.
- Serial communication circuitry and processes for the High Speed Data Bus (HSDB).
- 6. Asynchronous parallel communication to the other cards, i.e. alarm input and output circuitry.
- 7. AC Power Failure indication from the IAC.
- Provides an output from the IAC to the power amplifier to control the output power.
- 9. Exciter Logic Push-To-Talk (PTT).
- 10. Receiver synthesizer lock, Exciter synthesizer lock, thermal level from the power amplifier, VSWR level from the PA, forward power level, RSSI signal level, audio levels from the MAC, Receiver and Exciter from the IAC.

6.7.2 MAIN CONTROLLER MICROPROCESSOR

U27 contains the main software and control over the repeater (see Figure 6-10).

The main controller (U27) is a VLSI (Very Large Scale Integration) CMOS 16-bit single chip computer with an 8-bit external data bus. This processor has software compatibility with the V20 (8086/8088), faster memory access, superior interrupt processing ability, and enhanced control of internal peripherals. This ROMless processor has a variety of on-chip components including 256 bytes of RAM, serial and parallel inputs/outputs, comparator port lines and timers.

Eight banks of registers are mapped into internal RAM below an additional 256-byte special function register (SFR) area that is used to control on-chip peripherals. Internal RAM and the SFR area are together and can be relocated anywhere in the 1M-byte address space. This maintains compatibility with existing system memory maps.

The two microprocessors and USART (U22) are reset by integrated circuit U17. Reset occurs when power is turned on, when the 5V supply drops below a threshold level or the reset switch (S1) is active.

When a microprocessor is reset, several internal registers are cleared and the program is started over from the beginning. Low-voltage reset prevents improper operation resulting from low-voltage conditions.

When power is turned on, the RESET output U17, pin 6 is initially high and the inverted RESET output U17, pin 5 is initially low. Once the 5V supply stabilizes, these outputs remain in these states for approximately 100 ms to ensure that reset occurs.

This time delay is set by capacitor C14 connected to U17, pin 3. If the 5V supply drops below a nominal level, the RESET outputs change states and microprocessor operation is interrupted until the 5V supply returns to normal. C3 prevents fast transients on the 5V supply from causing reset.

Manual reset can be accomplished by pressing push-button switch S1. When U17, pin 2 goes low, U17 goes into the reset sequence described.

6.7.3 HIGH SPEED DATA BUS MICROPROCES-SOR (U13)

The HSDB processor (U13) on the MPC provides the interface with the HSDB. It monitors data on this bus and also transmits data on to this bus when necessary. Information on this bus indicates which repeaters are in use and also which mobiles are using the system. This information is used by the repeater to encode data messages to the mobiles that are monitoring that channel. These messages also include information on which repeater is free and current system priority.

Microprocessor U13 is an 8052 that uses external EPROM (Erasable Programmable Read Only Memory) U14, an 8-bit device that stores the program. The microprocessor uses 2k x 8 EPROM and 64k x 8 RAM. The RAM (Random Access Memory) is used for temporary data storage. The HSDB processor is configured by the Main Processor.

The internal data bus of the microprocessor has four input/output ports. These ports have eight lines each, giving a total of 32 input/output lines. These ports are designated P0, P1, P2, P3. P0 is used as a data bus. Ports P1 and P2 are always used as general purpose inputs/outputs. P3 is used for specialized functions, i.e. a serial port (RxD/TxD) and interrupt (INT).

The operating speed of the microprocessor is set by an 11.059 MHz clock generated by Y2. This clock frequency is divided down by an internal divider to provide a machine cycle time of 1.08 μ s. Most program instructions are executed in one machine cycle and none require more than four machine cycles.

The microprocessor U13 communicates with the main processor (U27) through U9 and U10. U9 is a Transmit FIFO (First In First Out) and U10 is a Receive FIFO. This combination makes up an asynchronous parallel-to-parallel interface to the Main Processor.

Microprocessor U13 also calculates the current system priority for the channel. This priority is from the programming software responses and the current priority is sent to the main processor. U13 also reads repeater number and channel number information in memory. U13 also determines the current free repeater and includes that information in the data sent to the Main Processor.

6.7.4 CHIP SELECT DECODERS (U15/U4)

Chip select decoders select the peripheral chip to read from or write to.

6.7.5 P1 SIGNAL CONNECTOR

This is the signal interface connector P1 (64 pin) that connects the Address and Data buses and control lines to the backplane connector.

Pins 1-10 ADDRESS BUS Pins 33-42

This provides a path between the MPC main processor and the external memory on the MPC and the other cards in the Controller. This bus retrieves information programmed into memory for the operation of the repeater.

Pins 11-14 DATA BUS Pins 43-46

The data bus provides a means of transferring data to and from the CPU on the MPC, memory storage on each card and peripheral devices in and out of the MAC and IAC.

Pin 15 MREQ

MREQ is a memory request line operates in conjunction with the Read/Write lines. These provide the ability to read from or write to the main processor memory on the MPC.

Pin 16 MSTB

MSTB is a memory strobe line used during MPC main processor Read/Write operations to external memory on the MPC and other cards plugged into the backplane.

Pins 17-20 UNUSED

Pin 21 LPTT

The Logic Push-To-Talk is an open collector from the Controller. It has a sink capability of 20 mA and a maximum voltage rating of 18V. The transmitter should produce power when this pin is a logic low. Transmit indicator is on the IAC and is controlled independently of the LPTT.

Pins 22-23 UNUSED

Pins 24/56 HSDB+/HSDB-

This interconnects all repeaters to provide an exchange of information. This control technique is called distributive processing and eliminates a separate system controller at each site. Information on this bus indicates which repeaters are in use and also which mobiles are using the system. This information is used by the repeater to encode data messages to the mobiles that are monitoring that channel. These messages also include information on which repeater is free and current system priority.

Pins 25-26 UNUSED

Pins 27/59 -5V IN

This is the -5V input to the MPC from the power supply via the Controller backplane.

Pins 28-29 +5V IN

Pins 60-61

This is the +5V input to the MPC from the power supply via the Controller backplane.

Pins 30/62 +15V IN

This is the +15V input to the MPC from the power supply via the Controller backplane.

Pins 31-32 GROUND

Pins 63-64

This is the ground connection to the MPC from the power supply via the Controller backplane.

Pin 47 READ

Read is used with the MREQ line to read data from the main processor and external memory.

Pin 48 WRITE

Write is used with the MREQ line to write data to the main processor and external memory.

Pins 49-55 UNUSED

Pins 57-58

6.7.6 J1 COMPUTER CONNECTOR

J1 is the MPC connection to the computer or modem.

Pin 1 Ground

Pin 2 Computer Tx

Pin 3 Computer Rx

Pin 4 Modem DCD

6.7.7 J2 MEMORY SELECT

J2 is jumpered to select either the Flash memory or the EPROM memory. Flash memory is ultra-fast data storage. The normal setting is pin 1 to pin 2.

Pin 1 +12V

Pin 2 U25, pin 1 Vpp

Pin 3 +5V

6.7.8 J3 BAUD RATE

J3 is jumpered to select the baud rate from the computer to the MPC, these two baud rates must be the same (see Figure 6-11). The baud rate of the computer can be found from the command line by requesting /b, /h or /? (see Section 3.1.5). To change jumper J13: Power off the station. Move P3 to the proper rate. Power on the station.

6.7.9 S2/S3 HSDB SETTINGS

These switches configure; the HSDB for RS-485 or single-ended 5V operation, indicate if the Summit repeaters are connected to existing repeaters or only Summit repeaters, and if the repeater is an end repeater termination. Refer to Sections 2.8 and 7.5.8.

6.7.10 J4 EPROM MEMORY LOADING

This jumper selects EPROM memory loading for LTR systems. The LTR setting is pin 3 to pin 4.

6.7.11 J5 HSDB SPEED

J5 is jumpered to select the data bus speed. J5, pins 2/3 select the LTR 12 MHz crystal.

6.7.12 J6 WATCHDOG

This jumper enables or disables the watchdog timer for reset. Normal operating mode is P6 jumpering J6, pins 2/3. This jumper should not be moved or removed.

6.8 MAIN AUDIO CARD

6.8.1 INTRODUCTION

This control card stores the information required to operate the routing of audio and data from the inputs of the repeater to the outputs. Data is received on the address bus from the MPC for the operations to perform. The Audio/Data microprocessor and the latches open and close gates to route a path for the audio or data.

Audio control functions for each repeater are performed by the Main Processor in the MPC. The MPC contains the software and maintains control over the repeater via microprocessor U27. The audio/data microprocessor passes received data to the main processor, and it is given the programmable parameters for the gates.

Information is exchanged between the cards in the Controller Backplane via a data bus and an address bus. The address bus provides the link between the main processor and the chip and the address latches on the MAC. These latches control the octal latches that select the audio and data gates. The data bus is the link between the Main Processor and the Audio/Data Processor on the MAC. The Main Processor controls the data to the octal latches and opens and closes the gates required to route audio/data in and out of the repeater. The MAC also contains:

- 1. The audio interface between the receiver and exciter and to the external connections.
- 2. The receive audio filtering with de-emphasis.
- 3. The squelch filter and detector.
- 4. Slow decay timing circuit that controls a mute gate on the main receive audio.
- A filter, DC restoration and slicer circuitry for detecting the subaudible data.
- 6. The fast squelch and data fed to the microprocessor that decodes the data and uses the squelch line as a data qualification signal.
- 7. Transmit audio filter and limiter with pre-emphasis.

6.8.2 AUDIO/DATA MICROPROCESSOR (U111)

This Audio/Data microprocessor is on the MAC card and is used to decode LTR data received from the mobiles. The LTR data is applied to U111, pin 8 (P1.7 input). When a word is successfully decoded the data is then sent to U161 (Tx FIFO) and transmitted on the data bus in parallel to the main processor on the MPC.

When it is time to transmit the CW Identification, the main processor on the MPC sends the identification to U111 via the data bus and U160 (Rx FIFO). The CWID is sent to the Tx Data Amplifier and Filter. The output of the filter is summed with the transmit audio and sent to the Exciter.

U111 also uses six octal latches to provide additional input and output lines. Latch U107/U108 provide outputs which allow U111 to control various audio gates. These gates control the CWID, FSK data, and receive/transmit audio signals.

Latch U106 provides outputs which allow U111 to route signals to the Audio/Data Test Point by switching gates on and off. U106 also provides adjustment of the selected EEPOTs.

U155-U156 allow U111 to select the EEPOT to adjust with chip select lines. These latches also provide routing of some audio/data signals through gates.

In addition, U111 controls the receive and transmit audio gates, receiver squelch, several front-panel indicators, and other functions. U111 encodes the data messages transmitted to mobiles monitoring that channel, and controls transmitter keying.

6.8.3 RECEIVE AUDIO

The Receive Wide Band Audio (RX WBAND) signal from the Receiver is fed into the MAC on P100, pin 27. This audio signal includes; audio, LTR data, and noise. The audio processing circuit provides filtering and amplification of the audio signal before it is routed to the outputs on the MAC card.

A low-pass filter consisting of U121A/B attenuates frequencies above 3 kHz. This removes high-frequency noise from the audio signal. From the filter

the signal is fed to amplifier U122A to increase the level before the high-pass filter to preserve adequate hum and noise ratio.

From the audio amplifier the signal is fed to a high-pass filter consisting of U122B/C/D. This filter attenuates frequencies below 300 Hz which removes data present in the wide band audio signal. These filters are configured to act like large inductors. The signal is then fed to U163A which provides 6 dB per octave de-emphasis.

Audio gates U113B/C/D permit noise squelch circuit, control logic, and audio switch to control gating of the audio signal. The control signal from the noise squelch circuit is applied to U113B through U113D. When a carrier is detected, this input is high and U113B passes the signal. Programming determines the gating of audio. When audio is passed by U113B/C and U114A, the audio can be routed through other gates to various outputs (see Section 6.8.6).

6.8.4 RECEIVE SQUELCH CIRCUITRY

The receive wide band audio includes audio, data and noise. The squelch circuit detects this noise to determine receive signal strength. When no carrier or a weak carrier is received, there is a large amount of noise present. Conversely, when a strong carrier is present, there is very little noise present.

U135A is a high-pass filter which attenuates frequencies below approximately 30 kHz so that only high-frequency noise is passed. This noise is amplified by U135B and U123A. A level control adjusts the gain of amplifier U135B. The gain of U123A is partially set by a thermistor to compensate for circuit gain and noise level changes caused by temperature variations.

The amplified noise is then applied to a bridge rectifier. The difference between bridge rectifier outputs is applied to the inputs of U123B. The output of U123B is positive-going pulses. These pulses are applied to U123C which is a Schmitt trigger. When the input signal rises above the reference the output goes low and causes the reference voltage to decrease slightly adding hysteresis to the triggering level. This hysteresis prevents intermittent squelching when the receive signal strength is near the threshold level.

The output of U123C is applied to U123D and Logic Squelch to Audio/Data Gate U159B and audio/data processor U111. Gate U159B routes the squelch output to the Audio/Data Test Point J100. U123D functions as a timing buffer. The output of U123D is applied to Receive Squelch Active Gate U113D. When this gate is closed, the squelch circuit controls Normal Receive Gate U113B to block receive audio if no signal is present.

6.8.5 RECEIVE DATA CIRCUITRY

The receive wide band audio signal is the unfiltered output of discriminator U202 in the Receiver. Therefore, this signal contains audio, LTR data, and noise. A low-pass filter formed by U124A/B attenuates frequencies above 150 Hz by 24 dB per octave so that only the data frequencies are passed. From the filter the signal is fed to amplifier U125A. The gain of U125A is adjusted by a level control. The output of U125A can be routed through Data To Audio/Date Gate U159C and the Audio/Data Test Point J100.

DC restoration circuit converts the data signal from AC floating near ground to a digital signal at levels of 0 and 4.5V. U125B/C provide the reference voltage on the inverting input of comparator U125D. Positive peak detector U125B handles the positive-going peaks of the data signal. Negative peak detector U125C handles the negative-going peaks of the data signal.

The voltage on non-inverting input to U125D is midway between the positive- and negative-going peaks. The data input is on the non-inverting input of U125D. When the data signal rises above the reference voltage, the output goes high. Conversely, when the input voltage drops below the reference voltage, the output goes low. The receive data is then passed to audio/data processor U111.

6.8.6 RECEIVE AUDIO PROCESSING

The receive audio signal is fed into the MAC on P100, pin 27. When a mobile-to-mobile call is received, Repeat Gate U153C is enabled and the receive audio signal is routed through Transmit Option Gate U158C to the input of the transmit audio buffer U164B to be retransmitted. Repeat Gate

U153C is controlled by processor U111 through latch U107. A logic 1 on the control input causes the signal to be passed.

When the received audio must be routed to the backplane (i.e. for other cards), Receive Voice Gate U115B is enabled by processor U111/latch U108 and passes the audio signal to amplifier U120B. Receive To Backplane (RX TO BP) U115C is enabled and passes the amplified audio to the backplane.

When the audio received must be routed to the external speaker or speaker/microphone, Local Audio Mute Gate U114D is enabled by U111/latch U108. The audio is passed to local audio output amplifier U132. The gain of U132 is adjusted by the local audio volume control and on/off switch.

6.8.7 VOTER AUDIO

When used, the Receive audio from the voter receiver comes into the MAC on P100, pin 25. Amplifier U120A sets the gain of the signal and the output is routed to Voter Audio Mute Gate U115A. The gate is controlled by A/D processor U111/latch U108. If the gate is enabled, the audio goes to the Receive Mute Gate U113C and passes throughout the MAC Card.

6.8.8 COMPANDOR OPTION

The compandor option enhances the receive and transmit audio when used in conjunction with the Telephone Interface Card (TIC) in LTR systems.

The filtered Receive Audio passes through the Receive Mute Gate U113C to the expander input on A301, pin 1. The expand output of A301, pin 2 is coupled to the audio outputs by U114C.

The TX-VOICE from P100, pin 32, passes through TX Voice Gate U158A to the expander input on A301, pin 5. The compressed output of A301, pin 4 is passed to the TX Audio Buffer.

6.8.9 TRANSMIT AUDIO

PTT switch (Q101/Q102) provides local microphone Push-To-Talk (PTT) indication to U105. U105 then tells U111 via the data bus that the local microphone PTT has been activated.

U164A amplifies the microphone audio signal to provide the correct input level to U164B. Local Microphone Mute Gate U117C is controlled by A/D processor U111/latch 106. The function of U117C is to mute the local microphone audio when the local microphone PTT switch is pressed. This prevents interference if the microphone remains live when the PTT switch is pressed.

Buffer U164B combines the microphone audio signal from U164A with the audio signal from the Repeat Gate U153C.

U127B/C form a high-pass filter that attenuates frequencies below 300 Hz to prevent interference with the LTR data applied at U129B. Pre-emphasis at 6 dB per octave is provided by an RC combination before the signal is fed to the Limiter U127D.

Limiter U127D and rectifiers form a precision limiter which prevents over modulation caused by high-level input signals. With normal input levels, the output of a bridge rectifier follows the input of the bridge. When a high-level signal is applied to the bridge, the bridge opens and the output of the bridge is limited to a specific level.

The output of the limiter passes to a composite 6pole splatter filter formed by U127A, U128D and U128A separated by buffers U128B and U128C.

The output from U128A is fed to Normal Modulation Mute Gate U118B that is controlled by A/D processor U111/latch U106. When enabled, the gate passes transmit audio to EEPOT U149. U149 is an electronically adjustable potentiometer that adjusts the gain of transmit audio amplifier U129C. The gain of U129C can only be adjusted through the software. Therefore, a computer must be attached to the MAC card when levels are set.

The output of U129C is fed to summing amplifier U129B where it is combined with LTR transmit data and CWID when present. The gain of audio and data are the same so unity gain is produced. The output signal is fed to the TCXO where it frequency modulates the transmit signal.

Standard 12V/24V AC control transformer outputs can be accepted as well as DC voltages. This input voltage range is 5-24V RMS. External resistors connected in series may be used to extend the input voltage range.

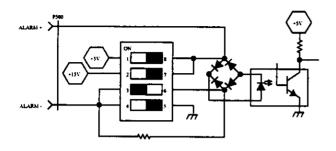


Figure 6-17 S500-S503

6.9.3 ALARM INDICATORS

There are three forms of alarm indicators from the repeater. One form is the two red LEDs and display combination on the MPC. Refer to Table 1-2 for the combinations and definitions of the active alarms.

Another form is the output relay to the terminal blocks at the rear of the repeater where outputs can be wired to external devices or to alarm inputs.

The third form is the output relay and to transmit a 15-character description of the alarm over-the-air to a remote location. The description is sent in Morse code with a transmit ID assigned during programming. A transceiver programmed with this ID can monitor the repeater and alert the system owner when an alarm occurs.

6.9.4 ALARM FUNCTIONS

The alarms can be configured in various modes to alert the system owner to conditions and hazards with the equipment and the repeater site facility. A few of the possibilities are shown in Figure 6-18. In this example the input alarm 2 of Repeater 1 is connected to the door of the building, input alarm 3 of Repeater 5 is connected to the fire alarm system, the AC fail alarm (#16 see Table 1-2) is mapped to alarm 2 output so it can be transmitted (see Figure 4-10) and the output alarm 1 of Repeater 1 is connected to the input alarm 1 of Repeater 2 and so on until the output

alarm 1 is fed back to the input alarm 1 of Repeater 1. Then the RF Shutdown alarm (#32) is mapped for alarm 1 in each repeater. This configuration allows Repeater 2 to give an alarm when Repeater 1 has an RF Shutdown alarm output, etc.

The input alarms are given a 15-character description during programming and a Transmit ID. These are used when an input alarm is activated to send a Morse code message consisting of the description over the air to a monitoring transceiver programmed with this ID.

There are 40 internal alarms that can be included in the output alarm configuration (see Table 1-2). These alarms can also be programmed to send an output as shown in the cross reference screen of the alarm configuration menu (see Figure 4-10). Among these alarms are the thermal sense from the PA and the AC fail alarm output on the terminal block at the rear of the repeater to activate the battery backup.

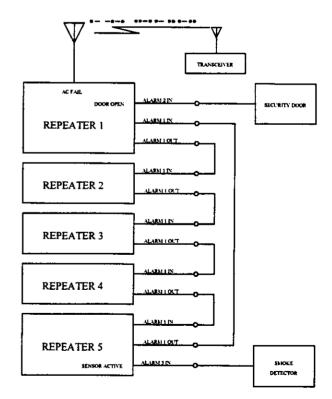


Figure 6-18 ALARM EXAMPLE

6.9.5 P500 SIGNALING CONNECTOR

The input and output connectors for the IAC are defined as follows. The signal interface connector P500 (64 pin) connects the Address and Data buses and control lines to the backplane connector. See Figure 6-14.

Pins 1-4 ADDRESS BUS (A12-A19 Only) Pins 33-36

This address bus provides a path between the MPC main processor and the latches and multiplexers of the IAC. This bus retrieves information programmed into the MPC memory for the operation of the IAC.

Pins 5/37 ALARM 1 IN +/ALARM 1 IN -

This is an input received from a connection to an external device as a specific alert condition.

Pins 6/38 ALARM 2 IN +/ALARM 2 IN -

This is an input received from a connection to an external device as a specific alert condition.

Pins 7/39 ALARM 3 IN +/ALARM 3 IN -

This is an input received from a connection to an external device as a specific condition.

Pins 8/40 ALARM 4 IN +/ALARM 4 IN -

This is an input received from a connection to an external device as a specific alert condition.

Pin 9 SQUELCH ENABLE

This is an output to rear connector J1. It can be configured for inverted output, non-inverted output or logic controlled non-inverted output.

Pin 10 EXTERNAL REO 2

This is an input received from a connection to an external device.

Pins 11-14 DATA BUS Pins 43-46

This data bus provides a means of transferring data to and from the latches and multiplexers on the IAC with peripheral devices in the IAC.

Pin 15 MREQ

A memory request line operates in conjunction with the Read/Write lines. These lines read from or write to the MPC processor memory.

Pins 16/17 UNUSED

Pin 18 SYNC IN

This is an input received from a connection to an external device.

Pins 19/51 ALARM 1 OUT +/ALARM 1 OUT -

This is an output to an external device to perform a specific function.

Pins 20/52 ALARM 2 OUT +/ALARM 2 OUT -

This is an output to an external device to perform a specific function.

Pins 21-23 UNUSED

Pins 24/25 +15V ACCESSORY

This DC supply is an output to an external device through rear connector J1.

Pins 26/58 +15V FILTERED

This DC supply is an output to an external device through rear connector J1.

Pins 27/59 -5V IN

This is the -5V input from the power supply via the Controller backplane.

Pins 28-29 +5V IN Pins 60-61

This is the +5V input to the MPC from the power supply via the Controller backplane.

Pins 30/62 +15V IN

This is the +15V input to the MPC from the power supply via the Controller backplane.

Pins 31-32 GROUND Pins 63-64

This is the ground connection to the MPC from the power supply via the Controller backplane.

Pins 41-42 UNUSED

Pin 47 READ

Read is used with the MREQ line to read data from the MPC processor and external memory.

Pin 48 WRITE

Write is used with the MREQ line to write data to the MPC processor and external memory.

Pins 49-50 UNUSED

Pins 53-55 UNUSED

Pin 56 THERMAL SENSOR

The Thermal Sensor monitors the PA temperature and creates an alarm condition if the temperature exceeds the limit.

Pin 57 POWER SWITCH

Pin 57 turns the voltage from the power supply to the Repeater on and off. This pin is connected to the on/off toggle switch S508.

6.9.6 P501 EXTERNAL OUTPUTS

Connector P501 contains data and control outputs to the terminal block on the back of the Repeater cabinet. These outputs are connected to other external devices.

The input and output connectors for the connector are defined as follows.

Pins 1/17 ALARM 3 OUT +/ALARM 3 OUT -

Pins 2/18 ALARM 4 OUT +/ALARM 4 OUT -

These are outputs to external devices to perform a specific function.

Pin 3 RX WBAND

Receive Wide Band Audio from the Receiver audio demodulator through the RF Interface Board. The typical amplitude is 387 mV RMS (-6 dBm) and 2V DC with Standard TIA Test Modulation into the receiver.

Pins 4-6 UNUSED

Pin 7 EXT OUT 1

This is an external output to rear connector J1.

Pin 8 RF CLOCK

The clock will control the synthesizer chips and power control circuit when loading. This pin is a TTL input from the Controller.

Pin 9 AC FAIL IN

This input from the AC supply is used by the AC fail output to indicate that the AC has been interrupted.

Pin 10 SYN CS RX

This is the chip select pin for the main receiver synthesizer chip. This chip is the same part as used in the Exciter. A low loads the synthesizer.

Pin 11 UNUSED

Pin 12 RF MUX 1 INH

The Multiplexer-1 Inhibit (U105, pin 6) is a CMOS input from the Controller that inhibits (disables) the Multiplexer-1 output with a logic high.

Pin 13 RF MUX 2 INH

The Multiplexer-2 Inhibit (U106, pin 6) is a CMOS input from the Controller that inhibits (disables) the Multiplexer-2 output with a logic high.

Pin 14 RF MUX 3 INH

The Multiplexer-3 Inhibit (U104, pin 6) is a CMOS input from the Controller that inhibits (disables) the output from the RF 3 Multiplexer with a logic high.

Pin 15 PC STR

The Power Control Strobe is normally low until after the power control data is shifted into the power control register. Then the strobe line goes high and back to low. The clock or data lines cannot be changed until after the strobe is set.

Pin 16 HS CS EX

This is the Exciter high stability synthesizer chip select. A low enables loading the high stability synthesizer loop. This pin is only used on high stability equipped units.

Pins 19-21 UNUSED

Pin 22 BUF RX WBAND

This is buffered Receive Wide Band Audio from the receiver audio demodulator through the RF Interface Board. The typical amplitude is 387 mV RMS (-6 dBm) and 5V DC with Standard TIA Test Modulation into the receiver. This is an output to the rear connector J1.

Pin 23 AC FAIL OUT

This is an indication that the AC power has been interrupted.

Pin 24 UNUSED

Pin 25 HS CS RX

This is the receiver high stability synthesizer chip select. A low enables loading the high stability synthesizer loop. This pin is only used on high stability equipped units.

Pin 26 SYN CS EX

Pin 26 is the exciter main Synthesizer Chip Select that allows input of data to U403 when the line is pulled to logic low.

Pin 27 UNUSED

Pin 28 A D LEVEL

20 lines (of the possible 24) of RF functions sampled are multiplexed to the Controller through this pin using three multiplex chips.

Pin 29 RF DATA A

Data A (U105, pin 11) is the least significant bit (LSB) in the 3 multiplex chips located on the RFIB. This pin is a CMOS input from the Controller requiring a logic high for activation.

Pin 30 RF DATA B

Data B (U105, pin 10) is the middle significant bit in the 3 multiplex chips located on the RFIB. This pin is a CMOS input from the Controller requiring a logic high for activation.

Pin 31 RF DATA C

Data C (U105, pin 9) is the most significant bit (MSB) in the 3 multiplex chips located on the RFIB. This pin is a CMOS input from the Controller requiring a logic high for activation.

Pin 32 RF DATA

This is a data pin with TTL levels from the Controller which has the dual role of loading the synthesizer chips and adjusting the power control D/A lines for proper output power. Up to four synthesizer chips and a shift-register could be connected to this pin.

6.9.7 J500 A D LEVEL TEST POINT

20 lines (of the possible 24) of RF functions sampled are multiplexed to the Controller through this pin using three multiplex chips.

6.9.8 J501 GROUND

J501 is an IAC ground reference for test points.

6.9.9 J502 +15V

J502 is a voltage test point.

6.9.10 POWER SWITCH

S508 turns the power supply DC voltage on and off from the front of the IAC.

6.9.11 J505 SQUELCH ENABLE OUTPUT

P505 jumpers J505, pins 1/2 to configure the squelch enable output for an inverted output. P505 jumpers J505, pins 2/3 to configure the squelch enable output for a non-inverted output. P505 jumpers J505, pins 3/4 to configure the squelch enable output for a non-inverted output under the control of U503.

CIRCUIT DESCRIPTION

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SECTION 7 ALIGNMENT AND TEST PROCEDURES

7.1 RECEIVER ALIGNMENT

CRITICAL ADJUSTMENT

The TCXO must be adjusted within 5 minutes of turning the AC power on to the repeater. Do not under any circumstances try to set frequency later on in any of the tests, as TCXO frequency stability cannot then be guaranteed.

Refer to Figure 7-1 for component locations. Refer to Figure 7-6 for equipment needed and setup diagram. Select "RECEIVER" from the "TEST" menu in the Repeater Software.

7.1.1 PRETEST

Preset L102, L103, L104, L108, L109, L110, L140 and L141 tuning screws about 1/4 inch above the top of the casting.

For 12.5 kHz operation, place jumper plugs P203, P204 and P205 across pins 2-3 of J203, J204 and J205.

For 25 kHz operation, place jumper plugs P203, P204 and P205 across pins 1-2 of J203, J204 and J205.

7.1.2 VOLTAGE MEASUREMENTS

Apply power to the Receiver by plugging the 20pin cable from the RF Interface Board into J201 (see Figure 7-1).

Measure the voltages at the following pins.

U301, pin 1	+6V DC ±0.2V
U302, pin 1	+12V DC ±0.4V
U303, pin 1	+12V DC ±0.4V
U304, pin 1	+12V DC ±0.4V
R402/R403 junction	+3.5V DC ±0.1V

7.1.3 PROGRAM TUNE-UP CHANNEL

Using the PC and software, program the Synthesizer for the Receive frequency.

- Tune the VCO capacitor C803 for +7V DC ±0.05V at TP401.
- 3. Alternately tune L140 and L141 in 1/2-turn to 1-turn increments until a voltage is measured at TP101. At that time, tune L140 for a peak, then L141 for a peak.
- 4. Retune L140/L141 for a peak at TP101.

NOTE: The Channel Frequency and Synthesizer Frequency appear at the bottom of the screen.

7.1.4 RECEIVER FREQUENCY ADJUST

- 1. Place a pick-up loop (sniffer) or RF probe connected to a frequency counter near L139.
- 2. Set Y401 (TCXO) for the Injection Frequency ±50 Hz (Inj Freq = chnl freq + 52.95 MHz).

7.1.5 VCO TEST

- The software programs the synthesizer for 1 MHz above the receive channel.
- 2. The voltage on TP401 should be < 10V.
- 3. Record the voltage on TP101 _____.
- The software programs the synthesizer for 1 MHz below the receive channel.
- 5. The voltage on TP401 should be > 4V.
- 6. Record the voltage on TP101 _____.
- If the voltages recorded in Steps 3 and 6 are not within ±0.2V, tune L141 as required to balance the voltage readings.
- 8. The software programs the synthesizer for the receive frequency.

7.1.6 FRONT END ADJUSTMENTS

NOTE: Verify that the appropriate IF jumpers (J203, J204, J205) are selected.

- 1. Set the signal generator to the receive frequency at a level sufficient to produce an output voltage at TP201 or J201, pin 7 (RSSI Output).
- 2. Tune L102, L103, L104, L108, L109 and L110, then repeat, for a peak voltage at TP201. Decrease the generator output level to maintain a 2-3V reading at TP201.

FOR 12.5 kHz CHANNELS:

NOTE: Perform this test if C239 and C249 are placed on the board.

- 1. Set the generator to an RF level sufficient to produce 2V DC at TP201.
- 2. Remove any modulation from the signal generator.
- 3. Increase the signal generator RF frequency 2.5 kHz.
- 4. Adjust C239 for peak DC voltage at TP201.
- 5. Adjust C249 for peak DC voltage at TP201.
- 6. Reset the signal generator to the tune-up frequency.
- 7. Set the signal generator to 100 μV into the receiver with a 1 kHz tone at ± 1.5 kHz deviation. (1000 μV at the generator with 20 dB pad gives 100 μV at the receive antenna.)
- 8. Tune Z215 for $2V \pm 0.05V$ at U203, pin 9.
- 9. Tune R253 for 387 mV RMS, ±5 mV RMS, at TP202.
- 10. Adjust R248 for $2V \pm 0.05V$ at TP202.
- 11. Connect a distortion analyzer to TP202.
- 12. Tune L211, L213, L214 and L216 for minimum distortion <5%, (typically <3%).
- 13. Repeat Step 12 then Steps 8, 9 and 10.

7.1.7 AUDIO DISTORTION

 Plug a 16 ohm load at J101 or J104 on the MAC (Main Audio Card).

- 2. Connect a distortion analyzer to the 16 ohm load.
- 3. Measure the distortion of the receive audio at J101 or J104 on the MAC with the local volume control set to 2.8V RMS.
- 4. The reading shall be less than 3%. (Typically less than 1%.)
- 5. Measure receive sensitivity at J101 or J104 on the MAC.
- 6. The reading should be less than 0.35 μ V. (Typically 0.25 μ V.)
- 7. The software programs the synthesizer for 1 MHz above the Receive frequency.
- 8. Receive sensitivity should be less than 0.35 μ V., (Typically less than 0.30 μ V.)
- The software programs the synthesizer for 1 MHz below the Receive frequency.
- 10. Receive sensitivity should be less than 0.35 μV . (Typically less than 0.30 μV .)
- 11. Adjust the signal generator level to produce 15 dB SINAD.
- 12. Adjust R221 for $0.5V \pm 0.02V$ at TP201.

FOR 25 kHz CHANNELS:

NOTE: Perform this test if C204 and C214 are placed on the board.

- 1. Set the generator to an RF level sufficient to produce 2V DC at TP201.
- 2. Remove any modulation from the signal generator.
- 3. Increase the signal generator RF frequency 5 kHz.
- 4. Adjust C204 for peak DC voltage at TP201.
- 5. Adjust C249 for peak DC voltage at TP201.
- 6. Reset the signal generator to the tune-up frequency.

- Set the generator to 100 μV into the receiver with a

 kHz tone at ±3 kHz deviation.
 1000 μV at the generator with 20 dB pad gives

 μV at the receive antenna.)
- 8. Tune Z205 for $2V \pm 0.05V$ at U201, pin 9.
- Tune R220 for 387 mV RMS, ±5 mV RMS, at TP202.
- 10. Adjust R216 for $2V \pm 0.05V$ at TP202.
- 11. Connect a distortion analyzer to TP202.
- 12. Tune L201, L203, L204 and L206 for minimum distortion <5%, (typically <3%).
- 13. Repeat Step 12 then Steps 8, 9 and 10.

7.1.8 AUDIO DISTORTION

- 1. Plug a 16 ohm load at J101 or J104 on the MAC (Main Audio Card).
- 2. Connect a distortion analyzer to the 16 ohm load.
- Measure the distortion of the receive audio at J101 or J104 on the MAC with the local volume control set to 2.8V RMS.

- 4. The reading shall be less than 3%. (Typically less than 1%.)
- 5. Measure receive sensitivity at J101 or J104 on the MAC.
- 6. The reading should be less than 0.35 μ V. (Typically 0.25 μ V.)
- 7. The software programs the synthesizer for 1 MHz above the Receive frequency.
- 8. Receive sensitivity should be less than 0.35 μ V. (Typically less than 0.30 μ V.)
- 9. The software programs the synthesizer for 1 MHz below the Receive frequency.
- 10. Receive sensitivity should be less than 0.35 μ V. (Typically less than 0.30 μ V.)
- 11. Adjust the signal generator level to produce 15 dB SINAD.
- 12. Adjust R219 for $0.5V \pm 0.02V$ at TP201.

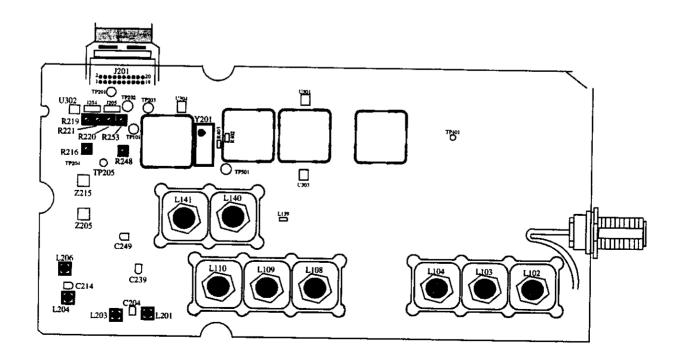


Figure 7-1 RECEIVER ALIGNMENT POINTS

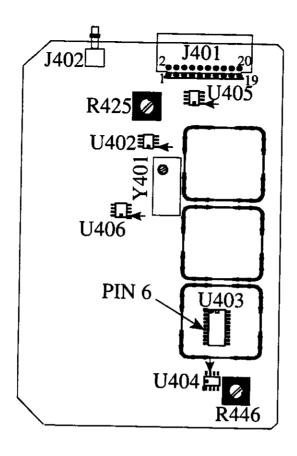


Figure 7-2 EXCITER ALIGNMENT POINTS

7.2 EXCITER ALIGNMENT

CRITICAL ADJUSTMENT

The TCXO must be adjusted within 5 minutes of turning the AC power on to the repeater. Do not under any circumstances try to set frequency later on in any of the tests, as TCXO frequency stability cannot then be guaranteed.

Refer to Figure 7-2 for component locations and Figure 7-7 for equipment needed and setup diagram.

NOTE: Some adjustments will be made using the cursor "Up"/"Dn" or "PgUp"/"PgDn" keys.

WARNING

SAFETY MEASURES ARE DISABLED IN TEST MODE. ALARMS ARE ACTIVE. HOWEVER, FEA-TURES SUCH AS THERMAL SHUTDOWN IN THE PA ARE DISABLED.

7.2.1 PRETEST

- 1. Set TCXO modulation adjust R425 fully counterclockwise.
- 2. Connect the power meter to J402.

7.2.2 VOLTAGE MEASUREMENTS

Apply power to the Exciter by plugging the 20pin cable from the RF Interface Board into J401.

Measure the voltages at the following pins.

U406, pin 1 +12V DC ±0.4V U405, pin 1 +5V DC ±0.2V U402, pin 1 +3.5V DC ±0.1V U404, pin 7 +3.5V DC ±0.1V

7.2.3 PROGRAM TUNE-UP CHANNEL

- 1. Program the Tune-Up frequency.
- 2. Press the space bar to key the Exciter.
- 3. Tune VCO capacitor C803 for 4.5V ±0.05V on U403, pin 6.
- Measure the Power Output of the Exciter at J402. Reading should be > +18 dBm.
- 5. Press the space bar to unkey the Exciter.

7.2.4 VCO TEST

- The software programs the synthesizer for 3 MHz above the Tune-Up frequency.
- 2. Press the space bar to key the Exciter.
- 3. The voltage on U403, pin 6 should be < 7V. Power output should be > +18 dBm.
- 4. Press the space bar to unkey the Exciter.
- The software programs the synthesizer for 3 MHz below the Tune-Up frequency.
- 6. Press the space bar to key the Exciter.
- 7. The voltage on U403, pin 6 should be > 2.5V. Power output should be > +18 dBm.
- 8. Press the space bar to unkey the Exciter.
- The software programs the synthesizer for the Transmit Channel.

7.2.5 TCXO FREQUENCY ADJUST

- 1. Connect a 10 dB pad and frequency counter to J402.
- 2. Press the space bar to key the Exciter.
- 3. Tune TCXO Y401 for the Transmit Channel Frequency, ± 50 Hz.
- 4. Press the space bar to unkey the Exciter.

7.2.6 TRANSMIT MODULATION ADJUST

- Connect a 10 dB pad and modulation analyzer to J402.
- 2. Press the "FM" and "3 kHz LPF" switches of the modulation analyzer.
- 3. Inject a 1 kHz sine wave at 400 mV RMS into P100, pin 32 on the MAC.
- 4. Adjust U149 with "Up/Dn" and "PgUp/PgDn" keys for 707 mV RMS on P100, pin 29. This waveform should be a "clean" sine wave.

NOTE: This test changes the Tx audio deviation limit. To correct the limit, perform adjustment per Section 7.4.5.

- 5. Press the space bar to key the Exciter.
- Set R446 for ±3 kHz deviation (25 kHz channels) or ±1.5 kHz deviation (12.5 kHz channels).
- 7. Press the space bar to unkey the Exciter.
- 8. Adjust U151 with "Up/Dn" and "PgUp/PgDn" keys for a 2V P-P square wave on P100, pin 29.

NOTE: This test changes the Tx audio deviation limit. To correct the limit, perform adjustment per Section 7.4.5.

- 9. Press the space bar to key the Exciter.
- 10. Set R425 for "best" square wave as observed on the modulation analyzer output to the oscilloscope.

NOTE: Ensure that the oscilloscope is "DC" coupled and the Modulation Analyzer has the 3 kHz LPF switch set but NOT the 300 Hz HPF or 50 Hz HPF switches set.

- 11. Press the space bar to unkey the Exciter.
- 12. Connect a 10 dB pad and modulation analyzer to J402.
- 13. Press the "FM" and 3 kHz LPF switches of the modulation analyzer.

- 14. Inject a 1 kHz sine wave with a level of 400 mV RMS into P100, pin 32.
- 15. Adjust U149 for 707 mV RMS on P100, pin 29. This waveform should be a clean sine wave.
- 16. Press the spacebar to key the Exciter.
- 17. Repeat Step 6.
- 18. Press the spacebar to unkey the Exciter.

7.3 110W POWER AMPLIFIER ALIGNMENT

7.3.1 INTRODUCTION

Refer to Figures 7-3 and 7-4 for component locations. Refer to Figure 7-8 for equipment needed and setup diagram. Select "PA" from the "TEST" menu in the Repeater Software.

IMPORTANT NOTE

No field alignment is required. Adjustments in Sections 7.3.2 and 7.3.3 are part of a new unit production test procedures. They should only be performed as required on "out-of-warranty" and "field-repaired" units. Broken seals on R116, R663 or R680 will void the warranty! Full power control range of 25-110W is controlled by the repeater configuration parameters under the Edit-Setup Parameters menu selection.

The adjustments in Section 7.3.2 provide for proper matching for the output of Q501 and set a protective limit on the drive to the final transistors. This limit is approached only under certain unusual operating or repair conditions. However, improper adjustment may impair normal operation of the PA, especially at temperature extremes.

If Q501 or U501 are replaced, only Section 7.3.2 adjustments should be performed. No other adjustments are necessary in this case. Replacement of RF components surrounding Q501, U501 does not justify performance of Section 7.3.2 adjustments. Replacement of active components within the power control circuitry of the RF Interface Board would require Section 7.3.2 adjustments.

These adjustments are necessary only if repairs are made and such repairs are likely to affect the sensitivity/calibration of the forward or reverse power detectors (e.g. replacement of detector diodes CR651/CR652 or of the entire forward/reverse power detector assembly). Replacement of components within the power control circuitry of the RF Interface Board are unlikely to affect the calibration of the power control.

NOTE: Replacement of Q501, Q502, Q503 or U501 does not require the adjustments in this Section.

7.3.2 DRIVER TUNING AND LIMIT ADJUST-MENTS

- 1. Connect attenuator and power meter to A8.
- 2. Connect the:

Power supply ground lead to P105 +15V DC lead to P103 +26.5V DC lead to P101 36-pin cable to J101 on the RFIB

- 3. Set the signal generator to +15 dBm ±0.1 dB. Connect the signal generator to A9.
- 4. Press the space bar to key the PA.
- 5. Set R116 on the RFIB for $22W \pm 1W (\pm 0.2 \text{ dB})$.

NOTE: All cable and attenuator loss must be measured and incorporated into this adjustment.

- 6. Tune C521 for maximum power.
- 7. Reset R116 for 22W ± 1 W (± 0.2 dB).
- Repeak C521.
- 9. Press the space bar to unkey the PA.

CRITICAL ADJUSTMENTS

NOTE: Improper adjustment may impair normal PA operation.

- 1. Set the generator to $+15 \text{ dBm } \pm 0.1 \text{ dB}$.
- 2. Press the space bar to key the PA.

- 3. Adjust R116 for $40W \pm 2W (\pm 0.2 \text{ dB})$.
- 4. Press the space bar to unkey the PA.
- 5. Set the generator to $+15 \text{ dBm } \pm 0.1 \text{ dB}$.
- 6. Press the space bar to key the PA.
- 7. Adjust R116 for 40W ±2W (±0.2 dB) only if the power exceeds 40W.
- 8. Press the space bar to unkey the PA.
- Disconnect the attenuator and power meter from J501 and connect to Transmit Antenna Connector A8.
- 10. Connect cable A501 to J501. Ensure the cable position is midway between the drive collector feed and the adjacent input Wilkinson combiner traces on the printed circuit board.

7.3.3 REFLECTED POWER ADJUST

- 1. Remove the load cable from A8.
- 2. Press the space bar to key the PA. NOTE: This will not harm the PA.
- 3. Adjust Reverse Power Calibration Pot R680 for equal voltages on W126 and W121 on the RFIB or for equal Forward and Reverse Power.
- 4. Press the space bar to unkey the PA.
- 5. Apply "Glyptol" to R663, R680 and R116.
- 6. Momentarily short R171 on the RFIB. The PA fan should turn ON.
- 7. Measure temperature detector voltage at W127 on the RFIB. Normal output at 25°C ambient is approximately +2.1V DC.

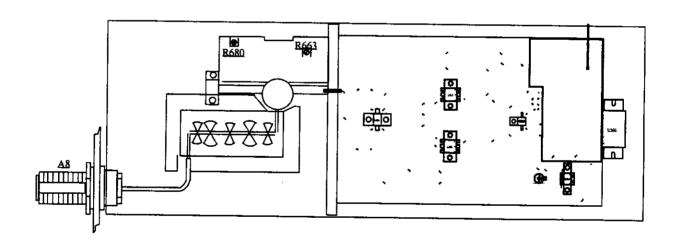


Figure 7-3 110W POWER AMPLIFIER ALIGNMENT POINTS

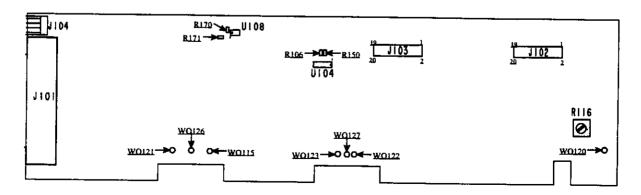
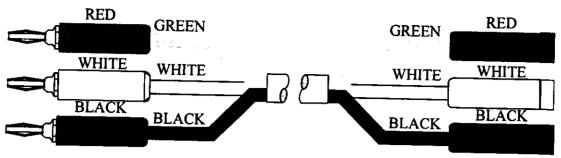


Figure 7-4 RF INTERFACE BOARD ALIGNMENT POINTS



(INCLUDED IN 2000 SERIES SERVICE KIT 250-2000-230)

Figure 7-5 POWER EXTENDER CABLES

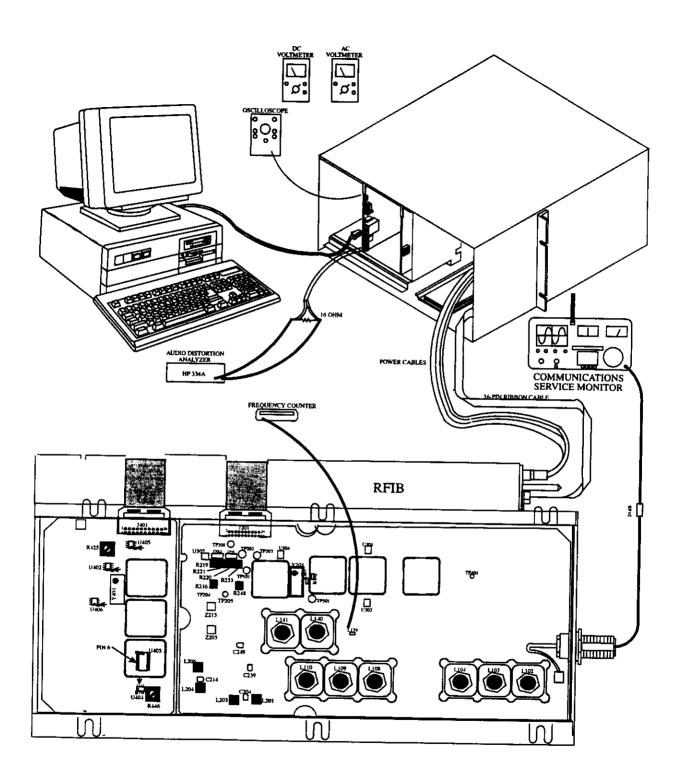


Figure 7-6 RECEIVER TEST SETUP

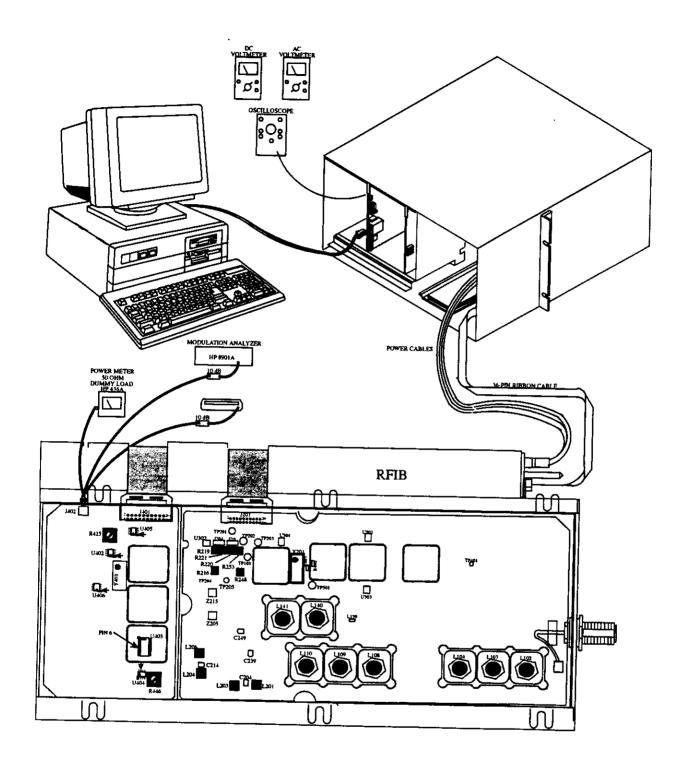


Figure 7-7 EXCITER TEST SETUP

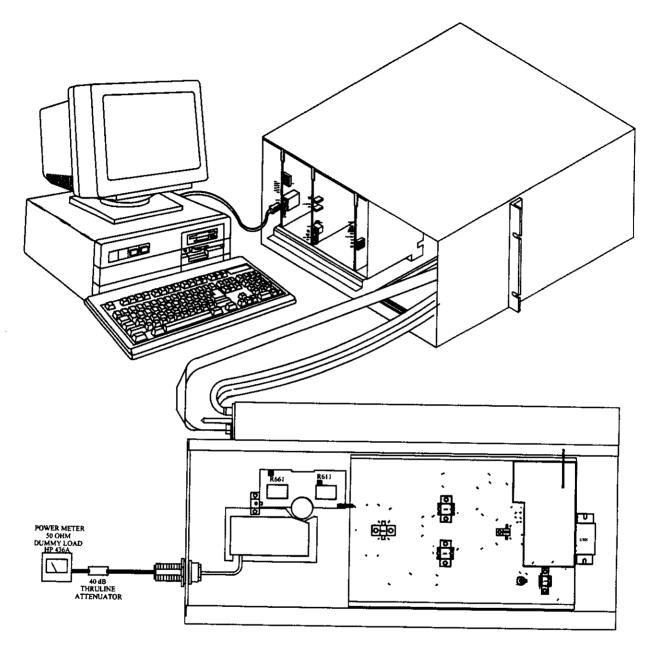


Figure 7-8 110W POWER AMPLIFIER TEST SETUP

7.4 FULL REPEATER ALIGNMENT

7.4.1 PERFORMANCE TEST PROGRAM

1. Select the TEST - FULL REPEATER - ALL TEST and press Enter.

7.4.2 REPEATER SETUP

The VIKING VX repeater has been pretested at the factory, therefore only performance tests are required to check the repeater. Refer to test setup diagrams for equipment and cabling diagram.

Turn on the repeater power supply switch (S508) in the IAC or engage the locking lever (see Figure 7-14).

The operating code has been programmed at the factory. The parameters are programmed into the MPC. If these parameters have changed or are incorrect, exit this test and reprogram the repeater.

It may be necessary to remove the RF assembly from the chassis and connect via extension cables for some of the tests or adjustments.

NOTE: All audio generators and audio voltmeters are unbalanced unless specifically stated otherwise.

7.4.3 TRANSMITTER TEST/ADJUSTMENTS

Transmit Mode

- 1. Press the space bar to key the repeater.
- The Transmit LED on the IAC should turn on to indicate the repeater is transmitting (see Figure 7-14).
- 3. Press the space bar to unkey the repeater.

Transmit TCXO Frequency Adjustment

CRITICAL ADJUSTMENT

The TCXO must be adjusted within 5 minutes of turning the AC power on to the repeater. Do not under any circumstances try to set frequency later on in any of the tests, as TCXO frequency stability cannot then be guaranteed.

- 4. Press the space bar to key the repeater.
- 5. Check the frequency of the transmitted signal. The frequency should be ± 50 Hz of the channel frequency.
- 6. Adjust the frequency with Y401 (TCXO) on the Exciter (see Section 7.2.5).
- 7. Press the space bar to unkey the repeater.

Transmitter Output Power Adjustment

- 1. Press the space bar to key the repeater.
- Check the transmit output power. The power can be adjusted from the computer using the cursor Up/Dn and PgUp/PgDn keys. The test equipment should be calibrated for ±2W.
- 3. Press the space bar to unkey the repeater.

7.4.4 RECEIVER TESTS/ADJUSTMENT

NOTE: Jumper J103 selects between a 12.5 kHz IF and a 25 kHz IF.

NOTE: If this is a voting repeater, it is not equipped with a receiver.

Receiver TCXO Frequency Adjustment

CRITICAL ADJUSTMENT

The TCXO must be adjusted within 5 minutes of turning the AC power on to the repeater. Do not under any circumstances try to set frequency later on in any of the tests, as TCXO frequency stability cannot then be guaranteed.

- 1. Check the receiver injection frequency by using a "sniffer" pickup loop, or RF probe connected to a suitable frequency counter placed near L139 in the Receiver (see Section 7.1.4).
- 2. Adjust Y401 (TCXO) on the Receiver to within ±50 Hz of the channel frequency + 52.95 MHz.

Receiver Audio Distortion Measurement

- Adjust the RF generator for 100 μV into the Receiver with a modulation tone of 1 kHz at ±3 kHz deviation (25 kHz channels) or ±1.5 kHz deviation (12.5 kHz channels).
- 2. Insert test cables into J100/J103 on the MAC and connect to an AC voltmeter.
- 3. Adjust R237 for 0 dBm (775 mV RMS).
- 4. Connect a 16 ohm load and distortion analyzer to J101 or J104 of the MAC.
- 5. Adjust R236 for 2.8V RMS and measure the distortion. Distortion should be < 3%.

Receiver Hum and Noise Measurement

- Adjust the RF generator for 100 μV into the Receiver with a modulation tone of 1 kHz at ±3 kHz deviation (25 kHz channels) or ±1.5 kHz deviation (12.5 kHz channels).
- Connect a 16 ohm load and distortion analyzer to J101 or J104 of the MAC.
- 3. Adjust R236 for 2.8V RMS.
- 4. Remove modulation from the RF generator. The measured level must be ≤ -50 dB.

Receiver SINAD Measurement

- Adjust the RF generator for 100 μV into the receiver with a 1 kHz tone at ±3 kHz deviation (25 kHz channels) or ±1.5 kHz (12.5 kHz channels).
- 2. Connect a 16 ohm load and distortion analyzer to J101 or J104 of the MAC.
- 3. Adjust R236 for 2.8V RMS.
- 4. Re-adjust RF level for 12 dB SINAD. 12 dB SINAD reading should be \leq 0.35 μ V.

Receiver Squelch Adjustment

- 1. Adjust the RF generator for $100 \mu V$ into the receiver with a 1 kHz tone at ± 3 kHz (25 kHz channels) or ± 1.5 kHz deviation (12.5 kHz channels).
- Connect a 16 ohm load and distortion analyzer to J101 or J104 of the MAC.
- 3. Adjust R236 for 2.8V RMS.
- 4. Set the RF generator output for 5 dB SINAD.
- 5. Adjust R234 on the MAC so the Receiver just squelches.
- Increase the RF generator output until the Receiver unsquelches. Reading should be ≤ 10 dB SINAD.

Receiver Data Level Adjustment

- Adjust the RF generator for 100 μV into the receiver with a 100 Hz tone at ±1 kHz (25 kHz channels) or ±800 Hz deviation (12.5 kHz channels).
- Insert test cables into J100/J103 on the MAC and connect to an AC voltmeter.
- 3. Adjust R235 to achieve 340 mV RMS.

Local Speaker/Microphone Check

- Adjust the RF generator for 100 μV into the receiver with a 1 kHz tone at ±3 kHz deviation (25 kHz channels) or ±1.5 kHz (12.5 kHz channels).
- Plug a Speaker/Microphone into J101/J102 of the MAC.
- 3. Adjust R236 until the 1 kHz tone is heard.

Receiver Desense Check

 Adjust the RF generator for 100 μV into the receiver with a 1 kHz tone at ±3 kHz deviation (25 kHz channels) or ±1.5 kHz (12.5 kHz channels).

- 2. Connect a 16 ohm load and distortion analyzer to J101 or J104 of the MAC.
- 3. Adjust R236 for 2.8V RMS.
- 4. Re-adjust the RF generator output for 12 dB SINAD.
- 5. Press the space bar to key the transmitter.
- 6. SINAD should not degrade more than 1 dB or to no less than 11 dB SINAD.
- 7. Press the space bar to unkey the transmitter.

Receiver Miscellaneous Tests (Optional)

Several additional tests may be performed on the Repeater Receiver as listed below:

- 1. Signal Displacement Bandwidth
- 2. Adjacent Channel Rejection
- 3. Offset Channel Selectivity
- 4. Intermodulation Rejection
- 5. Spurious Rejection
- 6. Audio Response
- 7. Audio Sensitivity

Perform the Test desired using the appropriate RF Generators, modulation frequencies and levels, RS-232 levels and test probes following the latest TIA document measurement procedures.

7.4.5 TRANSMIT AUDIO/DATA LEVEL ADJUST-MENTS

NOTE: All audio generators and audio voltmeters are unbalanced unless specifically stated otherwise.

Audio Deviation Limit Adjustment

1. Apply a 1 kHz tone at -3 dBm (578 mV RMS) to P100, pin 32 of the MAC.

- 2. Insert test cables into J100/J103 and connect to an AC voltmeter.
- 3. Press the space bar to key the transmitter.
- 4. Adjust R305 for 0 dBm (775 mV RMS).
- 5. Press the space bar to unkey the transmitter.
- Apply a 1 kHz tone at +7 dBm (1.73V RMS) to P100, pin 32 of the MAC. (Set modulation analyzer LPF to 3 kHz.)
- 7. Press the space bar to key the transmitter.
- 8. Adjust U149 with the PgUp/PgDn and CurUp/ CurDn keys to set the maximum allowed deviation at ±3.5 kHz deviation (25 kHz channels) or ±1.6 kHz (12.5 kHz channels).
- 9. Press the space bar to unkey the transmitter.
- 10. Remove the signal from P100, pin 32.

Repeat Audio Level Adjustment

NOTE: Audio Deviation Limit Adjustment must be completed before this test.

- Adjust the RF generator for 100 μV into the receiver with a 1 kHz tone at ±1.5 kHz deviation (25 kHz channels) or ±800 Hz (12.5 kHz channels). Be sure the Modulation Analyzer LPF switch is set to 3 kHz.
- 2. Press the space bar to key the transmitter.
- Adjust R237 on the MAC to achieve ±1.5 kHz (±100 Hz) transmit deviation (25 kHz channels) or ±800 Hz (12.5 kHz channels). Be sure the modulation analyzer LPF switch is set to 3 kHz.
- 4. Press the space bar to unkey the transmitter.
- 5. Connect an AC voltmeter to J103 and P100, pin 31 (RX_VOICE).
- 6. Adjust R238 for -3 dBm (548 mV RMS).
- 7. Remove the RF generator from the Receiver.

Data Level Adjustment

- Remove VNC cards if present.
 Set modulation analyzer LPF to 3 kHz.
 Press the space bar to key the transmitter.
- Adjust U151 with the PgUp/PgDn and CurUp/Cur/ Dn keys to achieve ±1 kHz (±100 Hz) transmit deviation (25 kHz channels) or ±800 Hz (12.5 kHz channels).
- 3. Press the space bar to unkey the transmitter.

Audio/Data Deviation Check

- Apply a 1 kHz tone at +7 dBm (1.73V RMS) to P100, pin 32 of the MAC. Set modulation analyzer LPF to 3 kHz.
- 2. Press the space bar to key the transmitter.
- Measured deviation should be ±4.5 kHz (±200 Hz) (25 kHz channels) or ±2.4 kHz (±100 Hz) (12.5 kHz channels).
- 4. Press the space bar to unkey the transmitter. Disconnect all cables.

CWID Level Check

- 1. Set modulation analyzer LPF switch to 3 kHz. Press the space bar to key the transmitter.
- 2. Deviation should be 1.5 kHz to 2.5 kHz (25 kHz channels) or ± 0.750 kHz to 1.75 kHz (12.5 kHz channels).
- 3. Press the space bar to unkey the transmitter.

Local Speaker/Microphone Check

- Plug a Speaker/Microphone into J101/J102 of the MAC. Set modulation analyzer LPF switch to 3 kHz.
- 2. Press the space bar to key the transmitter.
- 3. Press the microphone PTT and say "four" loudly into the microphone.

- Deviation should measure ±3 to ±3.5 kHz (25 kHz channels) or ±0.75 kHz to 1.6 kHz (12.5 kHz channels).
- 5. Release the microphone PTT.
- 6. Press the space bar to unkey the transmitter.

Transmitter Hum and Noise Ratio (Optional)

NOTE: An HP8901A modulation analyzer is required for this test.

1. On the modulation analyzer press:

300 Hz HPF 3000 Hz LPF FM Pre-Display 750 μS Avg RMS Cal .44 (25 kHz channels) .22 (12.5 kHz channels) dB

- Press the space bar to key the transmitter and measure the Hum and Noise Ratio. The reading should be less than -50 dB (12.5 kHz) or -55 dB (25 kHz).
- 3. Press the space bar to unkey the transmitter.

Transmit Audio Distortion

1. On the modulation analyzer press:

FM 50 Hz 15 kHz

- Apply -11.7 dBm at 1 kHz to P100, pin 32 of the MAC.
- 3. Press the space bar to key the transmitter.
- 4. Adjust audio level to produce ±1 kHz deviation (25 kHz) or ±0.5 kHz (12.5 kHz deviation).

5. On the modulation analyzer select:

300 Hz

3 kHz

750 µs de-emphasis

6. Distortion is < 2%.

LTR Modem Repeat Audio Level Adjust

NOTE: Valid only with LTR modem option.

- Adjust the RF generator for 100 μV into the receiver with a 1 kHz tone at ±1.5 kHz deviation (25 kHz channels) ±800 Hz (12.5 kHz channels). Be sure the Modulation Analyzer LPF switch is set to 3 kHz.
- 2. Press the space bar to key the transmitter.
- Adjust R305 for ±1.5 kHz ±100 Hz deviation (25 kHz channels) or 800 Hz (12.5 kHz channels) out of the Transmitter.
- 4. Press the space bar to unkey the transmitter.

7.4.6 VOTER AUDIO LEVEL ADJUSTMENT

NOTE: Use an unbalanced audio voltmeter.

- Inject a 1 kHz tone at -12 dBm (194 mV RMS) into J2, pin 17. This tone represents ±1.5 kHz deviation in the Voter Receiver.
- Adjust R233 to obtain a level of -6 dBm (387 mV RMS) at J100/J103 on the MAC.

7.4.7 AUDIO/DATA LEVEL ADJUSTMENTS

NOTE: Section 7.4.5 must be completed before any of the following adjustments can be made.

NOTE: All audio generators and audio voltmeters are unbalanced unless specifically stated otherwise.

Voice Audio From Repeater

- 1. Set MAC S100 and S101, all Sections OFF.
- 2. Adjust the RF generator for 100 μ V modulated with a 1 kHz tone at ± 1.5 kHz deviation.

- Connect a balanced AC voltmeter with a 600 ohm input impedance between balanced lines RXA+ and RXA- on J2, located on the back of the Repeater.
- 4. Adjust R239 on the MAC for the type of line used.

Leased Line/Direct Connect (default)
-12 dBm (194 mV RMS)

Microwave/T1 (optional) -28 dBm (31 mV RMS)

Voice Audio To Repeater

1. Set MAC S100 and S101, all Sections OFF (see Figure 7-9).

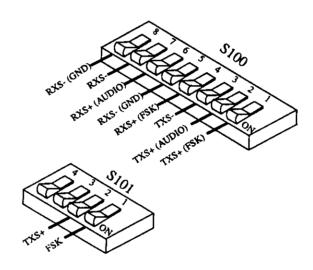


Figure 7-9 S100 SETTING

 Inject a 1 kHz tone from a balanced 600 ohm source, at the level determined by the type of line used, into TXA+ and TXA- of J2 located on the back of the Repeater (see Figure 7-11).

Leased Line/Direct Connect (default)
-12 dBm (194 mV RMS)

Microwave/T1 (optional)
-28 dBm (31 mV RMS)

3. Adjust R243 on the MAC to obtain -6 dBm (387 mV RMS) measured at J100/J103.

7.4.8 REPEATER OPERATION

New HSDB Test

1. Switch settings on the MPC for RS-485 operation are shown in Figure 7-10.

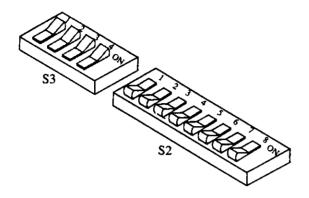


Figure 7-10 NEW HSDB SWITCH SETTINGS

- 2. Verify that the repeater is programmed for "Stand Alone" mode in Setup Parameters-F4 (see Section 4.3.1).
- 3. The repeater is now in Normal Operation mode. Verify by the MPC front panel indicators that no HSDB alarms have occurred (Alarm Number 10) see Table 1-2.

Handshake Test

1. Program an LTR portable or mobile for the following parameters.

Home Repeater - Same as repeater number.

Area - Same as repeater's area bit.

Home Repeater's Channel Number - Same
as repeater's channel number.

Group 1 Encode/Decode - 1

- 2. The repeater is now in Normal Operation mode.
- 3. Key the radio several times on the programmed System/Group. Access should occur every time. (Proper Tx/Rx antenna connections are assumed.)

Alarm Test

- 1. The repeater is now in Normal Operation mode.
- 2. Verify by the MPC front panel indicators that no alarms have occurred (see Table 1-2).

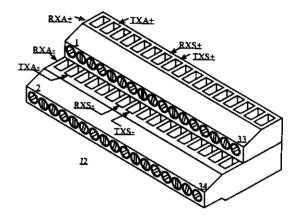


Figure 7-11 J2 TERMINAL BLOCK

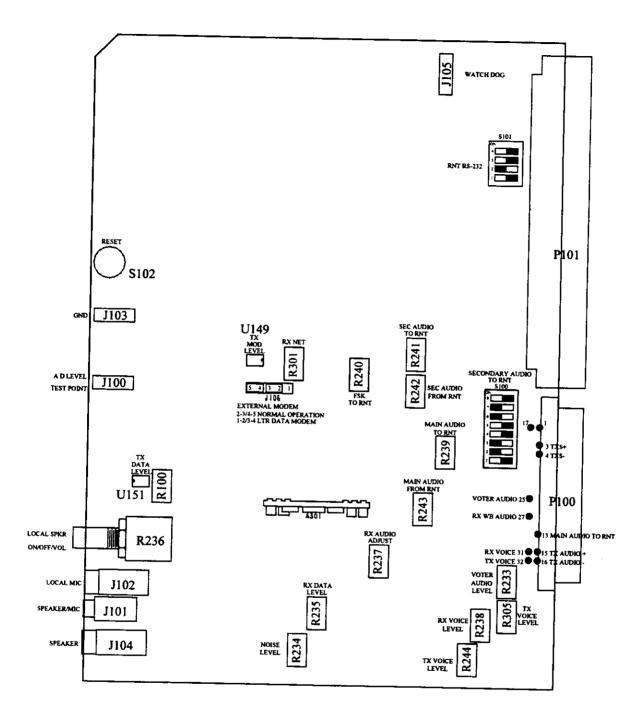


Figure 7-12 MAC ALIGNMENT POINTS

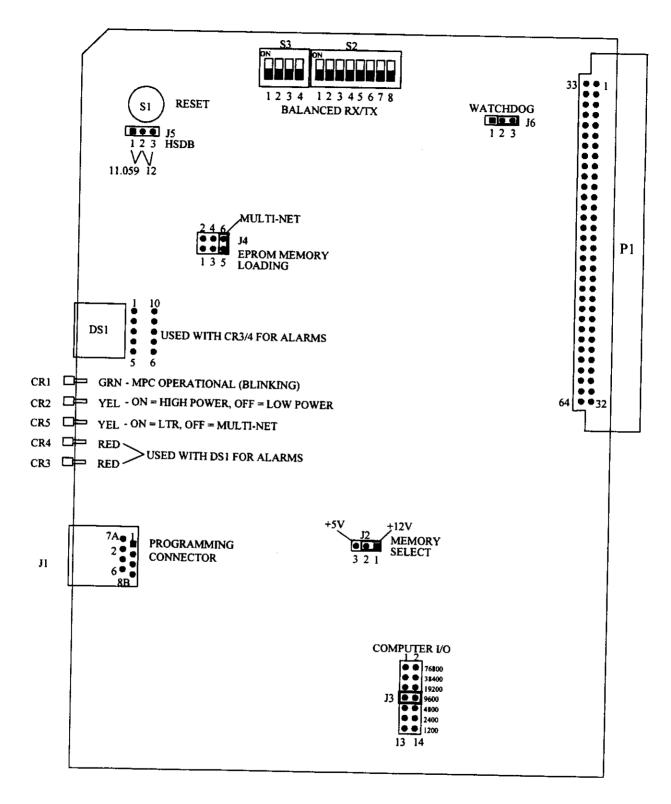


Figure 7-13 MAIN PROCESSOR CARD ALIGNMENT POINTS

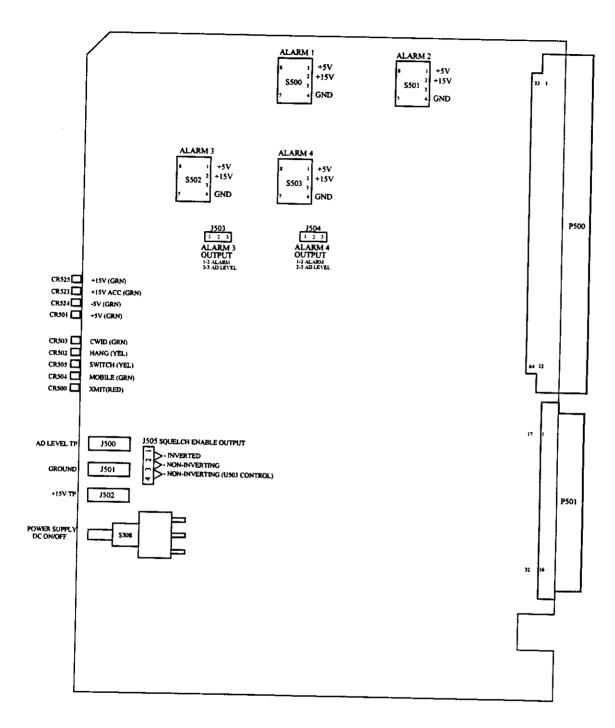


Figure 7-14 INTERFACE ALARM CARD ALIGNMENT POINTS

SECTION 8 SERVICING

8.1 INTRODUCTION

8.1.1 PERIODIC CHECKS

This repeater should be put on a regular maintenance schedule and an accurate performance record maintained. Important checks are receiver sensitivity and transmitter frequency, modulation, and power output. It is recommended that repeater performance be checked regularly even though periodic checks are not specifically required by the FCC.

8.1.2 SURFACE-MOUNTED COMPONENTS

A large number of the components used in this repeater are the surface-mounted type. Since these components are relatively small in size and are soldered directly to the PC board, care must be used when they are replaced to prevent damage to the component or PC board. Surface-mounted components should not be reused since they may be damaged by the unsoldering process. For more information on replacing surface-mounted components, refer to the Surface-Mounted Device Handbook, Part No. 001-0576-002.

8.1.3 SCHEMATIC DIAGRAMS AND COMPO-NENT LAYOUTS

Schematic diagrams and component layouts of the PC boards used in this repeater are located in Section 10. A component locator guide is also provided for both the schematic and board layouts to aid in component location.

8.1.4 REPLACEMENT PARTS LIST

A replacement parts list containing all the parts used in this repeater is located in Section 9. Parts are listed alpha numerically according to designator. For information on ordering parts, refer to Section 1.9.

8.1.5 TCXO MODULES NOT SERVICEABLE

Transmit or Receive TCXOs are not field serviceable because if a part is changed, a factory recalibration must be performed to ensure that it stays within its ± 1 PPM tolerance.

8.2 SYNTHESIZER SERVICING

8.2.1 INTRODUCTION

Synthesizer malfunctions can be caused by no VCO output, or the VCO is unlocked. The VCO can be unlocked due to a bad synthesizer chip, an incomplete synthesizer phase-lock loop, or because the synthesizer chip is programmed incorrectly.

To make certain that the synthesizer chip is receiving programming data, pins 17, 18 and 19 of the chip should be monitored during programming. Pin 17 (Enable) will go from a high to a low level. Pin 18 (Clock) will go from low to high in narrow pulses. Pin 19 (Data) goes from high to low with wider data pulses.

When the VCO is locked, the lock detect line of the synthesizer pin 2 is high with very narrow negative-going pulses. These pulses become wider when the VCO is out of lock. When this unlock condition exists either in the Exciter VCO or the Receiver VCO, it is relayed by the RF Interface board and is detected by the MPC via the RF Data lines. The MPC then does not allow the transmitter to key and the receiver cannot unsquelch.

When the VCO is unlocked, the fx and fv inputs to the phase detector are not in phase (refer to Sections 6.1.12 and 6.2.5). The phase detector in the synthesizer then causes the VCO control voltage to go to the high or low end of its operating range (Tx VCO 0 or 9V, Rx VCO 0 or 18V). This in turn causes the VCO to oscillate at the high or low end of its range.

As shown in Figures 6-1 and 6-4, a loop is formed by the VCO, buffer, frequency input (FIN) and the phase detector output (PD OUT). Therefore, if any of these components begin to malfunction, improper signals appear throughout the loop. However, correct operation of the counters can still be verified by measuring the input and output frequencies to check the divide number.

Proceed as follows to check the input and output signal of the synthesizer modules to determine if they are operating properly.

8.2.2 TCXO MODULE

Check the signal at TCXO, pin 5. It should be 17.5 MHz for Y201 and Y401 at a level of approximately 3V P-P. If the TCXO is defective, it is not serviceable and must be replaced with a new unit as described in Section 8.1.5.

Measure the signal at pin 20 (Ref In) of the synthesizer chip. It will be approximately 1V P-P. If the signal is low here, the TCXO buffer circuit may be defective.

8.2.3 VOLTAGE CONTROLLED OSCILLATOR (VCO)

Check for VCO output signal with a high impedance RF voltmeter. If there is no output signal, or if the frequency is greatly off, the VCO is defective.

Next, monitor the signal level at pin 11 (F In) of the synthesizer chip. If the signal is less than 100 mV P-P, the VCO buffer is defective.

Lock Detector

When the VCO is locked on frequency, the waveform at pin 2 (Lock Det) should be as follows. When the VCO is unlocked, the negative-going pulses should be much wider than those shown in Figure 8-1. If the lock detect circuit is operating properly, check prescaler input pin 11 (F In).

The operation of the N and A counters can be observed by monitoring pins 16 and 19. Pin 16 (fv) equals fin \div (64N+A) = 6.25 kHz if the synthesizer is locked. Pin 9 is the modulus control signal.

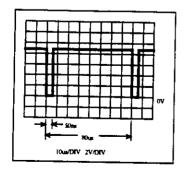


Figure 8-1 LOCK DETECT WAVEFORM

Modulus Control Signal

- The frequency of the modulus control signal on TEST 1, pin 9 should be equal to the N counter output frequency (either in or out of lock). When the VCO is in lock, this frequency should be 6.25 kHz.
- 2. The duty cycle of the modulus control signal determines the divide number of the prescaler. The duty cycle (T1 ÷ T2) should be as follows:

T1 ÷ T2 = A Cntr Div No ÷ N Cntr Div No T2 = $160 \mu s$ when locked.

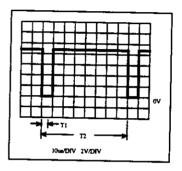


Figure 8-2 MODULUS CONTROL WAVE-FORM

If the modulus control signal is not correct, the synthesizer may be defective or the logic may not be programming the correct divide number.

8.2.4 INTERNAL PRESCALER

Checking Prescaler Divide Number

The prescaler divide number can be checked by measuring the input and output frequencies. The prescaler divide number can be calculated as follows. (A and N counter divide numbers are calculated as described in Section 8.2.5.)

Prescaler Divide Number = 64 + (A Cntr Div No ÷ N Cntr Div No)

Example: 450.250 MHz (receive)

Prescaler Div No = $64 + (40 \div 496) = 64.080645$

Measure the prescaler input frequency at fin, pin 11. Then measure the output frequency at TEST 2, pin 13 and calculate the divide number. If the VCO is not locked on frequency, the divide number should still be correct. The measured frequencies may not be exactly as calculated due to counter accuracy and resolution limitations.

NOTE: The counter should be connected to a high stability reference oscillator.

Example: 450.250 MHz VCO locked on frequency

 $397.3 \text{ (pin } 11) \div 6.2 \text{ (pin } 13) = 64.080645$

8.2.5 CALCULATING "N " AND "A " COUNTER DIVIDE NUMBERS

"N" Counter

N Counter Divide Number = Integer (VCO Freq. (MHz) ÷ 0.4)

 $6.25 \text{ kHz} (64) \div 1 \text{ MHz} = 0.4$

EXAMPLE: 450.025 MHz (receive)

VCO freq = 450.025 + 52.95 = 502.975 MHz N Cntr Div No = $502.975 \div 0.4 = 127.4375$ Integer (whole no.) of 1257.4375 = 1257

EXAMPLE: 450.250 MHz (transmit)

N Cntr Div No = $450.250 \div 0.4 = 1125.625$ Integer (whole no.) of 1125.625 = 1125

"A" Counter

A Counter Divide Number = (VCO freq (MHz) ÷ .00625) - (N Cntr Div No x 64)

EXAMPLE: 450.025 MHz (receive)

A Cntr Div No = (502.975 ÷ .00625) - (1257 x 64) = 80,476 - 80,448 = 28 EXAMPLE: 450.250 MHz (transmit)

A Cntr Div No = (450.250 ÷ .00625) - (1125 x 64) = 72,040 - 72,000 = 40

8.3 RECEIVER SERVICING

To isolate a receiver problem to a defective section, start by checking the DC voltages shown in Section 6.5.6 and on the schematic diagram (Section 10). If that does not indicate the problem, perform the performance tests in Section 7.1 to isolate the problem. If the synthesizer is out of lock, the receiver is also nonfunctional because the first injection and IF signals will be incorrect.

8.4 TRANSMITTER SERVICING

To isolate a transmitter problem to a defective section, start by checking the DC voltages shown in Sections 6.5.4 and 6.5.5 and on the schematic diagram (Section 10). If that does not indicate the problem, perform the performance tests in Sections 7.2 and 7.3 to isolate the problem. If the synthesizer is out of lock, the exciter is also nonfunctional because the software will not allow the repeater to transmit.

8.5 POWER SUPPLY SERVICING

The power supply is a switch mode type with very high voltages. It is recommended that the power supply be returned to the factory for servicing (see Section 1.8). Customers that desire to do their own repairs can obtain a service manual for the power supply, Part No. 004-2000-810.

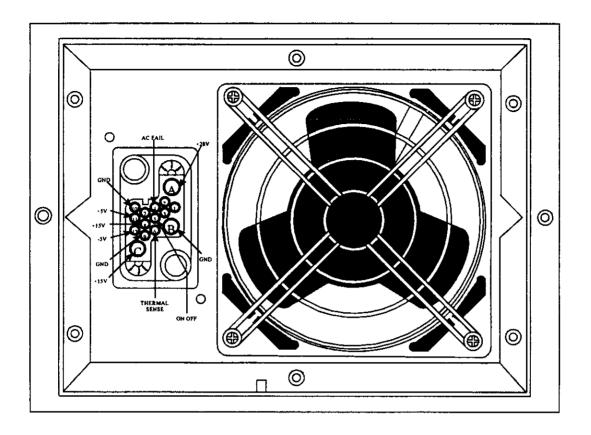


Figure 8-3 POWER SUPPLY REAR VIEW

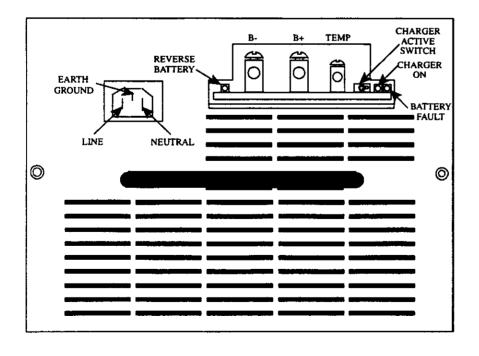


Figure 8-4 POWER SUPPLY FRONT VIEW

Standby Battery Jack

This provides a connection point for a +24V DC standby battery. Current is drawn from the battery only when the repeater enable line is on and AC has failed, or no AC is connected. A trickle charger can be switched in to charge the battery when AC returns. The charger switch is removed when a separate battery charger is used (see Figure 8-4). The standby battery connection to the power supply is factory or field installable.

NOTE: A small amount (<30 mA) of current is drawn from the batteries with the repeater off. If the repeater is going to be turned off for more than one week (with good batteries connected) the fuse should be removed from the DC cable harness.

8.5.1 VOLTAGE CHECKS

Secondary voltages can be checked at the power supply connector with the power supply removed from the Repeater. First the on/off line must be grounded, jumper pin 5 to ground, then check the supply voltages as shown (see Figure 8-3). If voltages are absent the supply must be sent to the E.F. Johnson Company.

8.6 CHIP COMPONENT IDENTIFICATION

8.6.1 CERAMIC CHIP CAPACITORS (510-36xx-xxx)

Ceramic chip capacitors are identified using either an American or Japanese EIA standard. The values for both standards are shown in Table 8-1.

American EIA Standard

Uses a single letter or number to indicate the value, and the color of this letter or number to indicate the multiplier.

Japanese EIA Standard

Uses a letter to indicate the value followed by a number to indicate the multiplier.

Example: 15 pF capacitor

American - Single Black "E"

Japanese -"E1"

The Japanese EIA Standard may also utilize a bar to indicate the temperature coefficient.

Example: A2 - 100 pF NPO

XX = NPO XX = N150 XX = N220

 $\underline{XX} = N330$ $\underline{XX} = N470$ $X\underline{X} = N750$

|XX = X7R|

8.6.2 TANTALUM CHIP CAPACITORS (510-26xx-xxx)

Tantalum chip capacitor identification varies with vendor and physical size. The positive (+) end is usually indicated by a colored board or beveled edge. The value and voltage may be indicated by printing on the capacitor or by using a special code.

8.6.3 CHIP INDUCTORS (542-9000-xxx)

Three colored dots are used to indicate the value of chip inductors. The two dots on the left side indicate the first and second digits of the value in nano-Henries, and the single dot on the right side indicates the multiplier (see Table 8-2).

Example: Dots - Brown-Black-Red

 $10 \text{ nH} \times 100 = 1000 \text{ nH} (1.0 \mu\text{H})$

The last three digits of the part number are also the value and multiplier. The multiplier digits are shown in Table 8-2.

8.6.4 CHIP RESISTORS

The value of chip resistors is indicated by a number printed on the resistor. A 3-digit number is used to identify $\pm 5\%$ and $\pm 10\%$ resistors, and a 4-digit number is used to identify $\pm 1\%$ resistors.

The 3-digit number used to identify $\pm 5\%$ and $\pm 10\%$ resistors corresponds to the last 3-digits of the E.F. Johnson part number. This number is derived as shown.

Example:

273 27k ohm339 3.3 ohm

Some resistors with a $\pm 1\%$ tolerance are identified by a 4-digit number and others may not have a marking. When identified with a 4-digit number, the first three digits are the value and the fourth is the multiplier.

Example: 57615.76k ohm

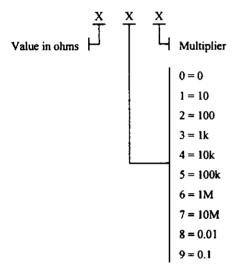
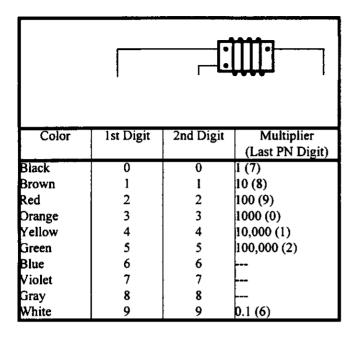


Figure 8-5 3-DIGIT RESISTOR

Table 8-1 CERAMIC CHIP CAP IDENTIFICATION

American ELA	Standard	Japanese EIA	Standard
First Letter/ Number	Value (pF)	First Letter/ Number	Value (pF)
Α	10	Α	1.0
В	11	В	1.1
С	12	С	1.2
D	13	Ð	1.3
Е	15	Е	1.5
Н	16	F	1.6
1	18	G	1.8
J	20	H	2.0
K	22	J	2.2
L	24	K	2.4
N	27	L	2.7
0	30	M	3.0
R	33	N	3.3
S	36	P	3.6
Т	39	Q	3.9
v	43	R	4.3
w	47	S	4.7
х	51	Т	5.1
Y	56	U	5.6
Z	62	v	6.2
3	68	w	6.8
4	75	Х	7.5
7	82	Y	8.2
9	91	Z	9.1
Color	Multiplier	Second Number	Multiplier
Orange	0.1	0	1
Black	1	1	10
Green	10	2	100
Blue	100	3	1000
Violet	1000	4	10,000
Red	10,000	5	100,000

Table 8-2 CHIP INDUCTOR IDENTIFICATION



8.6.5 CHIP TRANSISTORS AND DIODES

Surface mounted transistors and diodes are identified by a special number that is shown in a table on Section 10.

8.7 BERYLLIUM PRODUCT WARNING

Q501, Q502, Q503, R519, R538 and R668 in the Power Amplifier contain Beryllium (BeO). Inhalation of dust or fumes may cause serious chronic lung disease. Refer to the Material Safety Data Sheets for further details.

8.8 GRAFOIL REPLACEMENT PROCEDURE

When replacing a device that uses Grafoil for the thermal interface, the Grafoil must be replaced. The old Grafoil must be completely removed from the heatsink. To avoid scuffing the heatsink a plastic scraper (e.g. tuning tool) should be used to remove the old Grafoil.

SERVICING

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January 1997 Part No. 001-2004-200

SECTION 9 PARTS LIST

SYMBOI NUMBEI		PART NUMBER	SYMBO NUMBE	_	PART <u>NUMBER</u>
v	TKING VX UHF 110W REPI	EATER	C 005	1000 pF ±20% 1kV feedthru	510-3149-102
•	PART NO. NR2-20X4-21		C 006	1000 pF ±20% 1kV feedthru	510-3149-102
			C 007	1000 pF ±20% 1kV feedthru	510-3149-102
A 003	400-430 MHz PA/RFIB assem	023-2034-932	C 008	1000 pF ±20% 1kV feedthru	510-3149-102
A 003	430-470 MHz PA/RFIB assem	023-2044-932	C 009	1000 pF ±20% 1kV feedthru	510-3149-102
A 003	475-512 MHz PA/RFIB assem	023-2054-932	C 010	1000 pF ±20% 1kV feedthru	510-3149-102
A 006	400-430 MHz Rx/Tx assembly	023-2034-836	C 011	1000 pF ±20% 1kV feedthru	510-3149-102
A 006	430-470 MHz Rx/Tx assembly	023-2044-836	C 012	1000 pF ±20% 1kV feedthru	510-3149-102
A 006	475-512 MHz Rx/Tx assembly	023-2054-836	C 013	1000 pF ±20% 1kV feedthru	510-3149-102
A 010	2000 series power supply	023-2000-800			
			C 527	9.1 pF ±5% NPO 1206 chip	510-3602-919
HW001	6-32 machine panhead	575-1606-012		(400-430 MHz)	
			C 528		510-0220-470
MP033	PA hold down bracket	017-2210-032		(400-430 MHz)	
				39 pF ±5% 250V mica	510-0220-390
	Main Processor Card assem**	023-2000-310		(430-512 MHz)	
	Main Audio Card assem**	023-2000-320	C 529	•	510-0220-470
	Interface Alarm Card assem**	023-2000-350		(400-430 MHz)	510 0000 000
PA004	Repeater enclosure assembly	023-2000-200		39 pF ±5% 250V mica	510-0220-390
*** * * * *		507 1001 012	0.541	(430-512 MHz)	610 0000 600
W 013	AC power cord 6' 7"	597-1001-013	C 541	1	510-0220-680
**D	ing A lighting Engineering au	therization to		(400-430 MHz) 43 pF ±5% 250V mica	510-0220-430
•	ires Application Engineering au	uiorization to		(430-512 MHz)	310-0220-430
purchas	e.		C 542	•	510-0220-680
			C 3-2	(400-430 MHz)	310 0220 000
				43 pF ±5% 250V mica	510-0220-430
				(430-512 MHz)	
			C 543	•	510-0220-180
110V	V UHF REPEATER PA/RFIB	MODULE		(400-430 MHz)	
	PART NO. 023-20X4-93	2		22 pF ±5% 250V mica	510-0220-220
				(430-470 MHz)	
A 002	403-470 MHz 175W circulator	585-0590-006		16 pF ±5% 250V mica	510-0220-160
A 002	470-524 MHz 175W circulator	585-0590-007		(475-512 MHz)	
A 004	PA - Rx/Tx 20-cond ribbon	023-2000-190	C 546	9.1 pF hi Q .110 cube	510-3663-919
A 005	PA - Rx/Tx 20-cond ribbon	023-2000-190		(400-430 MHz)	
A 008	7.25" cable N-BNC	597-3003-292	C 547	47 pF ±5% 250V mica	510-0220-470
A 009	PA RF input coax assembly	597-3002-031		(400-430 MHz)	
A 011	UHF LPF Rptr to Final	023-2004-600		51 pF ±5% 250V mica	510-0220-510
				(430-512 MHz)	
C 001	1000 pF ±20% 1kV feedthru	510-3149-102	C 548	•	510-0220-470
C 002	1000 pF ±20% 1kV feedthru	510-3149-102		(400-430 MHz)	
C 003	1000 pF ±20% 1kV feedthru	510-3149-102		51 pF ±5% 250V mica	510-0220-510
C 004	1000 pF ±20% 1kV feedthru	510-3149-102		(430-512 MHz)	
			l		

SYMBO NUMBI		PART NUMBER	SYMBO NUMBI	· 	PART NUMBER
C 560	68 pF ±5% 250V mica (400-430 MHz)	510-0220-680	C 603	11 pF ±5% NPO 1206 chip (400-430 MHz)	510-3602-110
	82 pF ±5% 250V mica (430-470 MHz)	510-0220-820	C 604	12 pF hi Q .110 cube (400-430 MHz)	510-3663-120
	47 pF ±5% 250V mica (475-512 MHz)	510-0220-470	C 605	12 pF hi Q .110 cube (400-430 MHz)	510-3663-120
C 561	68 pF ±5% 250V mica (400-430 MHz)	510-0220-680	EP500	Jumper RF power detect	016-2228-015
	82 pF ±5% 250V mica (430-470 MHz)	510-0220-820		3 5/8-24 x 0.094 hex nut NPB	560-9079-028
	47 pF ±5% 250V mica (475-512 MHz)	510-0220-470	HW004	4 5/8 x 0.02 lockwasher int CPS	
C 562	18 pF ±5% 250V mica (400-430 MHz)	510-0220-180	J 001 J 002	2-pin lock receptacle #22 2-pin lock receptacle #22	515-9032-232 515-9032-232
	22 pF ±5% 250V mica (430-470 MHz)	510-0220-220	L 501	3T 0.250 ID air core	542-0020-093
	10 pF ±5% 250V mica (475-512 MHz)	510-0220-100	L 502 L 503	3T 0.250 ID air core 3T 0.250 ID air core	542-0020-093 542-0020-093
C 565	(400-430 MHz)	510-3663-919	PA001	110W PA mechanical assem	023-2004-732
C 568	47 pF ±5% 250V mica (400-430 MHz)	510-0220-470		RF Interface board assembly 110W 400-430 MHz PA	023-2008-110 023-2034-500
	51 pF ±5% 250V mica (430-512 MHz)	510-0220-510		110W 430-470 MHz PA 110W 470-512 MHz PA	023-2044-500 023-2054-500
C 569	47 pF ±5% 250V mica (400-430 MHz)	510-0220-470		UHF Fwd/Rev Power Detect	023-2004-660
0.670	51 pF ±5% 250V mica (430-512 MHz)	510-0220-510	Q 502*	100W UHF RF power amp	576-0006-119 576-0006-119
C 579	68 pF ±5% 250V mica (400-430 MHz)	510-0220-680	Q 503*	100W UHF RF power amp	576-0006-119
	82 pF ±5% 250V mica (430-470 MHz) 47 pF ±5% 250V mica	510-0220-820 510-0220-470		100 ohm 20W flange mount	569-5001-001
C 580	(475-512 MHz) 68 pF ±5% 250V mica	510-0220-680		100 ohm 100W flange mount 50 ohm 250W flange mount	569-5001-002 569-5001-003
C 380	(400-430 MHz) 82 pF ±5% 250V mica	510-0220-820	U 501	13W pwr mod 430-470 MHz 13W pwr mod 470-512 MHz	544-4001-065 544-4001-068
	(430-470 MHz) 47 pF ±5% 250V mica	510-0220-470	RI	EPEATER ENCLOSURE ASS	
C 581	(475-512 MHz) 18 pF ±5% 250V mica	510-0220-180	AC.	PART NO. 023-2000-20	
	(400-430 MHz) 22 pF ±5% 250V mica	510-0220-220	A 004 A 005	Shelf power harness assembly High speed data bus harness	023-2000-165 023-2000-170
	(430-470 MHz) 10 pF ±5% 250V mica	510-0220-100	A 006 A 007	Input/Output harness assembly Alarm harness assembly	
	(475-512 MHz)		A 008 A 009	RF input harness assembly Controller backplane card	023-2000-185 023-2000-210

^{*} DANGER Beryllium Product. Inhalation of dust or fumes may cause serious chronic lung disease.

SYMBO NUMBE		PART NUMBER	SYMBO NUMBE		PART NUMBER
A 010	External connector board	023-2000-220	MP025	Card guide 4.5"	574-9015-006
A 011	Power supply filter	023-2000-250		PA conn floating plate	017-2226-020
11011	Tower supply Times	025-2000-250		Flexible grommet	574-0001-025
CH017	Chassis	017-2210-080		Flexible grommet	574-0001-025
CIIOI	Cilassis	017-2210-000		Spacer	013-1723-228
EP001	Ferrite bead	517-2002-008		Spacer	013-1723-228
	Ferrite bead	517-2002-009		Dowel pin guide	013-1723-229
	3/8" heat shrink tubing	042-0241-556	IVII UJZ	Dower pin guide	015-1725-250
	3/8" heat shrink tubing	042-0241-556	NP001	Nameplate E.F. Johnson	559-5861-163
1111/01/	2 C 22	575 1606 014			
	3 6-32 machine panhead ZPS	575-1606-014		TRANSCEIVER MECHAN	
	4 6-32 panhead philips ZPS	575-1606-012		PART NO. 023-2000-20	15
	6 8-32 panhead philips ZPS	575-1608-012	CITOSO		
	7 10-32 machine panhead ZPS	575-1610-016	CH252	Transceiver housing	015-0902-010
	8 6-19 panhead philips ZPS	575-5606-008	EDOSO	0.002 OD DT 1211 1 .	554 0000 004
	9 6-32 flathead philips BZPS	575-8206-012	EP252	0.093 OD RF shield gasket	574-3002-036
	0 6-32 x 0.094 nut 1 8-32 socket head shield screw	560-1106-010	1133/27	700	575 0006 010
	2 8 x 0.032 flat washer NPB	575-9078-106 596-2408-012		2 6-32 pan torx ZPS	575-0006-010
	3 #10 flat washer NPB	596-1410-016	ПW2/3	3 6-32 machine panhead ZPS	575-1606-016
_	1 1/2" cable clamp	572-0001-007	MD252	Transceiver deck cover	015 0003 015
	Ratcheting flat wire	572-0011-005	IVIF 233	Transcerver deck cover	015-0902-015
	Floating connector shield	018-1007-028	(CONTROLLER BACKPLAN	E CADD
	7 Floating connector cushion	018-1007-028	•	PART NO. 023-2000-21	=
	3 7/16" cable clamp	572-0001-006		1 AN1 110. 025-2000-21	U
	Speed nut 0.093 stud	537-0002-004	F 001	4A 250V subminiature fuse	534-0017-020
	0 4-40 socket hd shldr screw	575-9078-105	F 002	4A 250V subminiature fuse	534-0017-020
	Adhesive lens	574-3002-115	F 003	1A 250V subminiature fuse	534-0017-014
HW032	2 6-32 machine panhead ZPS	575-1606-024			
	3 6 x 0.018 int lockwasher	596-1106-009	FH001	Fuse holder	534-0017-001
HW036	5 0.75 OD x 0.437 high	574-1004-003	FH002	Fuse holder	534-0017-001
	_		FH003	Fuse holder	534-0017-001
J 010	Banana jack assembly .166	108-2302-621			
J 011	Banana jack assembly .166	108-2303-621	HW012	Polarizing key box cont	515-7109-010
J 012	Banana jack assembly .166	108-2301-621			
			J 001	34 pin latch ejection header	515-9031-400
	PA floating connector bracket	017-2210-099	J 002	34 pin latch ejection header	515-9031-400
	8-32 x 1.15 spacer	013-1723-221			
	Guide pin shield	013-1723-220		Round swage spacer 0.5"	312-2483-216
	Chassis top cover	017-2210-070	MP002	Round swage spacer 0.75"	312-2483-224
	Door lock rod	013-1723-225			
	Mounting ears	017-2210-085	P 001	64-pin DIN female straight	515-7082-201
	Door lock cam	017-2210-110	P 002	32-pin DIN female straight	515-7082-200
	Front door lens	032-0758-025	P 003	64-pin DIN female straight	515-7082-201
	PA slide	032-0758-015	P 004	32-pin DIN female straight	515-7082-200
	Front door	032-0758-020	P 005	64-pin DIN female straight	515-7082-201
MP024	Slide lock cam	537-9007-012	P 006	32-pin DIN female straight	515-7082-200

SYMBO NUMBE		PART NUMBER	SYMBO NUMBI		PART NUMBER
P 007	64-pin DIN female straight	515-7082-201	C 117	1000 μF 50V axial low temp	510-4350-102
P 008	32-pin DIN female straight	515-7082-200	C 119	.1 μF ±10% X7R 1206 chip	510-3606-104
P 009	32-pin DIN female straight	515-7082-200	C 120	.1 μF ±10% X7R 1206 chip	510-3606-104
P 010	26-pin locking straight header	1	C 125	.01 μ F ±10% X7R 1206 chip	510-3606-103
P 011	6-pin friction lock conn	515-9031-205	C 126	.018 μ F ±10% X7R 0805 chip	
P 012	64-pin DIN female straight	515-7082-201	C 130	.1 μF ±10% X7R 1206 chip	510-3606-104
P 013	32-pin DIN female straight	515-7082-200	C 132	.001 µF ±5% NPO 1206 chip	510-3602-102
P 014	64-pin DIN female straight	515-7082-201	C 135	.001 μF ±5% NPO 1206 chip	510-3602-102
P 015	32-pin DIN female straight	515-7082-200	C 138	.001 µF ±5% NPO 1206 chip	510-3602-102
P 016	64-pin DIN female straight	515-7082-201	C 141	.001 µF ±5% NPO 1206 chip	510-3602-102
P 017	32-pin DIN female straight	515-7082-200	C 143	.1 μF ±10% X7R 1206 chip	510-3606-104
P 018	64-pin DIN female straight	515-7082-201	C 149	.1 μF ±10% X7R 1206 chip	510-3606-104
			C 150	.001 μF ±5% NPO 1206 chip	510-3602-102
PC001	PC board	035-2000-210		,	
			CR101	Switching SOT-23	523-1504-002
	EXTERNAL CONNECTOR I	BOARD		3.9V zener SOT-23	523-2016-399
	PART NO. 023-2000-22	0	CR104	4.7V zener SOT-23	523-2016-479
			CR107	5.1V zener SOT-23	523-2016-519
HW00	1 6-32 ss pem fastener	560-9106-010	CR108	5.1V zener SOT-23	523-2016-519
HW002	2 Polarizing key box cnt	515-7109-010	CR109	5.1V zener SOT-23	523-2016-519
	- '		CR110	5.1V zener SOT-23	523-2016-519
J 001	26-pos terminal block PC mt	515-7110-426	CR111	Dual switching common-cath	523-1504-022
J 002	34-pos terminal block PC mt	515-7110-434			
J 003	34-pos latch ejection header	515-9031-400	EP101	Terminal lug 2104-06	586-0005-106
			EP102	Terminal lug 2104-06	586-0005-106
P 001	26-pin locking straight header	515-9031-397	EP103	Q	586-0005-106
			EP104		586-0005-106
PC001	PC board	035-2000-220	EP105	Terminal lug 2104-06	586-0005-106
	RF INTERFACE BOAF	SD O	F 101	2A 250V AC sub-min	534-0017-017
	PART NO. 023-2008-11	0	F 102	2A 250V AC sub-min	534-0017-017
C 101	.1 μF ±10% X7R chip	510-3606-104	FH101	Fuse holder PC mount	534-1017-001
C 102	2.2 μF 20V tantalum SMD	510-2626-229		Fuse holder PC mount	534-1017-001
C 103	4.7 µF 16V tantalum SMD	510-2625-479			
C 104	.1 μF ±10% X7R 1206 chip	510-3606-104	HW10:	5 Polarizing key box cnt	515-7109-010
C 105	39 pF ±5% NPO 1206 chip	510-3602-390		6 Polarizing key box cnt	515-7109-010
C 107	2.2 μF 20V tantalum SMD	510-2626-229		7 6-32 mach pan head philips	575-1606-012
C 108	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183		• •	
C 109	.001 μF ±5% NPO 1206 chip	510-3602-102	J 101	36-pin right angle radial	515-0511-001
C 110	1 μF ±10% X7R 1206 chip	510-3606-104	J 102	20-pin straight low profile	515-9031-376
C 111	$.047 \mu F \pm 10\% X7R 1206 chip$	510-3606-473	J 103	20-pin straight low profile	515-9031-376
C 112	1 μF 35V tantalum SMD	510-2628-109	J 104	4-pin right angle header	515-9035-004
C 113	.047 μF ±10% X7R 1206 chip	510-3606-473		- -	
C 114	1 μF 35V tantalum SMD	510-2628-109	L 101	3 μH filter choke PC mount	542-5007-031
C 115	.047 μF ±10% X7R 1206 chip	510-3606-473			
C 116	.01 μF ±10% X7R 1206 chip	510-3606-103	MP101	PA connector mounting shield	032-0758-028
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SYMBO NUMBE		PART NUMBER	SYMBO		PART
MUMBE	SK DESCRIPTION	NUMBER	NUMBE	R DESCRIPTION	NUMBER
P 101	Banana plug panel mount	108-0753-001	R 086	270k ohm ±5% 1206 SMD	569-0115-274
P 102	Banana plug panel mount	108-0753-001	R 087	1k ohm ±1% 1206 SMD	569-0111-301
P 103	Banana plug panel mount	108-0753-001	R 088	1k ohm ±1% 1206 SMD	569-0111-301
P 104	Banana plug panel mount	108-0753-001	R 089	470 ohm ±5% 1206 SMD	569-0115-471
P 105	Banana plug panel mount	108-0753-001	R 090	270k ohm ±5% 1206 SMD	569-0115-274
			R 091	1k ohm ±1% 1206 SMD	569-0111-301
PC100	PC board	035-2008-110	R 092	1k ohm ±1% 1206 SMD	569-0111-301
			R 093	470 ohm ±5% 1206 SMD	569-0115-471
Q 101	Si PNP low noise SOT-23	576-0003-657	R 094	5.1k ohm ±5% 1206 SMD	569-0115-512
Q 102	Si NPN SOT-23	576-0003-600	R 095	1k ohm ±5% 1206 SMD	569-0115-102
Q 103	PNP D-pak power	576-0002-603	R 100	100 ohm ±5% 1206 SMD	569-0115-101
Q 104	Si NPN low noise SOT-23	576-0003-657	R 101	1k ohm ±5% 1206 SMD	569-0115-102
Q 105	Si NPN amp SOT-23	576-0003-658	R 102	2.7k ohm ±5% 1206 SMD	569-0115-272
Q 106	Si NPN SOT-23	576-0003-600	R 103	270k ohm ±5% 1206 SMD	569-0115-274
Q 107	PNP D-pak power	576-0002-603	R 104	270k ohm ±5% 1206 SMD	569-0115-274
Q 108	Si NPN gen purp sw/amp	576-0001-300	R 105	2.7k ohm ±5% 1206 SMD	569-0115-272
				10k ohm ±5% 1206 SMD	569-0115-103
R 045	100 ohm ±5% 1206 SMD	569-0115-101	1	560 ohm ±5% 1206 SMD	569-0115-561
R 046	100 ohm ±5% 1206 SMD	569-0115-101	1	2.7k ohm ±5% 1206 SMD	569-0115-272
R 048	7.5k ohm ±5% 1206 SMD	569-0115-752		1k ohm ±5% 1206 SMD	569-0115-102
R 049	1.5k ohm ±5% 1206 SMD	569-0115-152	1	5.1k ohm ±5% 1206 SMD	569 - 0115-512
R 050	4.99k ohm ±1% 1206 SMD	569-0111-368		330 ohm ±5% 1206 SMD	569 - 0115-331
R 051	100 ohm ±5% 1206 SMD	569-0115-101		1k ohm ±5% 1206 SMD	569-0115-102
R 052	10k ohm ±5% 1206 SMD	569-0115-103	1	1.8k ohm ±5% 1206 SMD	569-0115-182
R 053	10k ohm ±5% 1206 SMD	569-0115-103		1.8k ohm ±5% 1206 SMD	569-0115-182
R 054 R 055	10k ohm ±5% 1206 SMD	569-0115-103	ı	470 ohm ±5% 1206 SMD	569-0115-471
R 056	2.7k ohm ±5% 1206 SMD 470k ohm ±5% 1206 SMD	569-0115-272		470 ohm ±5% 1206 SMD	569-0115-471
R 057	10k ohm ±5% 1206 SMD	569-0115-474	1	270 ohm ±5% 1206 SMD	569-0115-271
R 059	10k ohm ±5% 1206 SMD	569-0115-103 569-0115-103		20k ohm ±1% 1206 SMD	569-0111-430
R 061	43k ohm ±5% 1206 SMD	569-0115-433		20k ohm ±1% 1206 SMD	569-0111-430
R 063	10k ohm ±5% 1206 SMD	569-0115-103		10k ohm ±1% 1206 SMD	569-0111-401
R 064	43k ohm ±5% 1206 SMD	569-0115-433		20k ohm ±1% 1206 SMD 10k ohm ±1% 1206 SMD	569-0111-430
R 065	10k ohm ±5% 1206 SMD	569-0115-103	1	20k ohm ±1% 1206 SMD	569-0111-401
R 066	43k ohm ±5% 1206 SMD	569-0115-433	I	10k ohm ±1% 1206 SMD	569-0111-430 569-0111-401
R 073	10k ohm ±5% 1206 SMD	569-0115-103	ľ	20k ohm ±1% 1206 SMD	569-0111-430
R 074	1k ohm ±5% 1206 SMD	569-0115-102	l	10k ohm ±1% 1206 SMD	569-0111-401
R 075	1k ohm ±5% 1206 SMD	569-0115-102		20k ohm ±1% 1206 SMD	569-0111-430
R 076	5k ohm single turn trimmer	562-0112-502		10k ohm ±1% 1206 SMD	569-0111-401
	270k ohm ±5% 1206 SMD	569-0115-274		20k ohm ±1% 1206 SMD	569-0111-430
R 079	1k ohm ±1% 1206 SMD	569-0111-301		10k ohm ±1% 1206 SMD	569-0111-401
R 080	1k ohm ±1% 1206 SMD	569-0111-301		20k ohm ±1% 1206 SMD	569-0111-430
R 081	470 ohm ±5% 1206 SMD	569-0115-471		10k ohm ±1% 1206 SMD	569-0111-401
	270k ohm ±5% 1206 SMD	569-0115-274		20k ohm ±1% 1206 SMD	569-0111-430
R 083	1k ohm ±1% 1206 SMD	569-0111-301		20k ohm ±1% 1206 SMD	569-0111-430
	1k ohm ±1% 1206 SMD	569-0111-301		22k ohm ±5% 1206 SMD	569-0115-223
	470 ohm ±5% 1206 SMD	569-0115-471		22k ohm ±5% 1206 SMD	569-0115-223
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SYMBO NUMBE		PART NUMBER	SYMBO NUMBE		PART NUMBER
R 137	22k ohm ±5% 1206 SMD	569-0115-223	R 185	22k ohm ±5% 1206 SMD	569-0115-223
R 138	22k ohm ±5% 1206 SMD	569-0115-223	R 186	10k ohm ±5% 1206 SMD	569-0115-103
R 139	10k ohm ±5% 1206 SMD	569-0115-103	R 187	15k ohm ±5% 1206 SMD	569-0115-153
R 140	10k ohm ±5% 1206 SMD	569-0115-103	R 188	22 ohm ±5% 1206 SMD	569-0115-220
R 141	10k ohm ±5% 1206 SMD	569-0115-103	R 189	22 ohm ±5% 1206 SMD	569-0115-220
R 141	10k ohm ±5% 1206 SMD	569-0115-103	R 190	22 ohm ±5% 1206 SMD	569-0115-220
R 143	22k ohm ±5% 1206 SMD	569-0115-223	R 191	22 ohm ±5% 1206 SMD	569-0115-220
R 144	22k ohm ±5% 1206 SMD	569-0115-223	R 192	22k ohm ±5% 1206 SMD	569-0115-223
R 145	22k ohm ±5% 1206 SMD	569-0115-223	R 193	10k ohm ±5% 1206 SMD	569-0115-103
R 146	22k ohm ±5% 1206 SMD	569-0115-223	R 194	15k ohm ±5% 1206 SMD	569-0115-153
R 147	22k ohm ±5% 1206 SMD	569-0115-223	R 197	10k ohm ±5% 1206 SMD	569-0115-103
R 148	22k ohm ±5% 1206 SMD	569-0115-223	R 198	10k ohm ±5% 1206 SMD	569-0115-103
R 149	22k ohm ±5% 1206 SMD	569-0115-223	R 199	10k ohm ±5% 1206 SMD	569-0115-103
R 151	10k ohm ±5% 1206 SMD	569-0115-103		1011 01111 12 70 12 00 DIVID	30% 0110 103
R 152	10k ohm ±5% 1206 SMD	569-0115-103	U 101	+5V regulator 78L05	544-2603-039
R 153	22k ohm ±5% 1206 SMD	569-0115-223	U 102	Dual op amp SOIC LM2904	544-2019-004
R 154	22k ohm ±5% 1206 SMD	569-0115-223	U 103	8-bit shift register MC14094	544-3016-094
R 155	22k ohm ±5% 1206 SMD	569-0115-223	U 104	8-chan mux 4051	544-3016-051
R 156	22k ohm ±5% 1206 SMD	569-0115-223	U 105	8-chan mux 4051	544-3016-051
R 157	10k ohm ±5% 1206 SMD	569-0115-103	U 106	8-chan mux 4051	544-3016-051
R 158	10k ohm ±5% 1206 SMD	569-0115-103	U 107	Dual op amp SOIC LM2904	544-2019-004
R 159	10k ohm ±5% 1206 SMD	569-0115-103	U 108	Dual op amp SOIC LM2904	544-2019-004
R 160	22k ohm ±5% 1206 SMD	569-0115-223	U 109	Quad op amp SOIC LM224	544-2020-014
R 161	22k ohm ±5% 1206 SMD	569-0115-223	U 110	Hex non-inv buffer 4050B	544-3016-050
R 162	22k ohm ±5% 1206 SMD	569-0115-223	U 111	Dual op amp SO-8 LM2904	544-2019-004
R 163	22k ohm ±5% 1206 SMD	569-0115-223	U 112	Quad op amp SOIC LM224	544-2020-014
R 164	22k ohm ±5% 1206 SMD	569-0115-223			
R 165	22k ohm ±5% 1206 SMD	569-0115-223			
R 166	22k ohm ±5% 1206 SMD	569-0115-223			
R 167	1k ohm ±1% 1206 SMD	569-0111-301			
R 168	10k ohm ±5% 1206 SMD	569-0115-103		REPEATER RX/EX MOD	
R 169	270k ohm ±5% 1206 SMD	569-0115-274		PART NO. 023-2034-83	36
R 170	1k ohm ±1% 1206 SMD	569-0111-301			
R 171	511 ohm ±1% 1206 SMD	569-0111-269		1 5/8-24 x 0.094 hex nut	560-9079-028
R 172	1k ohm ±5% 1206 SMD	569-0115-102		2 5/8 x 0.02 int lockwasher CPS	
R 173	3.3k ohm ±5% 1206 SMD	569-0115-332		10-32 machine panhead ZPS	575-1610-020
R 174	8.2k ohm ±5% 1206 SMD	569-0115-822	HW250) #10 flat washer ZPS	596-1410-016
R 175	8.2k ohm ±5% 1206 SMD	569-0115-822	1 (DOOO	T : 1	010 0010 105
R 176	8.2k ohm ±5% 1206 SMD	569-0115-822	MP200	Transceiver pad	017-2210-105
R 177	8.2k ohm ±5% 1206 SMD	569-0115-822	D 4 000	T	000 0000 005
R 178	8.2k ohm ±5% 1206 SMD	569-0115-822	PA002		023-2000-205
R 179	10k ohm ±5% 1206 SMD	569-0115-103		Receiver 400-430 MHz	023-2034-270
R 180	10k ohm ±5% 1206 SMD	569-0115-103		Receiver 430-470 MHz	023-2044-270
R 181	22 ohm ±5% 1206 SMD	569-0115-220		Receiver 470-512 MHz	023-2034-270
R 182	22 ohm ±5% 1206 SMD	569-0115-220		Exciter 400-430 MHz	023-2054-400
R 183	22 ohm ±5% 1206 SMD	569-0115-220		Exciter 430-470 MHz	023-2044-400
R 184	22 ohm ±5% 1206 SMD	569-0115-220	PAUUS	Exciter 470-512 MHz	023-2054-400
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SYMBO NUMBE		PART <u>NUMBER</u>	SYMBO NUMBI		PART NUMBER
RECEIVE VCO 403-470 MHz		MHz	R 805	10 ohm ±5% 0805 chip	569-0105-100
	PART NO. 023-2044-80	00	R 806	5.1k ohm ±5% 0805 chip	569-0105-512
			R 807	6.2k ohm ±5% 0805 SMD	569-0105-622
C 803	0.6-4.5 pF vertical SMT	512-0006-011	R 808	200 ohm ±5% 1206 SMD	569-0115-201
C 804		510-3601-159			
	(400-470 MHz)			12.5/25 kHz RECEIV	ER
C 804	1.2 pF ±5% NPO 0805 chip	510-3601-129	P	ART NO. 023-2034-270 (400	
	(470-512 MHz)			ART NO. 023-2044-270 (430	•
C 805	68 pF ±5% NPO 0805 chip	510-3601-680		ART NO. 023-2054-270 (470	,
	0.5 pF ±0.1 pF high Q	510-3710-508			·,
	7.5 pF ±5% NPO 0805 chip	510-3601-759	A 201	RF input coax	023-2000-161
C 808	7.5 pF ±5% NPO 0805 chip	510-3601-759	A 203	Top Shield	023-2000-199
C 809	68 pF ±5% NPO 0805 chip	510-3601-680	A 401	VCO 400-430 MHz	023-2034-800
C 810	68 pF ±5% NPO 0805 chip	510-3601-680		VCO 430-470 MHz	023-2044-800
C 811	•	510-3601-680		VCO 470-512 MHz	023-2054-800
	15 μF 20V tantalum SMD	510-2626-150		, , , , , , , , , , , , , , , , , , ,	023 203 1 000
C 813	•	510-3601-680	C 101	5.6 pF ±5% NPO 1206 chip	510-3602-569
C 814	68 pF ±5% NPO 0805 chip	510-3601-680		(400-430 MHz)	010 3002 303
	, , , , , , , , , , , , , , , , , , ,			7.5 pF ±5% NPO 1206 chip	510-3602-759
CR801	Varactor SOD-323 BB535	523-5005-022		(403-470 MHz)	010 0002 703
	Varactor SOD-323 BB535	523-5005-022		6.8 pF ±5% NPO 1206 chip	510-3602-689
				(470-512 MHz)	010 3002 009
J 001	2-pin PC mount wafer	515-9031-101	C 103	12 pF ±5% NPO 1206 chip	510-3602-120
J 002	2-pin PC mount wafer	515-9031-101	C 104	•	510-3602-759
J 003	4-pin PC mount wafer	515-9031-103		(400-430 MHz)	210 2002 100
	•			6.2 pF ±5% NPO 1206 chip	510-3602-629
L 801	180 nH ±10% 0805 SMD	542-9003-188		(403-470 MHz)	
	(400-430 MHz)			4.7 pF ±5% NPO 1206 chip	510-3602-479
L 801	150 nH ±10% 0805 SMD	542-9003-158		(470-512 MHz)	
	(430-512 MHz)		C 105	4.7 μF 16V tantalum SMD	510-2625-479
L 802	180 nH ±10% 0805 SMD	542-9003-188	C 106	150 pF ±5% NPO 1206 chip	510-3602-151
	(400-430 MHz)		C 107	4.7 µF 16V tantalum SMD	510-2625-479
L 802	150 nH ±10% 0805 SMD	542-9003-158	C 108	150 pF ±5% NPO 1206 chip	510-3602-151
	(430-512 MHz)		C 109	.001 µF ±5% NPO 1206 chip	510-3602-102
L 803	150 nH ±10% 0805 SMD	542-9003-158	C 110	$.001 \mu F \pm 5\%$ NPO 1206 chip	510-3602-102
L 804	150 nH ±10% 0805 SMD	542-9003-158	C 111	•	510-2625-479
L 805	12mm resonator SMD	542-9006-004	C 112	150 pF ±5% NPO 1206 chip	510-3602-151
			C 113	150 pF ±5% NPO 1206 chip	510-3602-151
MP400	UHF VCO shield	017-2226-044	C 114	6.2 pF ±5% NPO 1206 chip	510-3602-629
				(400-430 MHz)	
PC800	PC board	035-2044-800		6.8 pF ±5% NPO 1206 chip	510-3602-689
				(403-512 MHz)	
Q 801	Si NPN gen purp switch/amp	576-0001-300	C 115	6.8 pF ±5% NPO 1206 chip	510-3602-689
-	NPN UHF low noise SOT-23	576-0003-636		(400-430 MHz)	
-				7.5 pF ±5% NPO 1206 chip	510-3602-759
	10 1 158/ 0005 11	560 0105 100		-	
R 803	10 ohm ±5% 0805 chip	569-0105-100		(403-512 MHz)	

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SYMB(PART NUMBER	SYMBO NUMB		PART NUMBER
C 132	10 pF ±5% NPO 1206 chip	510-3602-100	C 211	.01 μF ±10% X7R chip	510-3606-103
C 133	68 pF ±5% NPO 1206 chip	510-3602-680	C 212		510-3602-390
C 134	.018 µF ±10% X7R 0805 chip	510-3605-183	C 213	-	510-3602-479
C 135	68 pF ±5% NPO 1206 chip	510-3602-680	C 214		510-1602-001
C 136	.018 µF ±10% X7R 0805 chip	510-3605-183	C 215	6.8 pF ±5% NPO 1206	510-3602-689
C 137	68 pF ±5% NPO 1206 chip	510-3602-680	C 216	•	510-3602-390
C 138	68 pF ±5% NPO 1206 chip	510-3602-680	C 217	3.9 pF ±5% NPO 1206 chip	510-3602-399
C 139	68 pF ±5% NPO 1206 chip	510-3602-680	C 218		510-3606-103
C 140	68 pF ±5% NPO 1206 chip	510-3602-680	C 219	.001 μF ±5% NPO 1206 chip	510-3602-102
C 141	.001 μF ±5% NPO 1206 chip	510-3602-102	C 220	.1 μF ±10% X7R chip	510-3606-104
C 142	68 pF ±5% NPO 1206 chip	510-3602-680	C 221	.1 μF ±10% X7R chip	510-3606-104
C 143	.1 μF ±10% X7R 1210	510-3607-104	C 222	.1 μF ±10% X7R chip	510-3606-104
C 144	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	C 223	.001 μF ±5% NPO 1206 chip	510-3602-102
C 145	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	C 225	.001 μF ±5% NPO 1206 chip	510-3602-102
C 146	7.5 pF ±5% NPO 1206 chip	510-3602-759	C 226	.001 μF ±5% NPO 1206 chip	510-3602-102
C 147	22 pF ±5% NPO 1206 chip	510-3602-220	C 227	4.7 pF ±5% NPO 1206	510-3602-479
C 148	4.7 μF 16V tantalum SMD	510-2625-479	C 228	27 pF ±5% NPO 1206 chip	510-3602-270
C 149	68 pF ±5% NPO 1206 chip	510-3602-680	C 236	8.2 pF ±5% NPO 1206	510-3602-829
C 150	.001 μF ±5% NPO 1206 chip	510-3602-102	C 237	39 pF ±5% NPO 1206	510-3602-390
C 151	68 pF ±5% NPO 1206 chip	510-3602-680	C 238	4.7 pF ±5% NPO 1206	510-3602-479
C 152	3.9 pF ±5% NPO 1206 chip	510-3602-399	C 239	1.5-5 pF ceramic SMD	510-1602-001
C 153	5.6 pF ±5% NPO 1206 chip	510-3602-569	C 240	100 pF ±5% NPO 1206 chip	510-3602-101
C 154	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	C 241	6.8 pF ±5% NPO 1206	510-3602-689
C 155	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	C 242	.001 μF ±5% NPO 1206 chip	510-3602-102
C 156	10 pF ±5% NPO 1206 chip	510-3602-100	C 243	.01 μF ±10% X7R 1206 chip	510-3606-103
C 157	68 pF ±5% NPO 1206 chip	510-3602-680	C 244	4.7 pF ±5% NPO 1206	510-3602-479
C 158	1.5 µF 25V tantalum SMD	510-2627-159	C 245	7.5 pF ±5% NPO 1206 chip	510-3602-759
C 159	.001 μF ±5% NPO 1206 chip	510-3602-102	C 246	$.01 \mu F \pm 10\% X7R 1206 chip$	510-3606-103
C 160	68 pF ±5% NPO 1206 chip	510-3602-680	C 247	39 pF ±5% NPO 1206 chip	510-3602-390
C 161	4.7 μF 16V tantalum SMD	510-2625-479	C 248	4.7 pF ±5% NPO 1206	510-3602-479
C 162	5.6 pF ±5% NPO 1206	510-3602-569	C 249	1.5-5 pF ceramic SMD	510-1602-001
C 163		510-3602-829		5.6 pF ±5% NPO 1206 chip	510-3602-569
C 164 C 165	.018 μF ±10% X7R 0805 chip	510-3605-183	C 251	39 pF ±5% NPO 1206	510-3602-390
C 166	1 pF ±5% NPO 1206 chip	510-3602-109	C 252	5.6 pF ±5% NPO 1206 chip	510-3602-569
C 167	.001 μF ±5% NPO 1206 chip	510-3602-102	C 253	$.01 \mu F \pm 10\% X7R 1206 chip$	510-3606-103
C 169	.001 μF ±5% NPO 1206 chip 6.8 pF ±5% NPO 1206	510-3602-102	C 254	.001 μF ±5% NPO 1206 chip	510-3602-102
C 201	10 pF ±5% NPO 1206 chip	510-3602-689	C 255	$.1 \mu\text{F} \pm 10\% \text{X7R}$	510-3606-104
C 202	39 pF ±5% NPO 1206 cmp	510-3602-100	C 256	$.1 \mu\text{F} \pm 10\% \text{X7R}$	510-3606-104
C 202	4.7 pF ±5% NPO 1206	510-3602-390	C 257	.1 μF ±10% X7R	510-3606-104
C 204	1.5-5 pF ceramic SMD	510-3602-479	C 258	.001 μF ±10% X7R 1206	510-3606-102
C 204	39 pF ±5% NPO 1206	510-1602-001	C 260	.001 μF ±10% X7R 1206	510-3606-102
C 203	10 pF ±5% NPO 1206 chip	510-3602-390	C 261	.001 μF ±10% X7R 1206	510-3606-102
C 207	.01 μF ±10% X7R chip	510-3602-100	C 262	4.7 μF 16V tantalum SMD	510-2625-479
C 207	4.7 pF ±5% NPO 1206	510-3606-103	C 263	27 pF ±5% NPO 1206 chip	510-3602-270
C 209	4.7 pr ±3% NPO 1206 .001 μF ±5% NPO 1206 chip	510-3602-479	C 265	100 pF ±5% NPO 1206	510-3602-101
C 210	10 pF ±5% NPO 1206 chip	510-3602-102	C 266	.01 μF ±10% X7R 1206 chip	510-3606-103
C 210	10 br. 70 MLO 1500 cuib	510-3602-100	C 267	4.7 μF 16V tantalum SMD	510-2625-479

SYMB(NUMB)		PART NUMBER	SYMBO NUMBI	-	PART NUMBER
C 268	.01 μF ±10% X7R 1206 chip	510-3606-103	C 416	.1 μF ±10% X7R	510-3606-104
C 269	$.001 \mu F \pm 10\% X7R 1200 cmp$	510-3606-102	C 431	100 pF ±5% NPO 1206 chip	510-3602-104
C 270	5.6 pF ±5% NPO 1206 chip	510-3602-569	C 431	100 pF ±5% NPO 1206 chip	510-3602-101
C 271	220 pF ±5% NPO 1206 chip	510-3602-221	C 433	68 pF ±5% NPO 1206 chip	510-3602-101
C 275	100 pF ±5% NPO 1206 chip	510-3602-101	C 434	.1 μF ±10% X7R	
C 276	.01 μ F ±10% X7R 1206 chip	510-3606-103	C 434	68 pF ±5% NPO 1206 chip	510-3606-104
C 277	4.7 μF 16V tantalum SMD	510-2625-479	C 435	.1 μF ±10% X7R	510-3602-680
C 278	$.01 \mu F \pm 10\% X7R 1206 chip$	510-3606-103	C 430	.1 μF ±10% X7R	510-3606-104 510-3606-104
C 279	.001 μF ±10% X7R 1200 cmp	510-3606-102	C 437	4.7 μF 16V tantalum SMD	510-3606-104
C 280	220 pF ±5% NPO 1206 chip	510-3602-221	C 439	68 pF ±5% NPO 1206 chip	510-2623-479
C 281	220 pF ±5% NPO 1206 chip	510-3602-221	C 440	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183
C 282	5.6 pF ±5% NPO 1206 chip	510-3602-221	C 441	68 pF ±5% NPO 1206 chip	510-3602-680
C 283	120 pF ±5% NPO 1206 chip	510-3602-303	C 442	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183
C 284	390 pF ±5% NPO 1206 chip	510-3602-391	C 443	68 pF ±5% NPO 1206 chip	510-3602-680
C 301	.001 μF ±10% X7R 1206	510-3606-102	C 444	10 pF ±5% NPO 1206 chip	510-3602-080
C 302	1.5 µF 25V tantalum SMD	510-2627-159	C 445	.1 μF ±5% X7R 1206	510-3609-104
C 303	4.7 μF 16V tantalum SMD	510-2625-479	C 446	5.1 pF ±5% NPO 1206 chip	510-3602-519
C 304	4.7 μF 16V tantalum SMD	510-2625-479	C 447	1 μF 16V tantalum SMD	510-2625-109
C 305	.001 μF ±5% NPO 1206 chip	510-3602-102	C 448	1 μF 16V tantalum SMD	510-2625-109
C 306	56 pF ±5% NPO 1206 chip	510-3602-560	C 449	.1 μF ±10% X7R	510-3606-104
C 307	.001 µF ±5% NPO 1206 chip	510-3602-102	C 450	1.5 µF 25V tantalum SMD	510-2627-159
C 308	1.5 µF 25V tantalum SMD	510-2627-159	C 451	.1 μF \pm 10% X7R	510-3606-104
C 309	4.7 µF 16V tantalum SMD	510-2625-479	C 452	10 pF ±5% NPO 1206 chip	510-3602-100
C 310	.001 μF ±5% NPO 1206 chip	510-3602-102	C 454	.001 µF ±5% NPO 1206 chip	510-3602-102
C 311	.001 μF ±5% NPO 1206 chip	510-3602-102	C 455	68 pF ±5% NPO 1206 chip	510-3602-680
C 312	1.5 μF 25V tantalum SMD	510-2627-159	C 456	3.3 pF ±5% NPO 1206 chip	510-3602-339
C 313	.001 μF ±5% NPO 1206 chip	510-3602-102	C 457	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183
C 314	4.7 μF 16V tantalum SMD	510-2625-479	C 458	68 pF ±5% NPO 1206 chip	510-3602-680
C 315	.001 μF ±5% NPO 1206 chip	510-3602-102	C 459	68 pF ±5% NPO 1206 chip	510-3602-680
C 316	1.5 µF 25V tantalum SMD	510-2627-159	C 460	68 pF ±5% NPO 1206 chip	510-3602-680
C 317	4.7 μF 16V tantalum SMD	510-2625-479	C 461	68 pF ±5% NPO 1206 chip	510-3602-680
C 318	.001 μF ±5% NPO 1206 chip	510-3602-102	C 462	68 pF ±5% NPO 1206 chip	510-3602-680
C 401	.01 μF ±10% X7R 1206	510-3606-103	C 463	68 pF ±5% NPO 1206 chip	510-3602-680
C 402	4.7 μF 16V tantalum SMD	510-2625-479	C 464	15 μF 20V tantalum SMD	510-2626-150
C 403	.01 μF ±10% X7R 1206	510-3606-103			
C 404	820 pF ±5% NPO 1206 chip	510-3602-821	CH200	3-cavity helical front end	015-0901-038
C 405	100 pF ±5% NPO 1206 chip	510-3602-101	CH201	3-cavity helical front end	015-0901-038
C 406	.01 μ F ±10% X7R 1206	510-3606-103	CH202	2-cavity helical front end	015-0901-028
C 407	.001 μF ±5% NPO 1206 chip	510-3602-102			
C 408	.01 μF ±5% NPO 1206 chip	510-3602-103	CR101	Switching diode SOT-23	523-1504-002
C 409	.01 μF ±5% NPO 1206 chip	510-3602-103		5.6V zener SOT-23	523-2016-569
C 410	.001 μF ±5% NPO 1206 chip	510-3602-102		5.6V zener SOT-23	523-2016-569
C 411	.1 μF \pm 10% X7R	510-3606-104		Hot carrier diode SOT-23	523-1504-016
C 412	$.1 \mu\text{F} \pm 10\% \text{X7R}$	510-3606-104		Si 9.1V zener SOT-23	523-2016-919
C 413	.01 μF ±10% X7R 1206	510-3606-103	CR402	Dual switching diode SOT-23	523-1504-023
C 414	6.8 μF 35V tantalum SMD	510-2628-689			
C 415	.1 μF ±10% X7R	510-3606-104	EP200	Crystal pin cer insulator mini	010-0345-280
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SYMBO NUMBE		PART NUMBER	SYMBO NUMBE		PART NUMBER	,
	Helical screw	013-1563-001 560-1810-022	L 110	5.125T helical coil (400-430 MHz)	016-1929-161	
	2 Tension lock nut CPS	575-0606-008		4.8125T helical coil	016-1929-158	
	3 6-32 panhead 1/4" taptite	515-7109-010		(430-470 MHz)	010-1727-130	
HW2U	5 Polarizing key box cnt	313-7109-010		4.4375T helical coil	016-1929-155	
7.001	20 to take mela bandan	616 0021 275		(470-512 MHz)	010-1727-133	
J 201	20-pin right angle header	515-9031-375	L 111	4T 22 AWG 0.05 ID SMD	542-0015-004	
J 203	3-pin single inline header	515-7100-003 515-7100-003	LIII	(400-470 MHz)	342-0013-004	
J 204	3-pin single inline header			3T 22 AWG 0.05 ID SMD	542-0015-003	
J 205	3-pin single inline header	515-7100-003		(470-512 MHz)	J 42-00 1J-00J	
L 101	2T 22 AWG 0.05 ID SMD	542-0015-002	L 131	.1 μH SMD inductor	542-9001-108	
2	(400-470 MHz)		L 132	.1 μH SMD inductor	542-9001-108	
	3T 22 AWG 0.05 ID SMD	542-0015-003	L 133	5.6 nH ceramic inductor	542-9003-566	
	(470-512 MHz)		L 134	.068 µH SMD inductor	542-9001-687	
L 102	5.125T helical coil	016-1929-161	L 135	15 nH inductor LL2012 F15N	542-9003-157	
	(400-430 MHz)		L 136	18 nH inductor LL2012 F18N	542-9003-187	
	4.8125T helical coil	016-1929-159	L 137	6.8 nH inductor LL2012 F6N8	542-9003-686	
	(430-470 MHz)		L 138	.068 μH SMD inductor	542-9001-687	
	4.4375T helical coil	016-1929-155	L 139	12 nH inductor LL2012 F12N	542-9003-127	
	(470-512 MHz)		L 140	4.625T helical coil	016-1929-157	
L 103	5.125T helical coil	016-1929-162		(400-430 MHz)		
	(400-430 MHz)			4.375T helical coil	016-1929-153	
	4.8125T helical coil	016-1929-159		(430-470 MHz)		
	(430-470 MHz)			4.0625T helical coil	016-1929-151	
	4.4375T helical coil	016-1929-156		(470-512 MHz)		
	(470-512 MHz)		L 141	4.625T helical coil	016-1929-157	
L 104	5.125T helical coil	016-1929-161		(400-430 MHz)	016 1000 150	
	(400-430 MHz)			4.375T helical coil	016-1929-153	
	4.8125T helical coil	016-1929-158	ļ	(430-470 MHz)	017 1000 151	
	(430-470 MHz)	016 1000 166		4.0625T helical coil	016-1929-151	
	4.4375T helical coil	016-1929-155	7 001	(470-512 MHz)	542-1012-015	
	(470-512 MHz)	542 0015 003	L 201	1 μH ±6% variable inductor	542-9001-828	
L 105	3T 22 AWG 0.05 ID SMD	542-0015-003	L 202	.82 μH SMD inductor	542-1012-015	
* 106	(470-512 MHz)	542 0015 006	L 203	1 μH ±6% variable inductor 1 μH ±6% variable inductor	542-1012-015	
	6T 22 AWG 0.05 ID SMD	542-0015-006 542-0015-006	L 204 L 205	.82 μH SMD inductor	542-9001-828	
L 107	6T 22 AWG 0.05 ID SMD	016-1929-161	L 203	1 μH ±6% variable inductor	542-1012-015	
L 108	5.125T helical coil	010-1929-101	L 200	1 μH ±6% variable inductor	542-1012-015	
	(400-430 MHz)	016-1929-158	L 211	.82 μH SMD inductor	542-9001-828	
	4.8125T helical coil	010-1929-136	L 212	1 μH ±6% variable inductor	542-1012-015	
	(430-470 MHz)	016-1929-155	L 213	l μH ±6% variable inductor	542-1012-015	
	4.4375T helical coil (470-512 MHz)	010-1323-133	L 215	.82 μH SMD inductor	542-9001-828	
T 100	5.125T helical coil	016-1929-162	L 216	1 μH ±6% variable inductor	542-1012-015	
L 109	(400-430 MHz)	010-1/27-102	L 222	.1 μH inductor SMD	542-9001-108	
	4.8125T helical coil	016-1929-159	L 223	.1 μH inductor SMD	542-9001-108	
	(430-470 MHz)	010-1747-107	L 224	.1 μH inductor SMD	542-9001-108	
	4.4375T helical coil	016-1929-156	L 401	.1 μH inductor SMD	542-9001-108	
	(470-512 MHz)	010/1727-130	L 402	.1 µH inductor SMD	542-9001-108	
	(T/0-312 MILE)					

SYMBO NUMBE		PART NUMBER	SYMBO NUMBI		PART NUMBER
L 403	.1 μH inductor SMD	542-9001-108	'R 137	36 ohm ±5% 1206 SMD	569-0115-360
L 404	.1 μH inductor SMD	542-9001-108	R 138	75 ohm ±5% 1206 SMD	569-0115-750
L 405	.1 μH inductor SMD	542-9001-108	R 139	300 ohm ±5% 1206 SMD	569-0115-101
			R 140	18 ohm ±5% 1206 SMD	569-0115-180
MP204	Bottom shield	017-2210-101	R 141	300 ohm ±5% 1206 SMD	569-0115-101
			R 142	270 ohm ±5% 1206 SMD	569-0115-271
P 203	2-pos shorting socket	515-5010-001	R 143	1k ohm ±5% 1206 SMD	569-0115-102
P 204	2-pos shorting socket	515-5010-001	R 144	390 ohm ±5% 1206 SMD	569-0115-391
P 205	2-pos shorting socket	515-5010-001	R 145	240 ohm ±5% 1206 SMD	569-0115-241
			R 146	240 ohm ±5% 1206 SMD	569-0115 - 241
PC200	PC board	035-2004-200	R 147	300 ohm ±5% 1206 SMD	569-0115-101
			R 148	18 ohm ±5% 1206 SMD	569-0115-180
Q 101	NPN .2-2 GHz SO-8 amp	576-0003-604	R 149	300 ohm ±5% 1206 SMD	569 - 0115-101
Q 102	Si PNP low noise SOT-23	576-0003-657	R 150	270 ohm ±5% 1206 SMD	569-0115-271
Q 131	NPN UHF low noise SOT-23	576-0003-636	R 151	1.2k ohm ±5% 1206 SMD	569-0115-122
Q 132	NPN UHF low noise SOT-23	576-0003-636	R 152	270 ohm ±5% 1206 SMD	569-0115-271
Q 133	NPN .2-2 GHz SO-8 amp	576-0003-604	R 153	68 ohm ±5% 1206 SMD	569-0115-680
Q 134	NPN 750 mW UHF/800 MHz	576-0004-098	R 154	68 ohm ±5% 1206 SMD	569-0115-680
Q 201	Si NPN RF amp SOT-23	576-0003-602	R 157	1k ohm ±5% 1206 SMD	569-0115-102
Q 202 Q 203	Si NPN RF amp SOT-23	576-0003-602	R 158	51k ohm ±5% 1206 SMD	569-0115-513
Q 203 Q 204	Si NPN amp Si NPN amp	576-0003-658	R 159	100k ohm ±5% 1206 SMD	569-0115-104
Q 401	Si NPN amp	576-0003-658 576-0003-658	R 160 R 161	10k ohm ±5% 1206 SMD 100k ohm ±5% 1206 SMD	569-0115-103
Q 402	Si NPN amp	576-0003-658	R 201	1.8k ohm ±5% 1206 SMD	569-0115-104
Q 403	Si NPN amp	576-0003-658	R 201	680 ohm ±5% 1206 SMD	569-0115-182 569-0115-681
Q 404	Si NPN amp	576-0003-658	R 203	51 ohm ±5% 1206 SMD	569-0115-510
Q 405	Si PNP low noise SOT-23	576-0003-657	R 204	220 ohm ±5% 1206 SMD	569-0115-221
Q 406	Si NPN GP sw/amp SOT-23	576-0001-300	R 205	560 ohm ±5% 1206 SMD	569-0115-561
Q 407	Si PNP low noise SOT-23	576-0003-650	R 206	1.8k ohm ±5% 1206 SMD	569-0115-182
Q 408	Si PNP low noise SOT-23	576-0003-650	R 207	51k ohm ±5% 1206 SMD	569-0115-513
Q 409	Si NPN GP sw/amp SOT-23	576-0001-300	R 208	100k ohm ±5% 1206 SMD	569-0115-104
Q 410	NPN UHF low noise SOT-23	576-0003-636	R 211	5.1k ohm ±5% 1206 SMD	569-0115-512
Q 411	NPN UHF low noise SOT-23	576-0003-636	R 212	100k ohm ±5% 1206 SMD	569-0115-104
			R 213	10k ohm ±5% 1206 SMD	569-0115-103
R 101	24 ohm ±5% 1206 SMD	569-0115-240	R 214	100k ohm ±5% 1206 SMD	569-0115-104
R 102	10k ohm ±5% 1206 SMD	569-0115-103	R 215	20k ohm ±5% 1206 SMD	569-0115-203
R 103	1.8k ohm ±5% 1206 SMD	569-0115-182	R 216	5k ohm SMD top adjust	562-0135-502
R 104	10k ohm ±5% 1206 SMD	569-0115-103	R 217	10k ohm ±5% 1206 SMD	569-0115-103
R 106	1k ohm ±5% 1206 SMD	569-0115-102	R 218	10k ohm ±5% 1206 SMD	569-0115-103
R 107	43 ohm ±5% 1206 SMD	569-0115-430	R 219	5k ohm SMD top adjust	562-0135-502
R 108	43 ohm ±5% 1206 SMD	569-0115-430	R 220	5k ohm SMD top adjust	562-0135-502
R 131	1.3k ohm ±5% 1206 SMD	569-0115-132	R 221	5k ohm SMD top adjust	562-0135-502
R 132	1.5k ohm ±5% 1206 SMD	569-0115-152	R 233	1.8k ohm ±5% 1206 SMD	569-0115-182
R 133	1.3k ohm ±5% 1206 SMD	569-0115-132	R 234	680 ohm ±5% 1206 SMD	569-0115-681
	3k ohm ±5% 1206 SMD	569-0115-302	R 235	51 ohm ±5% 1206 SMD	569-0115-510
	51 ohm ±5% 1206 SMD	569-0115-510	R 236	220 ohm ±5% 1206 SMD	569-0115-221
R 136	10 ohm ±5% 1206 SMD	569-0115-100	R 237	560 ohm ±5% 1206 SMD	569-0115-561
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SYMBO NUMBE		PART NUMBER	SYMBO NUMBE		PART NUMBER
R 238	1.8k ohm ±5% 1206 SMD	569-0115-182	R 428	1k ohm ±5% 1206 SMD	569-0115-102
R 239	51k ohm ±5% 1206 SMD	569-0115-513	R 429	910 ohm ±5% 1206 SMD	569-0115-911
R 240	100k ohm ±5% 1206 SMD	569-0115-104	R 430	240 ohm ±5% 1206 SMD	569-0115-241
R 243	5.1k ohm ±5% 1206 SMD	569-0115-512	R 431	51 ohm ±5% 1206 SMD	569-0115-510
R 244	100k ohm ±5% 1206 SMD	569-0115-104	R 432	47k ohm ±5% 1206 SMD	569-0115-473
R 245	100k ohm ±5% 1206 SMD	569-0115-104	R 433	100k ohm ±5% 1206 SMD	569-0115-104
R 246	100k ohm ±5% 1206 SMD	569-0115-104	R 434	30k ohm ±5% 1206 SMD	569-0115-303
R 247	20k ohm ±5% 1206 SMD	569-0115-203	R 435	3k ohm ±5% 1206 SMD	569-0115-302
R 248	5k ohm SMD top adjust	562-0135-502	R 436	1k ohm ±5% 1206 SMD	569-0115-102
R 249	1k ohm ±5% 1206 SMD	569-0115-102	R 437	100k ohm ±5% 1206 SMD	569-0115-104
R 250	10k ohm ±5% 1206 SMD	569-0115-103	R 438	9.1k ohm ±5% 1206 SMD	569-0115-912
R 253	5k ohm SMD top adjust	562-0135-502	R 439	3.6k ohm ±5% 1206 SMD	569-0115-362
R 254	1.8k ohm ±5% 1206 SMD	569-0115-182	R 440	1k ohm ±5% 1206 SMD	569-0115-102
R 255	680 ohm ±5% 1206 SMD	569-0115-681	R 441	15k ohm ±5% 1206 SMD	569-0115-153
R 256	51 ohm ±5% 1206 SMD	569-0115-510	R 442	10 ohm ±5% 1206 SMD	569-0115-100
R 257	220 ohm ±5% 1206 SMD	569-0115-221	R 443	51 ohm ±5% 1206 SMD	569-0115-510
R 258	10k ohm ±5% 1206 SMD	569-0115-103	R 444	4.3k ohm ±5% 1206 SMD	569-0115-432
R 259	1k ohm ±5% 1206 SMD	569-0115-102	R 445	1.5k ohm ±5% 1206 SMD	569-0115-152
R 260	270 ohm ±5% 1206 SMD	569-0115-271	R 446	1.3k ohm ±5% 1206 SMD	569-0115-132
R 261	10 ohm ±5% 1206 SMD	569-0115-100	R 447	150 ohm ±5% 1206 SMD	569-0115-151
R 262	1k ohm ±5% 1206 SMD	569-0115-102	R 448	36 ohm ±5% 1206 SMD	569-0115-360
R 301	220 ohm ±5% 1206 SMD	569-0115-221			
R 302	220 ohm ±5% 1206 SMD	569-0115-221	RT202	1k ohm ±5% chip thermistor	569-3013-002
R 303	220 ohm ±5% 1206 SMD	569-0115-221	RT204	1k ohm ±5% chip thermistor	569-3013-002
R 304	240 ohm ±5% 1206 SMD	569-0115-241			
R 305	43 ohm ±5% 1206 SMD	569-0115-430	TP101	Red vertical tip jack 0.08	105-2202-211
R 311	Zero ohm ±10% 1206 SMD	569-0115-001		Red vertical tip jack 0.08	105-2202-211
R 312	Zero ohm ±10% 1206 SMD	569-0115-001		Red vertical tip jack 0.08	105-2202-211
R 315	Zero ohm ±10% 1206 SMD	569-0115-001	TP203	Red vertical tip jack 0.08	105-2202-211
R 401	270 ohm ±5% 1206 SMD	569-0115-271			
R 402	12.1k ohm ±1% 1206 SMD	569 - 0111-409	U 101		544-0007-013
R 403	4.99k ohm ±1% 1206 SMD	569-0111-368	U 102	Op amp SO-8 MC33172D	544-2019-017
R 404	10 ohm ±5% 1206 SMD	569-0115-100	U 201	FM IF MC3371D SO-16	544-2002-031
R 406	2.7k ohm ±5% 1206 SMD	569 - 0115-272	U 202	Dual op amp SO-8	544-2019-004
R 407	3.3k ohm ±5% 1206 SMD	569-0115-332	U 203	FM IF MC3371D SO-16	544-2002-031
R 408	3.3k ohm ±5% 1206 SMD	569 - 0115-332	U 204	Dual op amp SO-8	544-2019-004
R 409	270 ohm ±5% 1206 SMD	569-0115-271	U 301	+5V regulator 78L05 SO-8	544-2603-039
R 410	68k ohm ±5% 1206 SMD	569-0115-683	U 302	+12V regulator 78L12 SO-8	544-2603-032
R 411	240 ohm ±5% 1206 SMD	5 69- 0115-241	U 303	+12V regulator 78L12 SO-8	544-2603-032
R 412	4.3k ohm ±5% 1206 SMD	569-0115-432	U 304	+12V regulator 78L12 SO-8	544-2603-032
R 413	1k ohm ±5% 1206 SMD	569-0115-102	U 401	Synthesizer MC145190F SOIC	544-3954-026
R 414	51 ohm ±5% 1206 SMD	569-0115-510			
R 421	10k ohm ±5% 1206 SMD	569-0115-103	Y 401	17.5 MHz crystal 1 PPM	518-7117 - 500
R 423	100 ohm ±5% 1206 SMD	569-0115-101			
R 424	100 ohm ±5% 1206 SMD	569-0115-101	Z 201	52.95 MHz 4-pole 15 kHz BW	
R 426	10k ohm ±5% 1206 SMD	569-0115-103	Z 202	52.95 MHz 4-pole 15 kHz BW	
R 427	1k ohm ±5% 1206 SMD	569-0115-102	Z 203	450 kHz cer filter 20 kHz BW	532-2004-013

^{*} DANGER Beryllium Product. Inhalation of dust or fumes may cause serious chronic lung disease

SYMBO NUMBE		PART NUMBER	SYMBO NUMBI		PART NUMBER
Z 204 Z 205	450 kHz cer filter 20 kHz BW 680 μH quad coil	532-2004-013 542-5102-001	MP400	UHF VCO shield	017-2226-044
Z 211 Z 212	52.95 MHz 4-pole 8 kHz BW 52.95 MHz 4-pole 8 kHz BW	532-0009-011 532-0009-011	PC800	PC board	035-2044-850
Z 213	450 kHz cer filter 9 kHz BW	532-2004-015	Q 801	Si NPN gen purp switch/amp	576-0001-300
Z 214 Z 215	450 kHz cer filter 9 kHz BW 680 μH quad coil	532-2004-015 542-5102-001	Q 802		576-0003-636
			R 803	10 ohm ±5% 0805 chip	569-0105-100
			R 804	3.6k ohm ±5% 0805 chip	569-0105-362
			R 805	10 ohm ±5% 0805 chip	569-0105-100
			R 806	5.1k ohm ±5% 0805 chip	569-0105-512
	TRANSMIT VCO 403-470		R 807	6.2k ohm ±5% 0805 SMD	569-0105-622
	PART NO. 023-20X4-85	U	R 808	200 ohm ±5% 1206 SMD	569-0115-201
C 001	60T. 60/ NDO 0006 CND	510 2701 700	R 809	47k ohm ±5% 0805 SMD	569-0105-473
C 801 C 803	68 pF ±5% NPO 0805 SMD 0.6-4.5 pF vertical SMT	510-3601-680 512-0006-011		EVOTTED 402 450 NOT	7 .
C 803	3.9 pF ±5% NPO 0805 chip	510-3601-399	į	EXCITER 403-470 MH PART NO. 023-2044-40	
C 804	(400-470 MHz) 3.6 pF ±5% NPO 0805 chip	510-3601-369	A 007	430-470 MHz VCO	
	(470-512 MHz)				023-2044-850
C 805	68 pF ±5% NPO 0805 chip	510-3601-680	C 409	.01 μF ±10% X7R chip	510-3606-103
C 806	0.7 pF ±0.1 pF high Q	510-3710-708	C 410	.01 μF ±10% X7R chip	510-3606-103
C 807	7.5 pF ±5% NPO 0805 chip	510-3601-759	C 416	.1 μF ±10% X7R 1210	510-3607-104
C 808 C 809	7.5 pF ±5% NPO 0805 chip 68 pF ±5% NPO 0805 chip	510-3601-759	C 417 C 418	.01 μF ±10% X7R 1206 chip	510-3606-103
C 810	68 pF ±5% NPO 0805 chip	510-3601-680 510-3601-680	C 418	.001 μF ±5% NPO 1206 chip .01 μF ±10% X7R chip	510-3602-102 510-3606-103
C 811	68 pF ±5% NPO 0805 chip	510-3601-680	C 420	5.6 pF ±5% NPO 1206 chip	510-3602-569
C 812	15 μF 20V tantalum SMD	510-2626-150	C 421	4.7 μF 16V tantalum SMD	510-3602-369
C 813	68 pF ±5% NPO 0805 chip	510-2620-150	C 422	$1 \mu F \pm 10\% X7R 1210$	510-2623-479
C 814	68 pF ±5% NPO 0805 chip	510-3601-680	C 423	100 pF ±5% NPO 1206 chip	510-3602-101
C 815	1.2 pF ±5% NPO 0805 chip	510-3601-129	C 424	.1 μF ±10% X7R 1210	510-3607-104
	1 pF ±5% NPO 0805 chip	510-3601-109	C 425	.1 μF ±10% X7R 1210	510-3607-104
	•		C 426	4.7 μF 16V tantalum SMD	510-2625-479
CR801	Varactor SOD-323 BB535	523-5005-022	C 427	68 pF ±5% NPO 1206 chip	510-3602-680
CR802	Varactor SOD-323 BB535	523-5005-022	C 428	4.7 μF 16V tantalum SMD	510-2625-479
CR803	Varactor SOD-323 BB535	523-5005-022	C 429	68 pF ±5% NPO 1206 chip	510-3602-680
			C 430	68 pF ±5% NPO 1206 chip	510-3602-680
J 001	2-pin PC mount wafer	515-9031-101	C 432	.01 μF ±10% X7R chip	510-3606-103
J 002	2-pin PC mount wafer	515-9031-101	C 433	6.8 pF ±5% NPO 1206 chip	510-3602-689
J 003	4-pin PC mount wafer	515-9031-103	C 434	68 pF ±5% NPO 1206 chip	510-3602 -68 0
			C 441	100 pF ±5% NPO 1206 chip	510-3602-101
L 801	150 nH ±10% 0805 SMD	542-9003-158	C 442	68 pF ±5% NPO 1206 chip	510-3602-680
L 802	150 nH ±10% 0805 SMD	542-9003-158	C 443	68 pF ±5% NPO 1206 chip	510-3602-680
L 803	150 nH ±10% 0805 SMD	542-9003-158	C 444	68 pF ±5% NPO 1206 chip	510-3602-680
L 804	150 nH ±10% 0805 SMD	542-9003-158	C 446	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183
L 805	12mm resonator SMD	542-9006-004	C 447	4.7 μF 16V tantalum SMD	510-2625-479
			C 448	68 pF ±5% NPO 1206 chip	510-3602-680

SYMBO NUMBI		PART <u>NUMBER</u>	SYMBO NUMBI		PART NUMBER
C 449	2.7 pF ±5% NPO 1206 chip	510-3602-279	C 513	.018 μF ±10% X7R 0805 chip	510-3605-183
C 450	7.5 pF ±5% NPO 1206 chip	510-3602-759	C 514	68 pF ±5% NPO 1206 chip	510-3602-680
C 451	4.3 pF ±5% NPO 1206 chip	510-3602-439		or produced according	
C 452	6.2 pF ±5% NPO 1206 chip	510-3602-629	CR401	Si 9.1V zener SOT-23	523-2016-919
C 453	820 pF ±5% NPO 1206 chip	510-3602-821	1	Si 5.6V zener SOT-23	523-2016-569
C 454	68 pF ±5% NPO 1206 chip	510-3602-680		Si 5.6V zener SOT-23	523-2016-569
C 455	68 pF ±5% NPO 1206 chip	510-3602-680			
C 456	68 pF ±5% NPO 1206 chip	510-3602-680	HW404	4 Polarized key box connector	515-7109-010
C 457	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183		•	
C 461	68 pF ±5% NPO 1206 chip	510-3602-680	J 401	20-pin right angle header	515-9031-375
C 462	.001 μF ±5% NPO 1206 chip	510-3602-102	J 402	Right angle PC JCM-B	131-3701-301
C 463	15 μF 20V tantalum SMD	510-2626-150			
C 464	.01 μF ±10% X7R chip	510-3606-103	L 402	.1 μH inductor SMD	542-9001-108
C 465	.018 μF ±10% X7R 0805 chip	510-3605-183	L 403	.1 μH inductor SMD	542-9001-108
C 466	.001 μF ±5% NPO 1206 chip	510-3602-102	L 405	.1 μH inductor SMD	542-9001-108
C 467	1.5 µF 25V tantalum SMD	510-2627-159	L 406	.1 μH inductor SMD	542-9001-108
C 468	4.7 μF 16V tantalum SMD	510-2625-479	L 407	.1 μH inductor SMD	542-9001-108
C 469	4.7 μF 16V tantalum SMD	510-2625-479	L 408	$10 \text{ nH} \pm 10\% 0805 \text{ SMD}$	542-9003-107
C 470	.001 μF ±5% NPO 1206 chip	510-3602-102	L 409	.068 μH inductor SMD	542-9001-687
C 471	.001 μF ±5% NPO 1206 chip	510-3602-102	L 410	15 nH inductor LL2012 F15N	542-9003-157
C 472	1.5 μF 25V tantalum SMD	510-2627-159	L 411	.068 μH inductor SMD	542-9001-687
C 474	4.7 μF 16V tantalum SMD	510-2625-479	L 412	18 nH inductor LL2012 F18N	542-9003-187
C 475	.001 μF ±5% NPO 1206 chip	510-3602-102	DC 464	P.C. 1	
C 476	4.7 μF 16V tantalum SMD	510-2625-479	PC401	PC board	035-2044-400
C 479	.01 μF ±10% X7R 1206 chip	510-3606-103	0.400	C' MDM	554 0000 650
C 480 C 481	68 pF ±5% NPO 1206 chip	510-3602-680	Q 403	Si NPN amp	576-0003-658
C 481	1 μF 16V tantalum SMD 68 pF ±5% NPO 1206 chip	510-2625-109 510-3602-680	Q 404 Q 405	Si NPN amp	576-0003-658
C 482	68 pF ±5% NPO 1206 chip	510-3602-680	Q 403 Q 406	Si PNP switching Si NPN low noise SOT-23	576-0003-612
C 484	68 pF ±5% NPO 1206 chip	510-3602-680	Q 400 Q 407	Si NPN low noise SOT-23	576-0003-636 576-0003-636
C 485	68 pF ±5% NPO 1206 chip	510-3602-680	Q 407	Si NPN amp	576-0003-658
C 496	15 μF 20V tantalum SMD	510-2626-150	Q 411	Si NPN low noise SOT-23	576-0003-636
C 498	$.018 \mu F \pm 10\% X7R 0805 chip$	510-2625-130	_	NPN 0.2-2 GHz SO-8	576-0003-604
C 499	68 pF ±5% NPO 1206 chip	510-3602-680	-	NPN 750 mW UHF/800 MHz	576-0004-098
C 500	22 pF ±5% NPO 1206 chip	510-3602-220	Q .13	THE TOTAL CHAPTER	370 0001 090
C 501	68 pF ±5% NPO 1206 chip	510-3602-680	R 402	10k ohm ±5% SMD 1206	569-0115-103
C 502	.001 µF ±5% NPO 1206 chip	510-3602-102	R 403	10k ohm ±5% SMD 1206	569-0115-103
C 503	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	R 404	100 ohm ±5% SMD 1206	569-0115-101
C 504	.018 µF ±10% X7R 0805 chip	510-3605-183	R 405	1k ohm ±5% SMD 1206	569-0115-102
C 505	8.2 pF ±5% NPO 1206 chip	510-3602-829	R 414	12.1k ohm ±1% SMD 1206	569-0111-409
C 506	75 pF ±5% NPO 1206 chip	510-3602-750	R 415	4.99k ohm ±1% SMD 1206	569-0111-368
C 507	4.7 μF 16V tantalum SMD	510-2625-479	R 416	270 ohm ±5% SMD 1206	569-0115-271
C 508	68 pF ±5% NPO 1206 chip	510-3602-680	R 417	10k ohm ±5% SMD 1206	569-0115-103
C 509	3.3 pF ±5% NPO 1206 chip	510-3602-339	R 419	12.1k ohm ±1% SMD 1206	569-0111-409
C 510	6.2 pF ±5% NPO 1206 chip	510-3602-629	R 424	10k ohm ±5% SMD 1206	569-0115-103
C 511	3.3 µF 16V tantalum SMD	510-2625-339	R 425	50k ohm single turn trimmer	562-0112-503
C 512	.33 μF 35V tantalum SMD	510-2628-338	R 426	10k ohm ±5% SMD 1206	569-0115-103

SYMBO NUMBE		PART NUMBER	SYMBO NUMBE		PART NUMBER
D 407	101 .1	500 0115 160	·	150 1	
R 427	10k ohm ±5% SMD 1206	569-0115-103	R 476	150 ohm ±5% SMD 1206	569-0115-151
R 428	10 ohm ±5% SMD 1206	569-0115-100	R 477	1.5k ohm ±5% SMD 1206	569-0115-152
R 429	4.99k ohm ±1% SMD 1206	569-0111-368	R 478	200 ohm ±5% SMD 1206	569-0115-201
R 430	2.7k ohm ±5% SMD 1206	569-0115-272	R 479	150 ohm ±5% SMD 1206	569-0115-151
R 431	3.3k ohm ±5% SMD 1206	569-0115-332	R 480	7.5k ohm ±5% SMD 1206	569-0115-752
R 432	3.3k ohm ±5% SMD 1206	569-0115-332	R 481	1.3k ohm ±5% SMD 1206	569-0115-132
R 433	270 ohm ±5% SMD 1206	569-0115-271	R 482	Zero ohm ±5% SMD 1206	569-0115-001
R 434	150 ohm ±5% SMD 1206	569-0115-151	R 486	12.1k ohm ±1% SMD 1206	569-0111-409
R 435	470 ohm ±5% SMD 1206	569-0115-471	R 487	4.99k ohm ±1% SMD 1206	569-0111-368
R 436	100 ohm ±5% SMD 1206	569-0115-101	R 488	10k ohm ±5% SMD 1206	5 69- 0115-103
R 437	100 ohm ±5% SMD 1206	569-0115-101	R 489	150 ohm ±5% SMD 1206	569-0115-151
R 438	10k ohm ±5% SMD 1206	569-0115-103	R 491	Zero ohm ±5% SMD 1206	569-0115-001
R 439	1k ohm ±5% SMD 1206	569-0115-102	R 493	6.8k ohm ±5% SMD 1206	569-0115-682
R 440	1k ohm ±5% SMD 1206	569-0115-102			
R 441	47k ohm ±5% SMD 1206	569-0115-473	U 402	Dual op amp SO-8 2904	544-2019-004
R 442	100 ohm ±5% SMD 1206	569-0115-101	U 403	Synthesizer SOIC MC145190	544-3954-026
R 444	10k ohm ±5% SMD 1206	569-0115-103	U 404	Dual op amp SO-8	544-2019-004
R 445	82k ohm ±5% SMD 1206	569-0115-823	U 405	+5V regulator 78L05 SO-8	544-2603-039
R 446	50k ohm single turn trimmer	562-0112-503	U 406	+12V regulator 78L12 SO-8	544-2603-032
R 447	1k ohm ±5% SMD 1206	569-0115-102	U 407	Dual op amp SO-8	544-2019-004
R 448	10k ohm ±5% SMD 1206	569-0115-103			
R 449	10k ohm ±5% SMD 1206	569-0115-103	Y 401	17.5 MHz, 1 PPM TCXO	518-7117-500
R 450	10 ohm ±5% SMD 1206	569-0115-100			
R 451	4.3k ohm ±5% SMD 1206	569-0115-432		UHF FEEDBACK LOO	
R 452	110 ohm ±5% SMD 1206	569-0115-111		PART NO. 023-2004-53	0
R 453	1.5k ohm ±5% SMD 1206	569-0115-152			
R 454	1.3k ohm ±5% SMD 1206	569-0115-132	C 001	.1 μF μ% X7R 1206	510-3609-104
R 455	150 ohm ±5% SMD 1206	569-0115-151			
R 456	470 ohm ±5% SMD 1206	569-0115-471	L 001	.082 μH inductor SMD	542-9001-827
R 458	3k ohm ±5% SMD 1206	569-0115-302			
R 459	150 ohm ±5% SMD 1206	569-0115-151	P 001	Edge clip 48 mil	515-9034-004
R 460	36 ohm ±5% SMD 1206	569-0115-360	P 002	Edge clip 48 mil	515-9034-004
R 461	150 ohm ±5% SMD 1206	569-0115-151			
R 462	10 ohm ±5% SMD 1206	569-0115-100	PC502	PC board	035-2004-530
R 463	51 ohm ±5% SMD 1206	569-0115-510			
R 464	330 ohm ±5% SMD 1206	569-0115-331	R 001	100 ohm ±5% X7R 1206	569-0175-101
	1.3k ohm ±5% SMD 1206	569-0115-132		440 771 / 2000 - 0.000	
R 466	1.5k ohm ±5% SMD 1206	569-0115-152		110 WATT POWER AMPLI	
R 467	1.3k ohm ±5% SMD 1206	569-0115-132		PART NO. 023-2044-50	U
R 468	75 ohm ±5% SMD 1206	569-0115-750			
R 469	2k ohm ±5% SMD 1206	569-0115-202		$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183
R 470	270 ohm ±5% SMD 1206	569-0115-271		2.2 μF 20v tantalum SMD	510-2626-229
R 471	300 ohm ±5% SMD 1206	569-0115-301	C 503	.1 μ F ±10% X7R chip	510-3606-104
R 472	300 ohm ±5% SMD 1206	569-0115-301	C 504	100 pF ±10% high Q cube	510-3663-101
R 473	150 ohm ±5% SMD 1206	569-0115-151	C 505	100 pF ±10% high Q cube	510-3663-101
R 474	36 ohm ±5% SMD 1206	569-0115-360		.018 μ F ±10% X7R 0805 chip	510-3605-183
R 475	150 ohm ±5% SMD 1206	569-0115-151	C 507	4.7 μF 16V tantalum SMD	510-2626-479
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SYMBO NUMBI		PART NUMBER	SYMBO NUMBI		PART NUMBER
C 508	100 pF ±10% high Q cube	510-3663-101	C 546	8.2 pF ±10% high Q cube	510-3663-829
C 509	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	05.0	(430-470 MHz)	310 3003-027
C 510	1 μF 35V tantalum SMD	510-2628-109	C 547	22 pF ±5% 250V mica	510-0220-220
C 511	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	00	(430-470 MHz)	310 0220 220
C 512	100 pF ±10% high Q cube	510-3663-101	C 548	27 pF ±5% 250V mica	510-0220-270
C 513	6.8 μF 35V tantalum SMD	510-2635-689		(400-470 MHz)	210 0220 270
C 514	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	C 549	$.018 \mu\text{F} \pm 10\% \text{X7R} 0805 \text{chip}$	510-3605-183
C 515	100 pF ±10% high Q cube	510-3663-101	C 550	.018 μ F ±10% X7R 0805 chip	510-3605-183
C 516	$.018 \mu\text{F} \pm 10\% \text{X7R} 0805 \text{chip}$	510-3605-183	C 551	100 pF ±10% high Q cube	510-3663-101
C 517	100 pF ±10% high Q cube	510-3663-101	C 552	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183
C 518	.1 μF ±10% X7R chip	510-3606-104	C 553	6.8 μF 35V tantalum SMD	510-2635-689
C 519	100 pF ±10% high Q cube	510-3663-101	C 554	100 pF ±10% high Q cube	510-3663-101
C 520	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	C 555	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183
C 521	.1 μF ±10% X7R chip	510-3606-104	C 556	6.8 μF 35V tantalum SMD	510-2635-689
C 522	6.8 µF 35V tantalum SMD	510-2635-689	C 557	100 pF ±10% high Q cube	510-3663-101
C 523	100 pF ±10% high Q cube	510-3663-101	C 558	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183
C 524	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	C 559	.018 µF ±10% X7R 0805 chip	510-3605-183
C 525	.018 μF ±10% X7R 0805 chip	510-3605-183	C 560	27 pF ±5% 250V mica	510-0220-270
C 526	62 pF ±5% NPO 1206 chip	510-3602-620		(400-470 MHz)	
C 527	8.2 pF ±5% NPO 1206 chip	510-3602-829	C 561	22 pF ±5% 250V mica	510-0220-220
	(430-470 MHz)			(430-470 MHz)	
	9.1 pF ±5% NPO 1206 chip	510-3602-919	C 562	13 pF ±5% 250V mica	510-0220-130
	(470-512 MHz)			(400-470 MHz)	
C 528	22 pF ±5% 250V mica	510-0220-220	C 563	100 pF ±10% high Q cube	510-3663-101
	(430-470 MHz)		C 564	56 pF ±10% high Q cube	510-3663-560
C 529	27 pF ±5% 250V mica	510-0220-270		(430-470 MHz)	
	(400-470 MHz)			27 pF ±5% 250V mica	510-0220-270
C 530	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183		(470-512 MHz)	
C 531	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	C 565	8.2 pF ±10% high Q cube	510-3663-829
C 532	100 pF ±10% high Q cube	510-3663-101		(430-470 MHz)	
C 533	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	C 566	$.018 \mu F \pm 10\% X7R 0805 chip$	
C 534	6.8 μF 35V tantalum SMD	510-2635-689	C 567	• •	510-3605-183
C 535	100 pF ±10% high Q cube	510-3663-101	C 568	22 pF ±5% 250V mica	510-0220-220
C 536	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	0.560	(430-470 MHz)	
C 537	6.8 μF 35V tantalum SMD	510-2635-689	C 569	27 pF ±5% 250V mica	510-0220-270
C 538	100 pF ±10% high Q cube	510-3663-101	0.550	(400-470 MHz)	
C 539	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	C 570	100 pF ±10% high Q cube	510-3663-101
C 540	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	C 571	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183
C 541	27 pF ±5% 250V mica	510-0220-270	C 572	6.8 µF 35V tantalum SMD	510-2635-689
C 542	(400-470 MHz)	510 0000 000	C 573	100 pF ±10% high Q cube	510-3663-101
C 542	22 pF ±5% 250V mica	510-0220-220	C 574	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183
C 543	(400-470 MHz)	610 0220 180	C 575	6.8 μF 35V tantalum SMD	510-2635-689
C 543	18 pF ±5% 250V mica	510-0220-180	C 576	100 pF ±10% high Q cube	510-3663-101
CEAE	(400-430 MHz)	510 2662 560	C 577	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183
C 545	56 pF ±10% high Q cube	510-3663-560	C 578	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183
	(430-470 MHz)	510 0000 000	C 579	27 pF ±5% 250V mica	510-0220-270
	27 pF ±5% 250V mica (470-512 MHz)	510-0220-270		(400-470 MHz)	
	(T/U-J12 WIII2)				

SYMBO NUMBI		PART NUMBER	SYMBO NUMBI		PART NUMBER
C 580	22 pF ±5% 250V mica	510-0220-220	O 501	* 100W UHF RF power amp	576-0006-119
	(430-470 MHz)		_	100W UHF RF power amp	576-0006-119
C 581	13 pF ±5% 250V mica	510-0220-130	_	100W UHF RF power amp	576-0006-119
	(430-470 MHz)		O 504	•	576-0001-300
C 582	100 pF ±10% high Q cube	510-3663-101	_	Si NPN GP sw/amp SOT-23	576-0001-300
C 583	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183		21 2 1 2 1 2 1 1 1 1 1 2 1 2 1 2 1 2 1	
C 584	.001 µF ±5% NPO 1206 chip	510-3602-102	R 501	150 ohm ±5% 1206 SMD	569-0115-151
C 585	39 pF ±5% NPO 1206 chip	510-3602-390	R 502	36 ohm ±5% 1206 SMD	569-0115-360
C 586	1 μF 16V tantalum SMD	510-2625-109	R 503	150 ohm ±5% 1206 SMD	569-0115-151
C 587	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	R 504	.03 ohm ±5% SMD 2W	569-2019-307
C 588	100 pF ±10% high Q cube	510-3663-101	R 505	200 ohm ±5% 1206 SMD	569-0115-201
C 589	1 μF 35V tantalum SMD	510-2628-109	R 506	200 ohm ±5% 1206 SMD	569-0115-201
C 590	4.7 μF 16V tantalum SMD	510-2625-479	R 508	2k ohm ±5% 1206 SMD	569-0115-202
C 591	4.7 μF 16V tantalum SMD	510-2625-479	R 509	4.7k ohm SMD top adjust	569-0115-472
C 592	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	R 510	5k ohm ±5% 1206 SMD	569-0135-502
C 593	.001 μF ±5% NPO 1206 chip	510-3602-102	R 511	2.2k ohm ±5% 1206 SMD	569-0115-222
C 594	100 pF ±10% high Q cube	510-3663-101	R 512	10k ohm ±5% 1206 SMD	569-0115-103
C 595	1 μF 35V tantalum SMD	510-2628-109	R 513	4.7k ohm ±5% 1206 SMD	569-0115-472
C 596	4.7 μF 16V tantalum SMD	510-2625-479	R 514	.03 ohm ±5% SMD 2W	569-2019-307
C 597	.018 μ F ±10% X7R 0805 chip	510-3605-183	R 515	200 ohm ±5% 1206 SMD	569-0115-201
C 598	.001 μF ±5% NPO 1206 chip	510-3602-102	R 516	200 ohm ±5% 1206 SMD	569-0115-201
C 600	.1 μF ±10% X7R chip	510-3606-104	R 517	Zero ohm ±5% 1206 SMD	569-0115-001
C 601	1 μF ±10% X7R chip	510-3606-104	R 518	2k ohm ±5% 1206 SMD	569-0115-202
C 602	.1 μF ±10% X7R chip	510-3606-104		100 ohm 20W flange mount	569-5001 - 001
C 603	$.018 \mu F \pm 10\% X7R 0805 chip$	510-3605-183	R 520	4.7k ohm ±5% 1206 SMD	569-0115-472
OD cos	G1 < G17 + 504 G0 G0 G0		R 521	5k ohm SMD top adjust	569-0115 - 502
	Si 6.2V ±5% zener SOT-23	523-2016-629	R 522	2.2k ohm ±5% 1206 SMD	569-0115-222
	Si 6.2V ±5% zener SOT-23	523-2016-629	R 523	10k ohm ±5% 1206 SMD	569-0115-103
CK503	Si 6.2V ±5% zener SOT-23	523-2016-629	R 524	4.7k ohm ±5% 1206 SMD	569-0115-472
ED601	Ferrite bead SMD 1233	517 2502 010	R 525	.03 ohm ±5% SMD 2W	569-2019-307
	Ferrite bead SMD 1233	517-2503-010 517-2503-010	R 526	200 ohm ±5% 1206 SMD	569-0115-201
	Ferrite bead SMD 1233	517-2503-010	R 527 R 528	200 ohm ±5% 1206 SMD 2k ohm ±5% 1206 SMD	569-0115-201
	Ferrite bead SMD 1233	517-2503-010	R 529	4.7k ohm ±5% 1206 SMD	569-0115-202
	Ferrite bead SMD 1233	517-2503-010	R 530	5k ohm SMD top adjust	569-0115 - 472 569-0115-502
	Ferrite bead SMD 1233	517-2503-010	R 531	2.2k ohm ±5% 1206 SMD	569-0115-222
	Ferrite bead SMD 1233	517-2503-010	R 531	10k ohm ±5% 1206 SMD	569-0115-103
	Ferrite bead SMD 1233	517-2503-010	R 532	4.7k ohm ±5% 1206 SMD	569-0115-472
	Ferrite bead SMD 1233	517-2503-010	R 534	.03 ohm ±5% SMD 2W	569-2019-307
	Ferrite bead SMD 1233	517-2503-010	R 535	200 ohm ±5% 1206 SMD	569-0115-201
	Ferrite bead SMD 1233	517-2503-010	R 536	200 ohm ±5% 1206 SMD	569-0115-201
	Ferrite bead SMD 1233	517-2503-010	R 537	2k ohm ±5% 1206 SMD	569-0115-202
21020	1 011110 0000 01110 1200	2203 010		100 ohm 100W flange mount	569-5001-002
L 504	.1 μH inductor SMD	542-9001-108	R 539	-	569-0115-471
L 505	.1 μH inductor SMD	542-9001-108	R 540	301k ohm ±1% 1206 SMD	569-0111-547
L 506	.1 μH inductor SMD	542-9001-108	R 541	100k ohm ±1% 1206 SMD	569-0111-501
	,		R 542	75 ohm ±5% 1206 SMD	569-0115-750
PC500	PC board	035-2044-500	R 543	56 ohm ±5% 1206 SMD	569-0115-560
		,	R 544	240 ohm ±5% 1206 SMD	569-0115-241
					

SYMBOL NUMBER	DESCRIPTION	PART NUMBER	SYMBO NUMBE		PART NUMBER
R 545 Z	ero ohm ±5% 1206 SMD	569-0115-001	C 652	68 pF ±5% NPO 1206 chip	510-3602-680
	l ohm ±5% 2512 SMD	569-0175-510	C 653	68 pF ±5% NPO 1206 chip	510-3602-680
	l ohm ±5% 2512 SMD	569-0175-510	C 654	68 pF ±5% NPO 1206 chip	510-3602-680
	1 ohm ±5% 2512 SMD	569-0175-510	C 655	68 pF ±5% NPO 1206 chip	510-3602-680
	0k ohm ±5% 1206 SMD	569-0115-103	C 656	68 pF ±5% NPO 1206 chip	510-3602-680
	00k ohm ±5% 1206 SMD	569-0115-104	C 657	68 pF ±5% NPO 1206 chip	510-3602-680
	0k ohm ±5% 1206 SMD	569-0115-103	C 658	.001 µF ±5% NPO 1206 chip	510-3602-102
			C 659	.001 μF ±5% NPO 1206 chip	510-3602-102
RT501 80	Ok ±5% chip thermistor	569-3006-803	C 660	68 pF ±5% NPO 1206 chip	510-3602-680
	0k ±5% chip thermistor	569-3006-803	C 661	.001 µF ±5% NPO 1206 chip	510-3602-102
	Ok ±5% chip thermistor	569-3006-803	C 662	2.2 µF 20V tantalum SMD	510-2626-229
	•		C 663	4.7 μF 10V tantalum SMD	510-2624-479
U 501 13	3W pwr mod 430-470 MHz	544-4001-065	C 664	.001 μF ±5% NPO 1206 chip	510-3602-102
	igh side current sense	544-2039-002	C 665	<u>-</u>	510-2624-479C
U 503 H	igh side current sense	544-2039-002	666	68 pF ±5% NPO 1206 chip	510-3602-680
U 504 H	igh side current sense	544-2039-002	C 667	4.7 μF 10V tantalum SMD	510-2624-479
U 505 H	igh side current sense	544-2039-002		•	
U 506 D	ual op amp 532 SO-8	544-2019-004	CR601	Dual Schottky SOT-143	523-1504-033
U 507 Te	emp sensor LM35 SO-8	544-2032-003	CR651	Dual Schottky SOT-143	523-1504-033
U 508 +5	5V regulator 78L05 SO-8	544-2603-039		·	
U 509 +5	5V regulator 78L05 SO-8	544-2603-039	L 602	9T 35.5 nH SMD air core	542-0030-009
			L 603	.1 μH SMD inductor	542-9001-108
	LOW-PASS FILTER		L 652	.1 μH SMD inductor	542-9001-108
	PART NO. 023-2004-60	0	L 653	9T 35.5 nH SMD air core	542-0030-009
			L 654	9T 35.5 nH SMD air core	542-0030 - 009
A 620 L	ow pass filter assembly	023-2004-620			
1 CD (00 T	777			PC board shield	017-2210-211
MP600 L	PF mounting plate	017-2222-264		PC board shield	017-2210-211
EODW	A DEMENSE DOWNED I	PERCEOD	MP653	Power detector board	017-2210-212
rokw.	ARD/REVERSE POWER I PART NO. 023-2004-66		DC/01	DC board	025 2004 660
	FART NO. 025-2004-00	"	PCOUL	PC board	035-2004-660
C 601 68	3 pF ±5% NPO 1206 chip	510-3602-680	R 601	51 ohm ±5% 1206 SMD	569-0115-510
	3 pF ±5% NPO 1206 chip	510-3602-680	R 603	51 ohm ±5% 1206 SMD	569-0115-510
	3 pF ±5% NPO 1206 chip	510-3602-680	R 604	51 ohm ±5% 1206 SMD	569-0115-510
	3 pF ±5% NPO 1206 chip	510-3602-680	R 605	10k ohm ±1% 1206 SMD	569-0111-401
	3 pF ±5% NPO 1206 chip	510-3602-680	R 606	10k ohm ±1% 1206 SMD	569-0111-401
	3 pF ±5% NPO 1206 chip	510-3602-680	R 607	20k ohm ±1% 1206 SMD	569-0111-430
	01 μF ±5% NPO 1206 chip	510-3602-102	R 608	10k ohm ±1% 1206 SMD	569-0111-401
C 608 68	3 pF ±5% NPO 1206 chip	510-3602-680	R 609	10k ohm ±1% 1206 SMD	569-0111-401
	01 μF ±5% NPO 1206 chip	510-3602-102	R 610	160 ohm ±5% 1206 SMD	569-0115-161
C 610 68	3 pF ±5% NPO 1206 chip	510-3602-680	R 611	5k ohm SMD top adjust	569-0135-502
C 611 4.	7 μF 10V tantalum SMD	510-2624-479	R 612	10k ohm ±1% 1206 SMD	569-0111-401
C 612 .0	01 μF ±5% NPO 1206 chip	510-3602-102	R 613	10k ohm ±1% 1206 SMD	569-0111-401
	3 pF ±5% NPO 1206 chip	510-3602-680	R 614	10k ohm ±1% 1206 SMD	569-0111-401
C 614 4.	7 μF 10V tantalum SMD	510-2624-479	R 615	470 ohm ±5% 1206 SMD	569-0115-471
C 651 68	3 pF ±5% NPO 1206 chip	510-3602-680	R 616	2k ohm ±5% 1206 SMD	569-0115-202

SYMBO: NUMBE		PART NUMBER	SYMBOL NUMBER		DESCRIPTION	PART NUMBER
R 651	51 ohm ±5% 1206 SMD	569-0115-510	MP240) PA coax g	round tab	017-2210-038
R 653	51 ohm ±5% 1206 SMD	569-0115-510	l .	_	e align dowel pin	017-2210-038
R 654	51 ohm ±5% 1206 SMD	569-0115-510		PA shield,		017-2210-121
R 655	10k ohm ±1% 1206 SMD	569-0111-401		7 PA shield,		017-2210-022
R 656	20k ohm ±1% 1206 SMD	569-0111-430			right, 1 fan	017-2210-022
R 657	10k ohm ±1% 1206 SMD	569-0111-401			filter shield	017-2210-229
R 658	10k ohm ±1% 1206 SMD	569-0111-401		B M PA stor		013-1723-222
R 659	10k ohm ±1% 1206 SMD	569-0111-401) PA shield		017-2210-207
R 660	150 ohm ±5% 1206 SMD	569-0115-151		, 111 0111010		017 2210 207
R 661	5k ohm SMD top adjust	569-0135-502		MAIN	PROCESSOR CA	RD
R 662	10k ohm ±1% 1206 SMD	569-0111-401			RT NO. 023-2000-31	
R 663	7.5k ohm ±5% 1206 SMD	569-0115-752				
R 664	12k ohm ±5% 1206 SMD	569-0115-123	C 001	10 pF ±5%	6 NPO 1206 chip	510-3602-100
R 665	470 ohm ±5% 1206 SMD	569-0115-471	C 002		6 NPO 1206 chip	510-3602-200
R 666	240 ohm ±5% 1206 SMD	569-0115-241	C 004	•	0% X7R chip	510-3606-103
R 667	47 ohm ±5% 1206 SMD	569-0115-470	C 005		0% X7R chip	510-3606-103
R 669	2k ohm ±5% 1206 SMD	569-0115-202	C 006)% X7R chip	510-3606-103
			C 007	$.01 \mu F \pm 10$	0% X7R chip	510-3606-103
U 601	Dual op amp SO-8	544-2019-004	C 008	10 pF ±5%	6 NPO 1206 chip	510-3602-100
U 651	Dual op amp SO-8	544-2019-004	C 009	$.01 \mu F \pm 10$	0% X7R chip	510-3606-103
U 652	5V regulator 78L05	544-2603-039	C 010	.01 μF ±10)% X7R chip	510-3606-103
			C 011	•)% X7R chip	510-3606-103
P	OWER AMPLIFIER MECH		C 012	•	0% X7R chip	510-3606-103
	PART NO. 023-2004-73	2	C 013	-	6 NPO 1206 chip	510-3602-200
5.000			C 014	•	tantalum SMD	510-2625-100
B 252	24V DC fan 3.14" sq x 1.26"	529-2002-027	C 015	•	% X7R chip	510-3606-103
EDOGG	6.14	604 0005 050	C 016	•	0% X7R chip	510-3606-103
EP200	6-14 ground lug	586-0007-070	C 017	•	electrolytic radial	510-4425-470
HWOSI	6 22 manhard abiling 7DC	575 1606 000	C 018	•	electrolytic radial	510-4425-470
	6-32 panhead philips ZPS 6-32 panhead philips ZPS	575-1606-008	C 019	-	6 NPO 1206 chip	510-3602-620
	1/8" cable clamp	575-1606-012 572-0001-001	C 020	•	% X7R chip	510-3606-104
	6-32 pan torx ZPS	575-0006-010	C 021	•	% X7R chip	510-3606-104
	4-40 panhead philips ZPS	575-1604-010	C 022 C 023	•	% X7R chip % X7R chip	510-3606-104
	6-32 panhead philips ZPS	575-1606-010	C 023	•	tantalum SMD	510-3606-104
	6-32 panhead philips ZPS	575-1606-016	C 024	•	tantalum SMD	510-2625-100 510-2625-100
	6-19 panhead philips ZPS	575-5606-008	C 023	•	% X7R chip	510-2625-100
	6 x 0.018 lockwasher int ZPS	596-1206-010	C 027	•	tantalum SMD	510-2625-100
	0.26 x 0.54 grafoil flgres	018-1007-030	C 028	•	tantalum SMD	510-2625-100
	0.42 x 0.995 grafoil mrf	018-1007-032	C 029		NPO 1206 chip	510-2625-100
	Grafoil M67709	018-1007-105	C 030	•	% X7R chip	510-3606-103
	Grafoil isolator	018-1007-041	C 031		% X7R chip	510-3606-103
	10-32 HHSL Sems scr ZPS	575-9810-012	C 032	•	% X7R chip	510-3606-103
	0.062 x 0.85 x 5.65 poron stp	574-3002-110				110 0000 100
	8-32 panhead CPS philips	575-0608-008	CR001	Green LEI	Submin radial	549-4001-122
	Solder ground terminal	017-2210-213			D submin radial	549-4001-121
	Self mount wire tie	574-9008-025			subminiature radial	549-4001-120
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SYMBO NUMBI		PART NUMBER	SYMBO NUMBI		PART NUMBER
CR004	Red LED subminiature radial	549-4001-120	R 017	2.2k ohm ±5% 1206 SMD	569-0115-222
CR005	Yellow LED submin radial	549-4001-121	R 018	2.2k ohm ±5% 1206 SMD	569-0115-222
			R 019	2.2k ohm ±5% 1206 SMD	569-0115-222
DS001	7-segment display .3" green	549-4002-020	R 020	2.2k ohm ±5% 1206 SMD	569-0115-222
			R 021	100k ohm ±5% 1206 SMD	569-0115-104
EP001	Crystal pin insulator	018-1080-001	R 022	10k ohm ±5% 1206 SMD	569-0115-103
EP002	Crystal pin insulator	018-1080-001	R 023	4.7k ohm ±5% 1206 SMD	569-0115-472
EP003	Crystal pin insulator	018-1080-001	R 024	4.7k ohm ±5% 1206 SMD	569-0115-472
EP004	Crystal pin insulator	018-1080-001	R 025	10k ohm ±5% 1206 SMD	569-0115-103
			R 026	10k ohm ±5% 1206 SMD	569-0115-103
HW00	l Panel fastener	537-0011-031	R 027	10k ohm ±5% 1206 SMD	569-0115-103
			R 028	4.7k ohm ±5% 1206 SMD	569-0115-472
J 001	8-cond modular jack PC mt	515-2006-040	R 029	10k ohm ±5% 1206 SMD	569-0115-103
J 002	3-pin single inline header	515-7100-003	R 030	10k ohm ±5% 1206 SMD	569-0115-103
J 003	14-pin double row header	515-7101-407	R 031	10k ohm ±5% 1206 SMD	569-0115-103
J 004	6-pin double row header	515-7101-403	R 032	1k ohm ±5% 1206 SMD	569-0115-102
J 005	3-pin single inline header	515-7100-003	R 033	1k ohm ±5% 1206 SMD	569-0115-102
J 006	3-pin single inline header	515-7100-003	R 034	10k ohm ±5% 1206 SMD	569-0115-103
P 001	64-pin DIN male right angle	515-7082-101	S 001	Push-button momentary sw	583-4005-002
P 002	2-pos shorting socket	515-5010-001	S 002	8-pos DIP switch	583-5002-008
P 003	2-pos shorting socket	515-5010-001	S 003	4-pos DIP switch	583-5002-004
P 004	2-pos shorting socket	515-5010-001		-	
P 005	2-pos shorting socket	515-5010-001	U 001	8k x 8 CMOS static RAM	544-5001-109
P 006	2-pos shorting socket	515-5010-001	U 002	Hex inverter SOIC 74HC04	544-3766-004
			U 003	1 of 8 demux 74HC138	544-3766-138
PC310	PC board	035-2000-310	U 004	1 of 8 demux 74HC138	544-3766-138
			U 005	1 of 16 demux SOIC 74HC154	
-	PNP switching SOT-23	576-0003-612	U 006	Quad 2-input OR 74HC32	544-3766-032
Q 003	NPN gen purp SOT-23	576-0001-300	U 007	Quad 2-input OR 74HC32	544-3766-032
D 001	1014 1 150/ 100/ 5147	440 0115 104	U 008	D-latch non-inv 74HC573	544-3766-573
R 001	10M ohm ±5% 1206 SMD	569-0115-106		9 bit x 64 word FIFO DIP-28	544-3764-703
R 002	2.2k ohm ±5% 1206 SMD	569-0115-222		9 bit x 64 word FIFO DIP-28	544-3764-703
R 003	Zero ohm ±5% 1206 SMD	569-0115-001	U 011	12V regulator TO-92 78L12	544-2003-032
R 004 R 005	2k ohm ±5% 1206 SMD	569-0115-202		12V regulator TO-92 78L12	544-2003-032
R 005	150 ohm ±5% 1206 SMD	569-0115-151	U 013		544-5010-448
R 007	200 ohm ±5% 1206 SMD 1.2k ohm ±5% 1/4W CF	569-0115-201		HSDB Multi-Net software	023-9998-289
R 007	1.2k ohm ±5% 1/4W CF	569-0115-122 569-0115-122		Hex open drain buffer SO-14 Driver/receiver RS232C/v28	544-3716-906 544-2023-014
R 009	1.2k ohm ±5% 1/4W CF	569-0115-122	U 017	Micro monitor SO-8 DS1232	
R 010	200 ohm ±5% 1206 SMD	569-0115-201	U 017		544-2003-085 544-5001-412
R 011	1.2k ohm ±5% 1/4W CF	569-0115-122	U 019	Triple line receiver	544-2023-003
R 012	10k ohm ±5% 1206 SMD	569-0115-103	U 020	Quad 2-input NAND 74HC00	544-3766-000
R 012	150 ohm ±5% 1206 SMD	569-0115-151	U 021	7-stage binary cntr SOIC 4024	
R 013	10k ohm ±5% 1206 SMD	569-0115-103	U 021	Prog comm intfc 82C51	544-5001-319
R 015	10k ohm ±5% 1206 SMD	569-0115-103	U 022	Differential bus xcvr SN65176	
R 016	10k ohm ±5% 1206 SMD	569-0115-103		Differential bus xcvr SN65176	
	THE VALUE OF THE PARTY OF THE P			MPC boot code	023-9998-277

SYMBO NUMBE		PART NUMBER	SYMBO NUMB		PART NUMBER
U 026	BCD 7 latch DIP-16 MC14495	544-3014-495	C 122	.022 μF ±5% X7R 1206	510-3609-223
U 027	CPU v25 PLCC-84 MPD7032	544-5002-016	C 123	.047 μF ±5% X7R 1206	510-3609-473
U 028	EEPROM PLCC32R 28C64	544-5002-412	C 124	.0068 μF ±10% X7R chip	510-3606-682
U 029	Dual inline driver	544-2023-002	C 125	680 pF ±2% NPO 1206	510-3616-681
			C 126	.01 μF ±2% NPO 1206	510-3617-103
X 001	10-pos right angle IC socket	515-5008-270	C 127	680 pF ±2% NPO 1206	510-3616-681
X 014	28-pin IC socket	515-5008-018	C 128	.0033 μF ±2% NPO 1206	510-3616-332
X 013	40-pin IC socket	515-5008-019	C 129	470 pF ±2% NPO 1206	510-3616-471
X 024	8-pin DIP socket	515-5008-011	C 130	470 pF ±2% NPO 1206	510-3616-471
X 025	32-pin IC socket	515-5008-108	C 131	.0047 μF ±5% X7R 1206	510-3609-472
X 027	84-pos PLCC socket	515-5020-100	C 132	.0056 μF ±2% NPO 1206	510-3617-562
			C 133	.0047 μF ±2% NPO 1206	510-3616-472
Y 001	10 MHz crystal HC-18	521-0010-000	C 134	20 pF ±5% NPO 1206 chip	510-3602-200
Y 002	11.059 MHz crystal	521-0011-059	C 136	100 pF ±5% NPO 1206	510-3602-101
Y 003	2.4576 MHz HC-18U	521-0002-458	C 137	100 pF ±5% NPO 1206	510-3602-101
Y 004	12 MHz μP crystal	521-0012-000	C 138	.1 μF ±10% X7R chip	510-3606-104
			C 139	.1 μF ±10% X7R chip	510-3606-104
Z 001	EMI suppression filter	532-3003-002	C 140	.1 μF ±10% X7R chip	510-3606-104
Z 002	EMI suppression filter	532-3003-002	C 141	.1 μF ±10% X7R chip	510-3606-104
			C 142	.01 μF ±5% X7R 1206	510-3609-103
	MAIN AUDIO CARD		C 143	.022 μF ±5% X7R 1206	510-3609-223
	PART NO. 023-2000-320	D	C 144	.047 μF ±10% X7R 1206	510-3606-473
			C 145	.0068 μF ±5% X7R 1206	510-3609-682
A 301	Compandor option	023-2000-940	C 146	390 pF ±5% NPO 1206	510-3602-391
C 100	450 E 450/ NDO 100/ 11	510 0 (04)=1	C 147	4700 pF ±2% NPO 1206	510-3616-681
C 100	470 pF ±5% NPO 1206 chip	510-3602-471	C 148	.01 μF ±2% NPO 1206	510-3617-103
C 101 C 102	.0022 μF ±10% X7R 1206	510-3606-222	C 149	4700 pF ±2% NPO 1206	510-3616-472
C 102	.001 μF ±2% NPO 1206	510-3616-102	C 150	.022 μF ±5% X7R 1206	510-3609-223
C 103	.1 μF ±10% X7R chip 100 pF ±2% NPO 1206	510-3606-104	C 151	.1 μF ±10% X7R chip	510-3606-104
C 104	.033 µF ±5% X7R 1210	510-3616-101	C 152	.1 μF \pm 10% X7R chip	510-3606-104
C 103	.068 μF ±5% X7R 1216	510-3610-333 510-3609-683	C 153	.1 μF ±10% X7R chip	510-3606-104
C 100	.022 μF ±5% X7R 1206	510-3609-083	C 154	.1 μF ±10% X7R chip	510-3606-104
C 107	.1 μF ±5% X7R 1206	510-3609-223	C 155	2200 pF ±5% NPO 1206 chip	510-3602-222
C 108	.1 μF ±5% X7R 1206	510-3609-104	C 156 C 157	.1 μF ±10% X7R chip	510-3606-104
C 110	.022 μF ±5% X7R 1206	510-3609-223	C 157	10 pF ±5% NPO 1206 chip	510-3602-100
C 111	.022 μF ±5% X7R 1206	510-3609-223	C 158	10 pF ±5% NPO 1206 chip .047 μF ±10% X7R chip	510-3602-100
C 111	.01 μF ±5% X7R 1206	510-3609-223	C 160	$.1 \mu\text{F} \pm 10\% \text{X/R} \text{chip}$	510-3606-473
C 113	100 pF ±5% NPO 1206 chip	510-3602-101	C 161	.1 μ F ±10% X/R chip .1 μ F ±10% X7R chip	510-3606-104
C 114	100 pF ±5% NPO 1206 chip	510-3602-101	C 162	20 pF ±5% NPO 1206 chip	510-3606-104 510-3602-200
C 115	100 pF ±5% NPO 1206 chip	510-3602-101	C 162	20 pF ±5% NPO 1206 chip	510-3602-200
C 116	.001 μF ±5% NPO 1206	510-3602-101	C 164	.001 μF ±2% NPO 1206	510-3616-102
C 117	.01 μF ±5% X7R 1206	510-3609-103	C 165	360 pF ±5% NPO 1206	510-3610-102
C 118	.01 μF ±5% X7R 1206	510-3609-103	C 170	.01 μF ±10% X7R chip	510-3602-361
C 119	.1 μF ±5% X7R 1206	510-3609-104	C 170	.01 μF ±10% X7R chip	510-3606-103
C 120	.1 μF ±5% X7R 1206	510-3609-104	C 171	.01 μF ±10% X7R chip	510-3606-103
C 121	.01 μF ±5% X7R 1206	510-3609-104	C 172	.01 μF ±10% X7R chip	510-3606-103
			0 173	.o. pr 210/0 21/12 onip	210-2000-103

SYMBO NUMB		PART NUMBER	SYMBO NUMBI	· -	PART NUMBER	_
C 174	.01 μF ±10% X7R chip	510-3606-103	C 221	.01 μF ±10% X7R chip	510-3606-103	
C 175	.01 μF ±10% X7R chip	510-3606-103	C 222	.01 μF ±10% X7R chip	510-3606-103	
C 176	.01 μF ±10% X7R chip	510-3606-103	C 223	.01 μF ±10% X7R chip	510-3606-103	
C 177	.01 μF ±10% X7R chip	510-3606-103	C 224	.01 μF ±10% X7R chip	510-3606-103	
C 178	.01 μF ±10% X7R chip	510-3606-103	C 225	.01 μF ±10% X7R chip	510-3606-103	
C 179	.01 μF ±10% X7R chip	510-3606-103	C 226	.01 μF ±10% X7R chip	510-3606-103	
C 180	.01 μF ±10% X7R chip	510-3606-103	C 227	.01 μF ±10% X7R chip	510-3606-103	
C 181	.01 μF ±10% X7R chip	510-3606-103	C 228	.01 μF ±10% X7R chip	510-3606-103	
C 182	.01 μF ±10% X7R chip	510-3606-103	C 229	.01 μF ±10% X7R chip	510-3606-103	
C 183	.01 μF ±10% X7R chip	510-3606-103	C 230	.01 μF ±10% X7R chip	510-3606-103	
C 184	.01 μF ±10% X7R chip	510-3606-103	C 231	.01 μF ±10% X7R chip	510-3606-103	
C 185	.01 μF ±10% X7R chip	510-3606-103	C 232	.01 µF ±10% X7R chip	510-3606-103	
C 186	.01 μF ±10% X7R chip	510-3606-103	C 233	.01 μF ±10% X7R chip	510-3606-103	
C 187	.01 μF ±10% X7R chip	510-3606-103	C 234	.01 μF ±10% X7R chip	510-3606-103	
C 188	.01 μF ±10% X7R chip	510-3606-103	C 235	1 μF tantalum SMD	510-2625-109	
C 189	.01 μF ±10% X7R chip	510-3606-103	C 236	.001 pF ±2% NPO 1206	510-3616-102	
C 190	.01 μF ±10% X7R chip	510-3606-103	C 237	.033 μF ±5% X7R 1210	510-3610-333	
C 191	.01 μF ±10% X7R chip	510-3606-103	C 238	.047 μF ±5% X7R 1206	510-3609-473	
C 192	.01 μF ±10% X7R chip	510-3606-103	C 239	.068 μF ±5% X7R 1206	510-3609-683	
C 193	.01 μF ±10% X7R chip	510-3606-103	C 240	1 μF tantalum SMD	510-2625-109	
C 194	.01 μF ±10% X7R chip	510-3606-103	C 241	15 μF 20V tantalum SMD	510-2626-150	
C 195	.01 μF ±10% X7R chip	510-3606-103	C 242	15 μF 20V tantalum SMD	510-2626-150	
C 196	.01 μF ±10% X7R chip	510-3606-103	C 243	10 μF 63V axial low temp	510-4363-100	
C 197	.01 μF ±10% X7R chip	510-3606-103	C 244	10 μF 63V axial low temp	510-4363-100	
C 198	.01 μF ±10% X7R chip	510-3606-103	C 245	10 μF 63V axial low temp	510-4363-100	
C 199	.01 μF ±10% X7R chip	510-3606-103	C 246	10 μF 63V axial low temp	510-4363-100	
C 200	.01 μF ±10% X7R chip	510-3606-103	C 247	l μF tantalum SMD	510-2625-109	
C 201	.01 μF ±10% X7R chip	510-3606-103	C 248	10 μF 16V tantalum SMD	510-2625-100	
C 202	.01 μF ±10% X7R chip	510-3606-103	C 249	.1 μF ±10% X7R chip	510-3606-104	
C 203	.01 μF ±10% X7R chip	510-3606-103	C 251	15 μF 20V tantalum SMD	510-2626-150	
C 204	.01 μF ±10% X7R chip	510-3606-103	C 254	.1 μF ±10% X7R 1206	510-3606-104	
C 205	.01 μF ±10% X7R chip	510-3606-103	C 255	47 μF 10V tantalum SMD	510-2624-470	
C 206	.01 μF ±10% X7R chip	510-3606-103	C 256	15 μF 20V tantalum SMD	510-2626-150	
C 207	1 μF tantalum SMD	510-2625-109	C 257	47 μF 10V tantalum SMD	510-2624-470	
C 208	.01 μF ±10% X7R chip	510-3606-103	C 258	47 μF 10V tantalum SMD	510-2624-470	
C 209	.01 μF ±10% X7R chip	510-3606-103	C 262	.01 μF ±10% X7R chip	510-3606-103	
C 210	.01 μF ±10% X7R chip	510-3606-103	C 263	.01 μF ±10% X7R chip	510-3606-103	
C 211	.01 μF ±10% X7R chip	510-3606-103	C 264	.01 μF ±10% X7R chip	510-3606-103	
C 212	.01 μF ±10% X7R chip	510-3606-103	C 265	.01 μF ±10% X7R chip	510-3606-103	
C 213	.01 μF ±10% X7R chip	510-3606-103	C 266	.01 μF ±10% X7R chip	510-3606-103	
C 214	.01 μF ±10% X7R chip	510-3606-103	C 267	47 μF 10V tantalum SMD	510-2624-470	
C 215	.01 μF ±10% X7R chip	510-3606-103	C 268	47 μF 10V tantalum SMD	510-2624-470	
C 216	.01 μF ±10% X7R chip	510-3606-103	C 269	47 μF 10V tantalum SMD	510-2624-470	
C 217	.01 μF ±10% X7R chip	510-3606-103	C 270	47 μF 10V tantalum SMD	510-2624-470	
C 218	.01 μF ±10% X7R chip	510-3606-103	C 271	.01 μF ±10% X7R chip	510-3606-103	
C 219	.01 μF ±10% X7R chip	510-3606-103	C 272	.01 μF ±10% X7R chip	510-3606-103	_
C 220	.01 μF ±10% X7R chip	510-3606-103	C 273	.01 μF ±10% X7R chip	510-3606-103	

SYMBO		PART	SYMB	SYMBOL		PART
NUMB	ER <u>DESCRIPTION</u>	NUMBER	NUME		DESCRIPTION	NUMBER
C 276	.0022 μF ±2% NPO 1206	510-3616-222	CBII	0 1637	COT 22	*** ***
C 277	.0047 μF ±2% NPO 1206	510-3616-222		8 15V zener		523-2016-150
C 278	.0068 μF ±2% NPO 1206	510-3617-682	1	9 5.1V zener		523-2016-519
C 279	.22 μF ±5% X7R 1210	510-3610-224	CRIZ	0 5.1V zener	SO1-23	523-2016-519
C 280	.022 μF ±5% X7R 1206		EDIO			
C 281	820 pF ±2% NPO 1206	510-3609-223	EPIU	Crystal pin	insulator	018-1080-001
C 282	.1 μF ±10% X7R 1206	510-3616-821	1133707	NID 16 .		
C 283	.1 μF ±10% X7R 1206	510-3606-104	,) Panel faster		537-0011-031
C 284	220 µF electrolytic axial	510-3606-104		1 Card inj/ex		537-9057-020
C 285	470 μF electrolytic axial	510-4325-221		2 Rivet snap		574-9015-050
C 286	10 μF tantalum SMD	510-4316-471	HWIL	3 PC board e	jector & handle	537-9057-025
C 287	300 pF ±5% NPO 1206	510-2625-100	1 100			
C 288	300 pF ±5% NPO 1206	510-3602-301	J 100		contal tip jack .080	105-2204-105
C 289	300 pF ±5% NPO 1206	510-3602-301 510-3602-301	J 101	-	k 0.1 enclosed	515-2002-012
C 290	300 pF ±5% NPO 1206	510-3602-301	J 102	3.6mm jack		515-2001-011
C 291	.1 μF ±5% X7R 1206	510-3609-104	J 103		tip jack .080	105-2203-101
C 292	360 pF ±5% NPO 1206	510-3602-361	J 104	3.6mm jack		515-2001-011
C 293	68 pF ±5% NPO 1206	510-3602-361	J 105		inline header	515-7100-003
C 294	.1 μF ±5% X7R 1206	510-3609-104	J 106	5-pin single	inline header	515-7100-005
C 295	220 μF electrolytic aluminum	510-3609-104	MOO	I Camer 11	1	
C 296	10 μF 16V tantalum SMD	510-2625-100	MIPUU	l Control kno	סס	032-0792-010
C 297	.0039 μF ±2% NPO 1206	510-3616-392	P 100	22i DDI		
C 298	.0033 μF ±2% NPO 1206	510-3616-332	P 101	52-pin DiN	male right angle	515-7082-102
C 299	.01 μ F ±10% X7R chip	510-3606-103	P 101	2-pos shorti	male right angle	515-7082-101
C 300	.0056 μF ±2% NPO 1210	510-3617-562	1 102	2-pos snorti	ilg socket	515-5010-001
C 301	.0047 μF ±2% NPO 1206	510-3616-472	PC200	PC board		025 2000 220
C 302	.0033 μF ±2% NPO 1206	510-3616-332	1 0200	1 C board		035-2000-320
C 303	.0039 μF ±2% NPO 1206	510-3616-392	Q 101	Si PNP SOT	T-23 2N3906	576-0003-657
C 304	.1 μF ±10% X7R 1206 chip	510-3606-104	Q 101		Γ-23 2N3904	576-0003-658
C 305	10 μF tantalum SMD	510-2625-100	Q 102	01111110	1-23 2113904	370-0003-038
			R 101	29.4k ohm ±	1% 1206 SMD	569-0111-446
CR100	Switching diode SOT-23	523-1504-002	R 102		1% 1206 SMD	569-0111-517
	Dual switching diode SOT-23	523-1504-023	R 103		1% 1206 SMD	569-0111-482
CR102	Dual switching diode SOT-23	523-1504-023	R 104		% 1206 SMD	569-0111-418
CR103	Dual switching diode SOT-23	523-1504-023	R 105		% 1206 SMD	569-0111-201
	Dual switching diode SOT-23	523-1504-023	R 106		±1% 1206 SMD	569-0111-604
	Dual switching diode SOT-23	523-1504-023	R 107		±1% 1206 SMD	569-0111-604
	Switching diode SOT-23	523-1504-002	R 108	110 ohm ±19	% 1206 SMD	569-0111-205
	4.3V zener SOT-23	523-2016-439	R 109		±1% 1206 SMD	569-0111-604
	UHF/VHF band switch SOT	523-1504-012	R 110		% 1206 SMD	569-0111-205
CR109	UHF/VHF band switch SOT	523-1504-012	R 111		1% 1206 SMD	569-0111-426
	UHF/VHF band switch SOT	523-1504-012	R 112		% 1206 SMD	569-0115-473
	2.4V 1W zener	523-2505-249	R 113		5% 1206 SMD	569-0115-154
	2.4V 1W zener	523-2505-249	R 114		% 1206 SMD	569-0115-183
	15V zener SOT-23	523-2016-150	R 115	47k ohm ±5%		569-0115-473
	15V zener SOT-23	523-2016-150	R 116		% 1206 SMD	569-0115-152
CR117	15V zener SOT-23	523-2016-150	R 117		% 1206 SMD	569-0115-622
		1				. —

SYMBO NUMBI		PART NUMBER	SYMBO NUMBI		PART NUMBER
R 118	12k ohm ±5% 1206 SMD	569-0115-123	R 169	54.9k ohm ±1% 1206 SMD	569-0111-472
R 119	47k ohm ±5% 1206 SMD	569-0115-473	R 170	1M ohm ±5% 1206 SMD	569-0115-105
R 120	10k ohm ±5% 1206 SMD	569-0115-103	R 171	10k ohm ±5% 1206 SMD	569-0115-103
R 121	47k ohm ±5% 1206 SMD	569-0115-473	R 172	10k ohm ±5% 1206 SMD	569-0115-103
R 122	10k ohm ±5% 1206 SMD	569-0115-103	R 173	430k ohm ±5% 1206 SMD	569-0115-434
R 123	330k ohm ±5% 1206 SMD	569-0115-334	R 174	160k ohm ±5% 1206 SMD	569-0115-164
R 124	1M ohm ±5% 1206 SMD	569-0115-105	R 175	4.3k ohm ±5% 1206 SMD	569-0115-432
R 125	100k ohm ±5% 1206 SMD	569-0115-104	R 176	6.8k ohm ±5% 1206 SMD	569-0115-682
R 126	100k ohm ±5% 1206 SMD	5 69- 0115-104	R 177	100k ohm ±5% 1206 SMD	569-0115-104
R 127	470k ohm ±5% 1206 SMD	569-0115-474	R 178	100k ohm ±5% 1206 SMD	569-0115-104
R 128	100k ohm ±5% 1206 SMD	569-0115-104	R 179	300 ohm ±5% 1206 SMD	569-0115-301
R 129	47k ohm ±5% 1206 SMD	569-0115-473	R 180	300 ohm ±5% 1206 SMD	569-0115-301
R 130	100k ohm ±5% 1206 SMD	569-0115-104	R 181	100k ohm ±5% 1206 SMD	569-0115-104
R 131	56k ohm ±5% 1206 SMD	569-0115-563	R 182	100k ohm ±5% 1206 SMD	569-0115-104
R 132	56k ohm ±5% 1206 SMD	569-0115-563	R 183	300 ohm ±5% 1206 SMD	569-0115 - 301
R 133	100k ohm ±5% 1206 SMD	569-0115-104	R 184	300 ohm ±5% 1206 SMD	569-0115-301
R 134	100k ohm ±5% 1206 SMD	569-0115-104	R 185	75k ohm ±1% 1206 SMD	569-0111 -48 5
R 135	47k ohm ±5% 1206 SMD	569-0115-473	R 186	75k ohm ±1% 1206 SMD	569-0111-485
R 136	10k ohm ±5% 1206 SMD	569-0115-103	R 187	75k ohm ±1% 1206 SMD	569-0111-485
R 137	121k ohm ±1% 1206 SMD	569-0111-509	R 188	75k ohm ±1% 1206 SMD	569-0111-485
R 138	121k ohm ±1% 1206 SMD	569-0111-509	R 189	300 ohm ±5% 1206 SMD	569-0115-301
R 139	35.7k ohm ±1% 1206 SMD	569-0111-454	R 190	300 ohm ±5% 1206 SMD	569-0115-301
R 140	27.4k ohm ±1% 1206 SMD	569-0111-443	R 191	75k ohm ±1% 1206 SMD	569-0111-485
R 141	22.6k ohm ±1% 1206 SMD	569-0111-435	R 192	75k ohm ±1% 1206 SMD	569-0111-485
R 142	17.4k ohm ±1% 1206 SMD	569-0111-424	R 193	75k ohm ±1% 1206 SMD	569-0111-485
R 143 R 144	3.3k ohm ±5% 1206 SMD 1k ohm ±5% 1206 SMD	569-0115-332 569-0115-102	R 194	75k ohm ±1% 1206 SMD 300 ohm ±5% 1206 SMD	569-0111-485
R 144	150k ohm ±5% 1206 SMD	569-0115-102 569-0115-154	R 195 R 196	300 ohm ±5% 1206 SMD	569-0115-301 569-0115-301
R 150	86.6k ohm ±1% 1206 SMD	569-0111-491	R 190	910 ohm ±5% 1206 SMD	569-0115-911
R 151	43.2k ohm ±1% 1206 SMD	569-0111-462	R 198	100k ohm ±5% 1206 SMD	569-0115-104
R 152		569-0115-223	R 199	10k ohm ±5% 1206 SMD	569-0115-103
R 153	43k ohm ±5% 1206 SMD	569-0115-433	R 200	1M ohm ±5% 1206 SMD	569-0115-105
	43k ohm ±5% 1206 SMD	569-0115-433	R 201	270k ohm ±5% 1206 SMD	569-0115-274
R 155	82k ohm ±5% 1206 SMD	569-0115-823	R 202	1M ohm ±5% 1206 SMD	569-0115-105
R 156	82k ohm ±5% 1206 SMD	569-0115-823	R 203	620 ohm ±5% 1206 SMD	569-0115-621
R 157	82k ohm ±5% 1206 SMD	569-0115-823	R 204	47k ohm ±5% 1206 SMD	569-0115-473
R 158	82k ohm ±5% 1206 SMD	569-0115-823	R 205	7.5k ohm ±5% 1206 SMD	569-0115-752
R 159		569-0111-343	R 206	10k ohm ±5% 1206 SMD	569-0115-103
R 160	1.1k ohm ±1% 1206 SMD	569-0111-305	R 207	10k ohm ±5% 1206 SMD	569-0115-103
R 161	3.01k ohm ±1% 1206 SMD	569-0111-347	R 208	10k ohm ±5% 1206 SMD	569-0115-103
R 162	18.2k ohm ±1% 1206 SMD	569-0111-426	R 209	10k ohm ±5% 1206 SMD	569-0115-103
R 163	100k ohm ±5% 1206 SMD	569-0115-104	R 210	10k ohm ±5% 1206 SMD	569-0115-103
R 164	100k ohm ±5% 1206 SMD	569-0115-104	R 211	100 ohm ±5% 1206 SMD	569-0115-101
R 165	47k ohm ±5% 1206 SMD	569-0115-473	R 212	1k ohm ±5% 1206 SMD	569-0115-102
R 166	56k ohm ±5% 1206 SMD	569-0115-563	R 213	5.1k ohm ±5% 1206 SMD	569-0115-512
R 167	56k ohm ±5% 1206 SMD	569-0115-563	R 214	3.9k ohm ±5% 1206 SMD	569-0115-392
R 168	2.2k ohm ±5% 1206 SMD	569-0115-222	R 215	1k ohm ±5% 1206 SMD	569-0115-102

SYMBO NUMBE		PART NUMBER	SYMBO NUMBI	-	PART NUMBER
D 016	1011 150/ 120/ CMD	660 0116 102	D 260	2611 150/ 1206 CMD	560 0115 262
R 216	10k ohm ±5% 1206 SMD	569-0115-103	R 269	36k ohm ±5% 1206 SMD 39k ohm ±5% 1206 SMD	569-0115-363
R 217	100 ohm ±5% 1206 SMD	569-0115-101	R 270 R 271		569-0115-393
R 218	82k ohm ±5% 1206 SMD	569-0115-823		180k ohm ±5% 1206 SMD	569-0115-184
R 219	180k ohm ±5% 1206 SMD	569-0115-184	R 274	36k ohm ±5% 1206 SMD	569-0115-363
R 220	16k ohm ±5% 1206 SMD	569-0115-163	R 275	36k ohm ±5% 1206 SMD	569-0115-363
R 223	6.8k ohm ±5% 1206 SMD	569-0115-682	R 276	18k ohm ±5% 1206 SMD	569-0115-183
R 225	10k ohm ±5% 1206 SMD	569-0115-103	R 277	5.1k ohm ±5% 1206 SMD	569-0115-512
R 226	10k ohm ±5% 1206 SMD	569-0115-103	R 279	150k ohm ±5% 1206 SMD	569-0115-154
R 227	10k ohm ±5% 1206 SMD	569-0115-103	R 280	150k ohm ±5% 1206 SMD	569-0115-154
R 228	5.1k ohm ±1% 1206 SMD	569-0111-512	R 281	1M ohm ±5% 1206 SMD	569-0115-105
R 229	1k ohm ±5% 1206 SMD	569-0115-102	R 282	10k ohm ±5% 1206 SMD	569-0115-103
R 230	7.5k ohm ±5% 1206 SMD	569-0115-752	R 283	Zero ohm ±5% 1206 SMD	569-0115-001
R 231	10k ohm ±5% 1206 SMD	569-0115-103	R 284	10k ohm ±5% 1206 SMD	569-0115-103
R 232	100 ohm ±5% 1/4W CF	569-0513-101	R 285	2.2k ohm ±5% 1206 SMD	569-0115-222
R 233	100k ohm multi-turn pot	562-0110-104	R 286	75k ohm ±5% 1206 SMD	569-0115-753
R 234	100k ohm multi-turn pot	562-0110-104	R 287	100 ohm ±5% 1/4W CF	569-0513-101
R 235	100k ohm multi-turn pot	562-0110-104	R 288	220 ohm ±5% 1206 SMD	569-0115-221
R 236	10k ohm Vol/Audio switch	562-0018-044	R 289	2.2 ohm $\pm 10\%$ 1206 SMD	569-0115-229
R 237	100k ohm multi-turn pot	562-0110-104	R 290	1 ohm ±10% 1206 SMD	569-0115-109
R 238	100k ohm multi-turn pot	562-0110-104	R 291	1k ohm ±5% 1206 SMD	569-0115-102
R 239	100k ohm multi-turn pot	562-0110-104	R 292	39 ohm ±5% 1206 SMD	569-0115-390
R 240	100k ohm multi-turn pot	562-0110-104	R 293	6.2k ohm ±5% 1206 SMD	569-0115-622
R 241	100k ohm multi-turn pot	562-0110-104	R 294	1k ohm ±5% 1206 SMD	569-0115-102
R 242	100k ohm multi-turn pot	562-0110-104	R 295	10k ohm ±5% 1206 SMD	569-0115-103
R 243	100k ohm multi-turn pot	562-0110-104	R 296	10k ohm ±5% 1206 SMD	569-0115-103
R 244	100k ohm multi-turn pot	562-0110-104	R 297	10k ohm ±5% 1206 SMD	569-0115-103
R 247	54.9k ohm ±1% 1206 SMD	569-0111-472	R 298	10k ohm ±5% 1206 SMD	569-0115-103
R 248	120k ohm ±5% 1206 SMD	569-0115-124	R 299	10k ohm ±5% 1206 SMD	569-0115-103
R 249	36k ohm ±5% 1206 SMD	569-0115-363	R 300	36k ohm ±5% 1206 SMD	569-0115-363
R 250	270k ohm ±5% 1206 SMD	569-0115-274	R 301	100k ohm multi-turn pot	562-0110-104
R 251	51k ohm ±5% 1206 SMD	569-0115-513	R 302	36k ohm ±5% 1206 SMD	569-0115-363
R 252	43k ohm ±5% 1206 SMD	569-0115-433	R 303	240 ohm ±5% 1206 SMD	569-0115-241
R 253	390k ohm ±5% 1206 SMD	569-0115-394	R 304	27 ohm ±5% 1206 SMD	569-0115-270
R 254	47k ohm ±5% 1206 SMD	569-0115-473	R 305	100k ohm multi-turn pot	562-0110-104
R 256	36k ohm ±5% 1206 SMD	569-0115-363	R 306	36k ohm ±5% 1206 SMD	569-0115-363
R 257	36k ohm ±5% 1206 SMD	569-0115-363	R 307	36k ohm ±5% 1206 SMD	569-0115-363
R 258	2.2k ohm ±5% 1206 SMD	569-0115-222	R 308	909k ohm ±1% 1206 SMD	569-0111-593
R 259	10k ohm ±5% 1206 SMD	569-0115-103	R 309	25.5k ohm ±1% 1206 SMD	569-0111-440
R 260	36k ohm ±5% 1206 SMD	569-0115-363	R 310	Zero ohm ±10% 1206 SMD	569-0115-001
R 261	300k ohm ±5% 1206 SMD	569-0115-304	R 311	Zero ohm ±10% 1206 SMD	569-0115-001
R 262	2.2k ohm ±5% 1206 SMD	569-0115-222	R 312	Zero ohm ±10% 1206 SMD	569- 0115-001
R 263	10k ohm ±5% 1206 SMD	569-0115-103	R 313	Zero ohm ±10% 1206 SMD	569-0115-001
R 264	10k ohm ±5% 1206 SMD	569-0115-103	R 314	43.2k ohm ±1% 1206 SMD	569-0111-462
R 265	2.2k ohm ±5% 1206 SMD	569-0115-222	R 315	86.6k ohm ±1% 1206 SMD	569-0111-491
R 266	10k ohm ±5% 1206 SMD	569-0115-103	R 316	25.5k ohm ±1% 1206 SMD	569-0111-440
R 267	2.2k ohm ±5% 1206 SMD	569-0115-222	R 317	909k ohm ±1% 1206 SMD	569-0111-593
R 268	36k ohm ±5% 1206 SMD	569-0115-363	R 318	10k ohm ±5% 1206 SMD	569-0115-103
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SYMBO NUMBE		PART NUMBER	SYMBO NUMBE		PART NUMBER
R 319	10k ohm ±5% 1206 SMD	569-0115-103	U 153	Quad analog sw SPST SO-16	544-3003-001
R 320	180k ohm ±5% 1206 SMD	569-0115-184	U 154	Quad 2-in OR SOIC 74HC32	544-3766-032
R 321	100 ohm ±5% 1206 SMD	569-0115-101	U 155	D flip flop SOIC 74HC574	544-3766-574
R 322	Zero ohm ±5% 1206 SMD	569-0115-001	U 156	D flip flop SOIC 74HC574	544-3766-574
R 323	Zero ohm ±5% 1206 SMD	569-0115-001	U 157	D flip flop SOIC 74HC574	544-3766-574
10 323			U 158	Quad analog sw SOIC DG202	544-3003-001
RT100	10k ohm chip thermistor	569-3013-007	U 159	Quad analog sw SOIC DG202	544-3003-001
•	F		U 160	9 bit x 64 word FIFO DIP-28	544-3764-703
S 100	8-pos DIP switch	583-5002-008	U 161	9 bit x 64 word FIFO DIP-28	544-3764-703
S 101	4-pos DIP switch	583-5002-004	U 162	Dr/Rcvr RS232C V.28 145406	544-2023-014
	P		U 163	Dual op amp SOIC LM2904	544-2019-004
U 100	Quad 2-input NOR	544-3766-002	U 164	Dual op amp SOIC LM2904	544-2019-004
U 101	Hex inverter SOIC 74HC04	544-3766-004	U 165	Dual op amp SOIC LM2904	544-2019-004
U 102	1 of 8 demux 74HC138	544-3766-138	U 166	Dual op amp SO-8 MC33178	544-2019-018
U 103	1 of 16 demux SOIC 74HC154	544-3766-154	U 167	Quad op amp SOIC MC3404	544-2020-008
U 104	D-latch non-inverting SOIC	544-3766-573			
U 105	D-latch non-inverting SOIC	544-3766-573	X 111	40-pin IC socket	515-5008-019
U 106	D flip flop SOIC 74HC574	544-3766-574	X 112	28-pin IC socket	515-5008-018
U 107	D flip flop SOIC 74HC574	544-3766-574	Y 100	2.4576 MHz crystal HC-18U	521-0002-458
U 108	D flip flop SOIC 74HC574	544-3766-574	Y 101	11.059 MHz crystal	521-0011-059
U 111	EEPROM masked DIP-40	544-5010-448			
U 112	Main Audio Card/LTR	023-9998-291	Z 100	EMI suppression filter	532-3003-002
U 113	Quad analog sw SPST SO-16	544-3003-001	Z 101	EMI suppression filter	532-3003-002
U 114	Quad analog sw SPST SO-16	544-3003-001	Z 102	EMI suppression filter	532-3003-002
U 115	Quad analog sw SPST SO-16	544-3003-001			
U 116	Quad analog sw SPST SO-16	544-3003-001		INTERFACE ALARM CA	
U 117	Quad analog sw SPST SO-16	544-3003-001		PART NO. 023-2000-35	V
U 118	Quad analog sw SPST SO-16	544-3003-001	0.500	01 E 1100/3/70 11	510 2606 102
U 119	Micro monitor SO-8 DS1232	544-2003-085	C 500	.01 μF ±10% X7R chip	510-3606-103
U 120	Dual op amp SOIC LM2904	544-2019-004	C 501	.015 μF ±10% X7R chip	510-3606-153
U 121	Dual op amp SOIC LM2904	544-2019-004	C 502	.1 μF ±10% X7R 1210	510-3607-104
U 122	Quad op amp SOIC MC3403	544-2020-008 544-2020-008	C 503	150 pF ±5% NPO 1206 chip	510-3602-151 510-2625-100
U 123	Quad op amp SOIC MC3403	544-2019-004	C 504 C 505	10 μFD 16V tantalum SMD 10 μFD 16V tantalum SMD	510-2625-100
U 124	Dual op amp SOIC LM2904	544-2020-008	C 506	10 μFD 16V tantalum SMD	510-2625-100
U 125	Quad op amp SOIC MC3404	544-2020-008	C 507	10 μFD 16V tantalum SMD	510-2625-100
U 126 U 127	Quad op amp SOIC MC3404 Quad op amp SOIC MC3404	544-2020-008	C 508	33 μF 10V tantalum SMD	510-2624-330
U 128	Quad op amp SOIC MC3404 Quad op amp SOIC MC3404	544-2020-008	C 509	1 μF 16V tantalum SMD	510-2625-109
U 129	Quad op amp SOIC MC3404 Quad op amp SOIC MC3404	544-2020-008	C 510	33 µF 10V tantalum SMD	510-2624-330
U 130	Dual op amp SOIC LM2904	544-2019-004	C 511	.01 μF ±10% X7R chip	510-3606-103
U 131	Quad op amp SOIC MC3404	544-2020-008	C 512	.01 μF ±10% X7R chip	510-3606-103
U 132	Audio amp 10W TO-220	544-2006-013	C 513	.01 μ F ±10% X7R chip	510-3606-103
U 133	1 of 16 demux SOIC 74HC154		C 514	.01 μF ±10% X7R chip	510-3606-103
U 135	Dual op amp SO-8 MC33178	544-2019-018	C 515	.01 μF ±10% X7R chip	510-3606-103
U 136	+5V regulator SOIC 78L08	544-2603-042	C 516	.01 μ F ±10% X7R chip	510-3606-103
U 149	EEPOT 100k SOIC 9C104	544-0004-209	C 517	.01 μF ±10% X7R chip	510-3606-103
U 151		544-0004-209	C 518	.01 μF ±10% X7R chip	510-3606-103
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SYMBO NUMBI		PART NUMBER	SYMBO NUMB		PART NUMBER
C 519	.01 μF ±10% X7R chip	510-3606-103	CR533	3 15V zener SOT-23	523-2016-150
C 520	.1 μF ±10% X7R chip	510-3607-104		4 15V zener SOT-23	523-2016-150
C 521	.01 μF ±10% X7R chip	510-3606-103	1	5 4.3V zener SOT-23	
C 522	47 μF 25V electrolytic radial	510-4425-470	!	5 4.5 V zener SOT-23	523-2016-439
C 523	47 μF 25V electrolytic radial	510-4425-470		7 15V zener SOT-23	523-2016-150
C 524	10 μFD 16V tantalum SMD	510-2625-100	CKJ3.	7 13 V Zener SO1-23	523-2016-150
C 525	10 μFD 16V tantalum SMD	510-2625-100	F 501	1A 250V submin fuse	624 0017 014
C 526	1 μF 16V tantalum SMD	510-2625-109	1 701	1A 250 V Submitt Tuse	534-0017-014
C 527	.1 μF 35V tantalum SMD	510-2628-108	EUSAI	Fuse holder	524 1017 001
C 528	.01 μF ±10% X7R chip	510-3606-103	10001	ruse noider	534-1017-001
C 529	.01 μ F ±10% X7R chip	510-3606-103	LIMEO	0 Cand :=:/aux ===1== ===11	527 0057 000
C 530	220 μF electrolytic axial	510-4325-221	nwsu	0 Card inj/ext nylon pull	537-9057-020
C 531	.01 µF ±10% X7R chip	510-3606-103	J 500	Harimantal annua dia ingle 000	105 2004 105
C 532	1000 μF electrolytic	510-4350-103	J 500	Horizontal green tip jack .080	105-2204-105
C 533	.01 μF ±10% X7R chip	510-3606-103	J 502	Horizontal black tip jack .080	105-2203-101
C 533	100 pF ±5% NPO 1206	510-3602-103	J 502 J 503	Horizontal red tip jack .080	105-2202-101
C 535	100 pF ±5% NPO 1206	510-3602-101	J 503	3-pin single inline header	515-7100-003
C 536	.1 μF ±10% X7R 1210	510-3607-104		3-pin single inline header	515-7100-003
C 537	.1 μF ±10% X7R 1210	510-3607-104	J 505	4-pin single inline header	515-7100 - 004
C 538	.01 μF ±10% X7R chip	510-3606-103	17 500	1037 CDDT 1 4 1 1 1	
C 539	.01 μF ±10% X7R chip	510-3606-103	K 500	12V SPDT 1A relay submin	567-2002-021
C 337	.or pr 11070 X/R cmp	310-3000-103	K 501	12V SPDT 1A relay submin	567-2002-021
CR 500	Red LED submin radial	549-4001-120	K 502	12V SPDT 1A relay submin	567-2002-021
	Green LED submin radial	549-4001-120	K 503	12V SPDT 1A relay submin	567-2002-021
	Yellow LED submin radial	549-4001-121	L 501	2 ull filter shales DC	540 5005 001
	Green LED submin radial	549-4001-121	L 301	3 μH filter choke PC mount	542-5007-031
	Green LED submin radial	549-4001-122	P 500	64-pin DIN male right angle	£1.5 7000 101
	Yellow LED submin radial	549-4001-121	P 501	32-pin DIN male right angle	515-7082-101
	Dual switch diode SOT-23	523-1504-023	P 503	2-pos shorting socket	515-7082-102
	Dual switch diode SOT-23	523-1504-023	P 504	2-pos shorting socket	515-5010-001
	Dual switch diode SOT-23	523-1504-023	P 505	2-pos shorting socket	515-5010-001
	Dual switch diode SOT-23	523-1504-023	1 303	2-pos shorting socket	515-5010-001
	Dual switch diode SOT-23	523-1504-023	PC500	PC board	035-2000-350
	Dual switch diode SOT-23	523-1504-023	1 0300	i C board	033-2000-330
	Dual switch diode SOT-23	523-1504-023	O 500	Si NPN SOT-23 2N3904	576-0003-658
	Dual switch diode SOT-23	523-1504-023	Q 501	Si NPN SOT-23 2N3904	576-0003-658
	5.1V zener SOT-23	523-2016-519	-	Si NPN SOT-23 2N3904	576-0003-658
	Green LED submin radial	549-4001-122	Q 502 Q 503	Si NPN SOT-23 2N3904	576-0003-658
	Green LED submin radial	549-4001-122	Q 503	NPN dig SOT-23F RN1404	576-0003-638
	Green LED submin radial	549-4001-122	-	NPN dig SOT-23F RN1404	576-0003-616
	200V 1.5A rectifier 1N4818	523-0013-201	Q 303	NFN dig 501-23F KN1404	3/0-0003-010
	5.1V zener SOT-23	523-2016-519	R 500	4.7k ohm ±5% 1206 SMD	560 0115 470
	5.1V zener SOT-23	523-2016-519	R 501	4.7k ohm ±5% 1206 SMD	569-0115-472
	15V zener SOT-23	523-2016-150	R 501	430 ohm ±5% 1/4W CF	569-0115-472
	15V zener SOT-23	523-2016-150	R 502	5.1k ohm ±5% 1206 SMD	569-0513-431
	15V zener SOT-23	523-2016-150	R 503	1k ohm ±5% 1206 SMD	569-0115-512
	15V zener SOT-23	523-2016-150	R 504	2k ohm ±5% 1206 SMD	569-0115-102
V	12 · Loner CO 1-23	J2J-2010-1JU	K JUJ	2K UHH 1376 1200 SML)	569-0115-202

SYMBO NUMBI		PART NUMBER	SYMBO NUMBI		PART NUMBER
R 506	1k ohm ±5% 1206 SMD	569-0115-102	R 554	1.2k ohm ±5% 1206 SMD	569-0115-122
R 507	100k ohm ±5% 1206 SMD	569-0115-104	R 555	1.2k ohm ±5% 1206 SMD	569-0115-122
R 508	10k ohm ±1% 1206 SMD	569-0111-401	R 556	10k ohm ±5% 1206 SMD	569-0115-103
R 509	10k ohm ±1% 1206 SMD	569-0111-401	R 557	10k ohm ±5% 1206 SMD	569-0115-103
R 510	10k ohm ±5% 1206 SMD	569-0115-103	R 558	10k ohm ±5% 1206 SMD	569-0115-103
R 511	20k ohm ±5% 1206 SMD	569-0115-203	R 559	10k ohm ±5% 1206 SMD	569-0115-103
R 512	10k ohm ±5% 1206 SMD	569-0115-103	R 560	10k ohm ±5% 1206 SMD	569-0115-103
R 513	10k ohm ±5% 1206 SMD	569-0115-103	R 561	10k ohm ±5% 1206 SMD	569-0115-103
R 514	10k ohm ±5% 1206 SMD	569-0115-103	R 562	10k ohm ±5% 1206 SMD	569-0115-103
R 515	1k ohm ±5% 1206 SMD	569-0115-102	R 563	3.9k ohm ±5% 1206 SMD	569-0115-392
R 516	2.7k ohm ±5% 1/4W CF	569-0115-272	R 564	1k ohm ±5% 1206 SMD	569-0115-102
R 517	2.7k ohm ±5% 1/4W CF	569-0115-272	R 567	200 ohm ±5% 1206 SMD	569-0115-201
R 518	2.7k ohm ±5% 1/4W CF	569-0115-272	R 568	200 ohm ±5% 1206 SMD	569-0115-201
R 519	2.7k ohm ±5% 1/4W CF	569-0115-272	R 569	200 ohm ±5% 1206 SMD	569-0115-201
R 520	2.7k ohm ±5% 1/4W CF	569-0115-272	R 570	1k ohm ±5% 1206 SMD	569-0115-102
R 521	4.7k ohm ±5% 1206 SMD	569-0115-472	R 571	10k ohm ±5% 1206 SMD	569-0115-103
R 522	10k ohm ±1% 1206 SMD	569-0111-401	R 572	16k ohm ±5% 1206 SMD	569-0115-163
R 523	10k ohm ±1% 1206 SMD	569-0111-401	R 573	5.1k ohm ±5% 1206 SMD	569-0115-512
R 524	4.7k ohm ±5% 1206 SMD	569-0115-472	R 574	51k ohm ±5% 1206 SMD	569-0115-513
R 525	10k ohm ±1% 1206 SMD	569-0111-401	R 575	82k ohm ±5% 1206 SMD	569-0115-823
R 526	10k ohm ±1% 1206 SMD	569-0111-401	R 576	2.7k ohm ±5% 1206 SMD	569-0115-272
R 527	4.7k ohm ±5% 1206 SMD	569-0115-472	R 577	1k ohm ±5% 1206 SMD	569-0115-102
R 528	1.2k ohm ±5% 1206 SMD	569-0115-122	R 578	2.7k ohm ±5% 1206 SMD	569-0115-272
R 529	4.7k ohm ±5% 1206 SMD	569-0115-472			
R 530	10k ohm ±1% 1206 SMD	569-0111-401	S 500	4-pos recessed DIP switch	583-5002-104
R 531	4.32k ohm ±1% 1206 SMD	569-0111-362	S 501	4-pos recessed DIP switch	583-5002-104
R 532	4.7k ohm ±5% 1206 SMD	569-0115-472	S 502	4-pos recessed DIP switch	583-5002-104
R 533 R 534	1k ohm ±5% 1206 SMD 1M ohm ±5% 1206 SMD	569-0115-102	S 503	4-pos recessed DIP switch	583-5002-104
R 535	4.7k ohm ±5% 1206 SMD	569-0115-105 569-0115-472	S 508	Toggle switch on/on rt angle	583-0006-014
R 536	10k ohm ±5% 1206 SMD	569-0115-103	U 500	1 of 16 demux SOIC 74HC154	544 2766 15A
R 538	100k ohm ±5% 1206 SMD	569-0115-104	U 501	1 of 16 demux SOIC 74HC154	
R 539	100k ohm ±5% 1206 SMD	569-0115-104	U 503		544-3766 - 574
R 540	100k ohm ±5% 1206 SMD	569-0115-104		D flip flop SOIC 74HC574	544-3766-574
R 541	200 ohm ±5% 1206 SMD	569-0115-201	U 505	D flip flop SOIC 74HC574	544-3766-574
	10k ohm ±5% 1206 SMD	569-0115-103	U 506	8-bit A/D converter	544-2031-001
R 543	10k ohm ±5% 1206 SMD	569-0115-103	U 507	Bilateral switch SOIC 4066B	544-3016-066
R 544	1k ohm ±5% 1206 SMD	569-0115-102	U 508	Hex open drain buffer SO-14	544-3716-906
R 545	10k ohm ±5% 1206 SMD	569-0115-103	U 509	-	544-2020-008
R 546	430 ohm ±5% 1/4W CF	569-0513-431	U 510	NPN out opto isolator 4N35	544-2010-001
R 547	430 ohm ±5% 1/4W CF	569-0513-431	U 511	NPN out opto isolator 4N35	544-2010-001
R 548	430 ohm ±5% 1/4W CF	569-0513-431	U 512	NPN out opto isolator 4N35	544-2010-001
R 549	10k ohm ±5% 1206 SMD	569-0115-103	U 513	Bilateral switch SOIC 4066B	544-3016-066
R 550	10k ohm ±5% 1206 SMD	569-0115-103	U 514	Dual op amp SOIC LM2904	544-2019-004
R 551	10k ohm ±5% 1206 SMD	569-0115-103		NPN out opto isolator 4N35	544-2010-001
R 552	10k ohm ±5% 1206 SMD	569-0115-103			
R 553	1.2k ohm ±5% 1206 SMD	569-0115-122			

SYMBO NUMBI	· 	PART NUMBER
U 516	NPN out opto isolator 4N35	544-2010-001
U 517	Transparent latch SOIC	544-3766-573
U 518	D flip flop SOIC 74HC574	544-3766-574
U 519	Low pwr FM IF SO-16	544-2026-008
U 520	NPN out opto isolator 4N35	544-2010-001
U 521	Transparent latch SOIC	544-3766-573
U 522	+12V regulator TO-92 78L12	544-2003-032
U 523	+8V regulator 78M08	544-2003-081
Z 500	EMI suppression filter	532-3003-002
Z 501	EMI suppression filter	532-3003-002

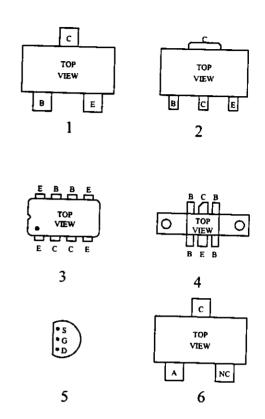
PARTS LIST

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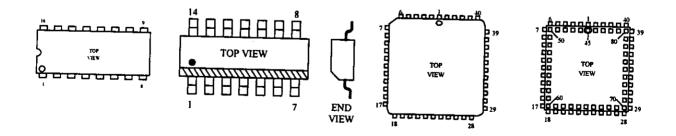
SECTION 10 SCHEMATICS AND COMPONENT LAYOUTS

TRANSISTORS

HOUSE CONTRACT	5 5 5	
Part Number	Basing Diagram	Identification
576-0001-300	1	IR
576-0002-603	b	•
576-0003-600	1	2X
576-0003-602	1	R2/R3
576-0003-604	3	3604
576-0003-612	1	2T
576-0003-636	1	R25
576-0003-657	1	2A
576-0003-658	1	IA
576-0004-098	В	
576-0004-820	4	
576-0004-821	4	
576-0006-109	5]
51018125	A CONTRACTOR OF THE STATE OF TH	
523-1504-002	6	5A
523-1504-012	6	2A
523-1504-015	6	4E
523-1504-016	6	ьн !
523-1504-023	}	A7
523-2016-180	6	Y7
523-2016-479	6 6	8E/Z1
523-2016-519		8F/Z2
523-2016-629	6	8J/Z4
523-2016-919	6	8P/Z8
523-5004-002		



INTEGRATED CIRCUITS



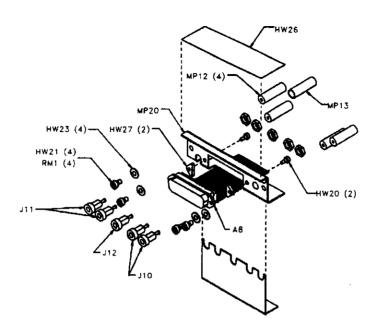


Figure 10-1 RF MODULE INTERFACE CONNECTOR

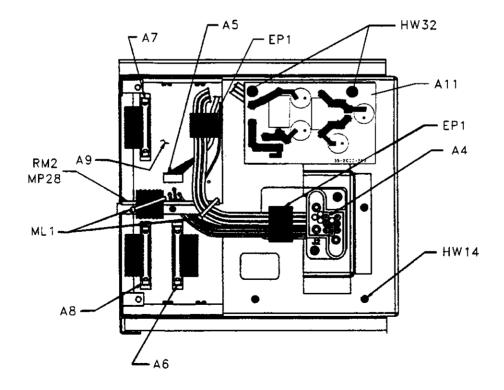


Figure 10-2 BACKPLANE CABLE CONNECTIONS